



External Memory Interface Handbook Volume 3

Section II. DDR3 SDRAM Controller with ALTMEMPHY IP User Guide



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Chapter 1. About This IP

Release Information	1-2
Device Family Support	1-2
Features	1-3
Unsupported Features	1-5
MegaCore Verification	1-5
Resource Utilization	1-5
ALTMEMPHY Megafunction	1-5
High-Performance Controller	1-7
High-Performance Controller II	1-7
System Requirements	1-8
Installation and Licensing	1-8
Free Evaluation	1-9
OpenCore Plus Time-Out Behavior	1-9

Chapter 2. Getting Started

Design Flow	2-1
SOPC Builder Flow	2-2
Specifying Parameters	2-2
Completing the SOPC Builder System	2-3
MegaWizard Plug-In Manager Flow	2-4
Specifying Parameters	2-4
Generated Files	2-6
HardCopy Device Migration Guidelines	2-10
Enabling Hardcopy Migration Performance Improvement with ALTMEMPHY	2-10
Generating Your IP Core For a Mid-speed Grade FPGA	2-10
Compiling Your Design for a Faster Speed Grade FPGA	2-11

Chapter 3. Parameter Settings

ALTMEMPHY Parameter Settings	3-1
Memory Settings	3-2
Using the Preset Editor to Create a Custom Memory Preset	3-3
Derating Memory Setup and Hold Timing	3-10
PHY Settings	3-11
Board Settings	3-13
DDR3 SDRAM Controller with ALTMEMPHY Parameter Settings	3-13
Controller Settings	3-14

Chapter 4. Compiling and Simulating

Compiling the Design	4-1
Simulating the Design	4-4

Chapter 5. Functional Description—ALTMEMPHY

Block Description	5-2
Calibration	5-3
DDR3 SDRAM Without Leveling	5-3
Step 1: Memory Device Initialization	5-4
Step 2: Write Training Patterns	5-4

Step 3: Read Resynchronization (Capture) Clock Phase	5-5
Step 4: Read and Write Datapath Timing	5-5
Step 5: Address and Command Clock Cycle	5-5
Step 6: Postamble	5-5
Step 7: Prepare for User Mode	5-5
DDR3 SDRAM With Leveling	5-7
Step 1: Memory Device Initialization	5-9
Step 2: Write Leveling	5-10
Step 3: Write Training Patterns	5-10
Step 4: Read Resynchronization	5-10
Step 5: Address and Command Path Clock Cycle	5-10
Step 6: Postamble	5-10
Step 7: Write Clock Path Setup	5-11
Step 8: Prepare for User Mode	5-11
VT Tracking	5-11
Mimic Path	5-11
Address and Command Datapath	5-11
Arria II GX Devices	5-11
Stratix III and Stratix IV Devices	5-13
Clock and Reset Management	5-13
Clock Management	5-13
Reset Management	5-17
Read Datapath	5-18
Arria II GX Devices	5-18
Stratix III and Stratix IV Devices	5-20
Write Datapath	5-22
Arria II GX Devices	5-22
Stratix III and Stratix IV Devices	5-22
ALTMEMPHY Signals	5-23
PHY-to-Controller Interfaces	5-31
Using a Custom Controller	5-38
Preliminary Steps	5-38
Design Considerations	5-38
Clocks and Resets	5-38
Calibration Process Requirements	5-39
Other Local Interface Requirements	5-39
Address and Command Interfacing	5-39
Handshake Mechanism Between Read Commands and Read Data	5-39
Handshake Mechanism Between Write Commands and Write Data	5-40
Partial Writes	5-41

Chapter 6. Functional Description—High-Performance Controller

Block Description	6-1
Command FIFO Buffer	6-2
Write Data FIFO Buffer	6-2
Write Data Tracking Logic	6-3
Main State Machine	6-3
Bank Management Logic	6-3
Timer Logic	6-3
Initialization State Machine	6-3
Address and Command Decode	6-3
PHY Interface Logic	6-4
ODT Generation Logic	6-4
Low-Power Mode Logic	6-4

Control Logic	6-5
Error Correction Coding (ECC)	6-5
Interrupts	6-8
Partial Writes	6-8
Partial Bursts	6-9
ECC Latency	6-9
ECC Registers	6-10
ECC Register Bits	6-12
Example Top-Level File	6-14
Example Driver	6-15
Top-level Signals Description	6-16

Chapter 7. Functional Description—High-Performance Controller II

Upgrading from HPC to HPC II	7-1
Block Description	7-2
Avalon-MM Data Slave Interface	7-3
Write Data FIFO Buffer	7-4
Command Queue	7-4
Bank Management Logic	7-4
Timer Logic	7-5
Command-Issuing State Machine	7-5
Address and Command Decode Logic	7-5
Write and Read Datapath, and Write Data Timing Logic	7-5
ODT Generation Logic	7-6
User-Controlled Side-Band Signals	7-6
User-Refresh Commands	7-6
Multi-Cast Write	7-6
Low-Power Mode Logic	7-7
Configuration and Status Register (CSR) Interface	7-7
Error Correction Coding (ECC)	7-7
Partial Writes	7-8
Partial Bursts	7-9
Example Top-Level File	7-10
Example Driver	7-11
Top-level Signals Description	7-12
Register Maps Description	7-18
ALTMEMPHY Register Map	7-19
Controller Register Map	7-21

Chapter 8. Latency

Chapter 9. Timing Diagrams

DDR3 High-Performance Controllers	9-1
Auto-Precharge	9-2
User Refresh	9-3
Half-Rate Read for Avalon Interface	9-4
Half-Rate Write for Avalon Interface	9-6
Half Rate Write for Native Interface	9-8
Initialization Timing	9-10
Calibration Timing	9-12
DDR3 High-Performance Controllers II	9-13
Half-Rate Read (Burst-Aligned Address)	9-14
Half-Rate Write (Burst-Aligned Address)	9-16

Half-Rate Read (Non Burst-Aligned Address)	9-18
Half-Rate Write (Non Burst-Aligned Address)	9-20
Half-Rate Read With Gaps	9-22
Half-Rate Write With Gaps	9-23
Half-Rate Write Operation (Merging Writes)	9-24
Write-Read-Write-Read Operation	9-26

Additional Information

Document Revision History	Info-1
How to Contact Altera	Info-1
Typographic Conventions	Info-2

The Altera® DDR3 SDRAM Controller with ALTMEMPHY IP provides simplified interfaces to industry-standard DDR3 SDRAM. The ALTMEMPHY megafunction is an interface between a memory controller and the memory devices, and performs read and write operations to the memory. The DDR3 SDRAM Controller with ALTMEMPHY IP works in conjunction with the Altera ALTMEMPHY megafunction.

The DDR3 SDRAM Controller with ALTMEMPHY IP and ALTMEMPHY megafunction support DDR3 SDRAM interfaces in half-rate mode. The DDR3 SDRAM Controller with ALTMEMPHY IP offers two controller architectures: the high-performance controller (HPC) and the high-performance controller II (HPC II). HPC II provides higher efficiency and more advanced features.


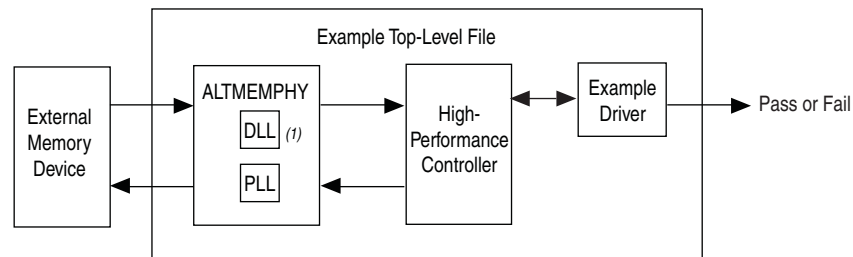
 DDR3 SDRAM high-performance controller denotes both HPC and HPC II unless indicated otherwise.

Figure 1–1 on page 1–1 shows a system-level diagram including the example top-level file that the DDR3 SDRAM Controller with ALTMEMPHY IP creates for you.

Figure 1–1. System-Level Diagram



Note to Figure 1–1:

- (1) When you choose **Instantiate DLL Externally**, delay-locked loop (DLL) is instantiated outside the ALTMEMPHY megafunction.

The MegaWizard™ Plug-In Manager generates an example top-level file, consisting of an example driver, and your DDR3 SDRAM high-performance controller custom variation. The controller instantiates an instance of the ALTMEMPHY megafunction which in turn instantiates a phase-locked loop (PLL) and DLL. You can also instantiate the DLL outside the ALTMEMPHY megafunction to share the DLL between multiple instances of the ALTMEMPHY megafunction. You cannot share a PLL between multiple instances of the ALTMEMPHY megafunction, but you may share some of the PLL clock outputs between these multiple instances.

The example top-level file is a fully-functional design that you can simulate, synthesize, and use in hardware. The example driver is a self-test module that issues read and write commands to the controller and checks the read data to produce the pass or fail, and test complete signals.

The ALTMEMPHY megafunction creates the datapath between the memory device and the memory controller. The megafunction is available as a stand-alone product or can be used in conjunction with Altera high-performance memory controllers. When using the ALTMEMPHY megafunction as a stand-alone product, use with either custom or third-party controllers.

Release Information

Table 1–1 provides information about this release of the DDR3 SDRAM Controller with ALTMEMPHY IP.

Table 1–1. Release Information

Item	Description
Version	10.0
Release Date	July 2010
Ordering Codes	IP-SDRAM/DDR3 (HPC) IP-HPMCII (HPC II)
Product IDs	00C2 (DDR3 SDRAM) 00C0 (ALTMEMPHY Megafunction)
Vendor ID	6AF7

Altera verifies that the current version of the Quartus® II software compiles the previous version of each MegaCore function. The *MegaCore IP Library Release Notes and Errata* report any exceptions to this verification. Altera does not verify compilation with MegaCore function versions older than one release. For information about issues on the DDR3 SDRAM high-performance controller and the ALTMEMPHY megafunction in a particular Quartus II version, refer to the *Quartus II Software Release Notes*.

Device Family Support

The MegaCore function provides either final or preliminary support for target Altera device families:

- **Final support** means the core is verified with final timing models for this device family. The core meets all functional and timing requirements for the device family and can be used in production designs.
- **Preliminary support** means the core is verified with preliminary timing models for this device family. The core meets all functional requirements, but might still be undergoing timing analysis for the device family. It can be used in production designs with caution.
- **HardCopy Compilation** means the core is verified with final timing models for the HardCopy® device family. The core meets all functional and timing requirements for the device family and can be used in production designs.
- **HardCopy Companion** means the core is verified with preliminary timing models for the HardCopy companion device. The core meets all functional requirements, but might still be undergoing timing analysis for HardCopy device family. It can be used in production designs with caution.

Table 1–2 shows the level of support offered by the DDR3 SDRAM Controller with ALTMEMPHY IP to each of the Altera device families.

Table 1–2. Device Family Support

Device Family	Support
Arria® II GX	Preliminary
HardCopy III	HardCopy Companion
HardCopy IV E	HardCopy Companion
HardCopy IV GX	HardCopy Companion
Stratix® III	Final
Stratix IV	Final
Other device families	No support

Features

The ALTMEMPHY megafunction offers the following features:

- Simple setup.
- Support for the Altera PHY Interface (AFI) for DDR3 SDRAM on all supported devices.
- Automated initial calibration eliminating complicated read data timing calculations.
- Voltage and temperature (VT) tracking that guarantees maximum stable performance for DDR3 SDRAM interface.
- Self-contained datapath that makes connection to an Altera controller or a third-party controller independent of the critical timing paths.
- Easy-to-use parameter editor.

The ALTMEMPHY megafunction supports DDR3 SDRAM DIMMs with leveling and DDR3 SDRAM components without leveling:

- ALTMEMPHY with leveling is for unbuffered DIMMs (including SODIMM and MicroDIMM) or DDR3 SDRAM components up to 80-bit total data bus width with a layout like a DIMM that target Stratix III and Stratix IV devices:
 - Supports a fully-calibrated DDR3 SDRAM PHY for DDR3 SDRAM unbuffered DIMM with ×4 and ×8 devices with 300-MHz to 533-MHz frequency targets.
 - Deskew circuitry is enabled automatically for interfaces higher than 400 MHz.
 - Supports single and multiple chip selects.
- ALTMEMPHY supports DDR3 SDRAM components without leveling for Arria II GX, Stratix III, and Stratix IV devices using T-topology for clock, address, and command bus:
 - Supports multiple chip selects.
- The DDR3 SDRAM PHY with leveling f_{MAX} is 533 MHz; without leveling f_{MAX} is 400 MHz for single chip selects.

- No support for data-mask (DM) pins for ×4 DDR3 SDRAM DIMMs or components, so select **No** for **Drive DM pins from FPGA** when using ×4 devices.
- The ALTMEMPHY megafunction supports half-rate DDR3 SDRAM interfaces only.

In addition, [Table 1-3](#) shows the features provided by the DDR3 SDRAM HPC and HPC II.

Table 1-3. DDR3 SDRAM HPC and HPC II Features (Part 1 of 2)

Features	Controller Architecture	
	HPC	HPC II
Half-rate controller	✓	✓
Support for AFI ALTMEMPHY	✓	✓
Support for Avalon® Memory Mapped (Avalon-MM) local interface	✓	✓
Support for Native local interface	✓	—
Configurable command look-ahead bank management with in-order reads and writes	—	✓
Additive latency	—	✓ (1)
Optional support for multi-cast write for t_{RC} mitigation	—	✓
Support for arbitrary Avalon burst length	—	✓
Built-in flexible memory burst adapter	—	✓
Configurable Local-to-Memory address mappings	—	✓
Integrated half-rate bridge for low latency option	—	✓
Optional run-time configuration of size and mode register settings, and memory timing	—	✓ (2)
Partial array self-refresh (PASR)	—	✓
Support for industry-standard DDR3 SDRAM devices; and DIMMs	✓	✓
Optional support for self-refresh command	✓	✓
Optional support for user-controlled power-down command	✓	—
Optional support for automatic power-down command with programmable time-out	—	✓
Optional support for auto-precharge read and auto-precharge write commands	✓	—
Optional support for user-controller refresh	✓	✓
Reduced bank tracking for area optimization	—	✓
Controller variable latency	—	✓
Optional multiple controller clock sharing in SOPC Builder Flow	✓	✓
Integrated error correction coding (ECC) function 72-bit	✓	✓
Integrated ECC function 40-bit	—	✓
Support for partial-word write with optional automatic error correction	—	✓
SOPC Builder ready	✓	✓
Support for OpenCore Plus evaluation	✓	—

Table 1–3. DDR3 SDRAM HPC and HPC II Features (Part 2 of 2)

Features	Controller Architecture	
	HPC	HPC II
IP functional simulation models for use in Altera-supported VHDL and Verilog HDL simulator	✓	✓

Notes to Table 1–3:

- (1) HPC II supports additive latency values greater or equal to $t_{\text{RCD}}-1$, in clock cycle unit (t_{CK}).
- (2) This feature is not supported with DDR3 SDRAM with leveling.

Unsupported Features

The DDR3 SDRAM Controller with ALTMEMPHY IP does not support the following features:

- Timing simulation.
- Partial burst and unaligned burst in ECC and non-ECC mode when DM pins are disabled.

MegaCore Verification

Altera performs extensive random, directed tests with functional test coverage using industry-standard Denali models to ensure the functionality of the DDR3 SDRAM Controller with ALTMEMPHY IP.

Resource Utilization

The following sections show the resource utilization data for the ALTMEMPHY megafunction, and the DDR3 high-performance controllers (HPC and HPC II).

ALTMEMPHY Megafunction

Table 1–4 and Table 1–5 show the typical size of the ALTMEMPHY megafunction with the AFI in the Quartus II software version 10.0 for the following devices:

- Arria II GX (EP2AGX260FF35C4) devices
- Stratix III (EP3SL110F1152C2) devices
- Stratix IV (EP4SGX230HF35C2) devices

Table 1-4. Resource Utilization in Arria II GX Devices (Note 1)

Memory Type	PHY Rate	Memory Width (Bits)	Combinational ALUTs	Logic Registers	M9K Blocks	Memory ALUTs
DDR3 SDRAM (without leveling)	Half	8	1,431	1,189	2	18
		16	1,481	1,264	4	2
		64	1,797	1,970	12	22
		72	1,874	2,038	13	2

Note to Table 1-4:

- (1) The listed resource utilization refers to resources used by the ALTMEMPHY megafunction with AFI only. Memory controller overhead is additional.

Table 1-5. Resource Utilization in Stratix III and Stratix IV Devices (Note 1)

Memory Type	PHY Rate	Memory Width (Bits)	Combinational ALUTs	Logic Registers	M9K Blocks	Memory ALUTs
DDR3 SDRAM (400 MHz, without leveling only)	Half	8	1,359	1,047	1	40
		16	1,426	1,196	1	80
		64	1,783	2,080	1	320
		72	1,871	2,228	1	360
DDR3 SDRAM (400 MHz, with leveling only)		8	3,724	2,723	2	80
		16	4,192	3,235	2	160
		64	6,835	6,487	5	640
		72	7,182	6,984	5	720
DDR3 SDRAM (533 MHz with read and write deskew, with leveling only)		8	4,098	2,867	2	80
		16	4,614	3,391	2	160
		64	7,297	6,645	5	640
		72	7,641	7,144	5	720

Note to Table 1-5:

- (1) The listed resource utilization refers to resources used by the ALTMEMPHY megafunction with AFI only. Memory controller overhead is additional.

High-Performance Controller

Table 1-6 and Table 1-7 show the typical sizes for the DDR3 SDRAM HPC (including ALTMEMPHY) for Stratix III and Stratix IV devices.

Table 1-6. Resource Utilization in Stratix III Devices

Local Data Width (Bits)	Memory Width (Bits)	Combinational ALUTs	Dedicated Logic Registers	Memory (M9K)
32	8	1,891	1,558	2
64	16	1,966	1,707	3
256	64	2,349	2,591	9
288	72	2,442	2,739	10

Table 1-7. Resource Utilization in Stratix IV Devices

Local Data Width (Bits)	Memory Width (Bits)	Combinational ALUTs	Dedicated Logic Registers	Memory (M9K)
32	8	1,924	1,580	2
64	16	1,987	1,724	3
256	64	2,359	2,584	9
288	72	2,449	2,728	10

High-Performance Controller II

Table 1-9 through Table 1-10 show the typical sizes for the DDR3 SDRAM HPC II (including ALTMEMPHY) for Arria II GX, Stratix III, and Stratix IV devices.

Table 1-8. Resource Utilization in Arria II GX Devices

Local Data Width (Bits)	Memory Width (Bits)	Combinational ALUTs	Dedicated Logic Registers	Memory (M9K)
32	8	2,516	1,945	3
64	16	2,604	2,101	5
256	64	3,121	3,021	17
288	72	3,243	3,175	18

Table 1-9. Resource Utilization in Stratix III Devices


Local Data Width (Bits)	Memory Width (Bits)	Combinational ALUTs	Dedicated Logic Registers	Memory (M9K)
32	8	2,430	1,776	2
64	16	2,499	1,919	3
256	64	2,902	2,809	9
288	72	3,001	2,959	10

Table 1-10. Resource Utilization in Stratix IV Devices

Local Data Width (Bits)	Memory Width (Bits)	Combinational ALUTs	Dedicated Logic Registers	Memory (M9K)
32	8	2,427	1,773	2
64	16	2,496	1,914	3
256	64	2,887	2,774	9
288	72	2,981	2,924	10

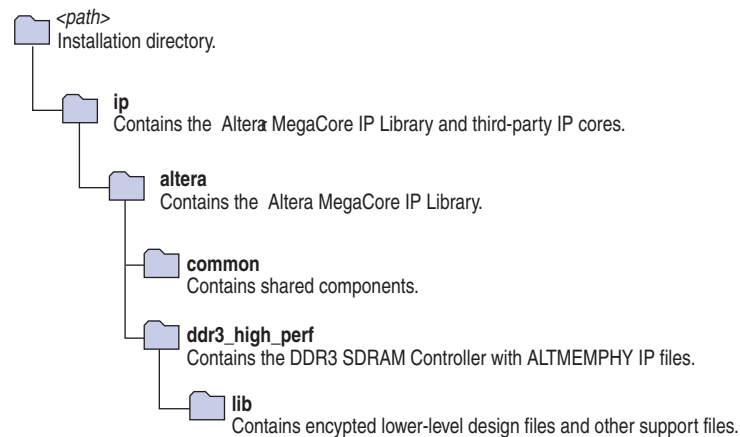
System Requirements

The DDR3 SDRAM Controller with ALTMEMPHY IP is a part of the MegaCore IP Library, which is distributed with the Quartus II software and downloadable from the Altera website, www.altera.com.

 For system requirements and installation instructions, refer to *Altera Software Installation & Licensing*.

Installation and Licensing

Figure 1-2 shows the directory structure after you install the DDR3 SDRAM Controller with ALTMEMPHY IP, where *<path>* is the installation directory. The default installation directory on Windows is `c:\altera\<version>`; on Linux it is `/opt/altera<version>`.

Figure 1-2. Directory Structure

You need a license for the MegaCore function only when you are completely satisfied with its functionality and performance, and want to take your design to production.

To use the DDR3 SDRAM HPC, you can request a license file from the Altera web site at www.altera.com/licensing and install it on your computer. When you request a license file, Altera emails you a **license.dat** file. If you do not have Internet access, contact your local representative.

To use the DDR3 SDRAM HPC II, contact your local sales representative to order a license.

Free Evaluation

Altera's OpenCore Plus evaluation feature is only applicable to the DDR3 SDRAM HPC. With the OpenCore Plus evaluation feature, you can perform the following actions:

- Simulate the behavior of a megafunction (Altera MegaCore function or AMPPSM megafunction) within your system.
- Verify the functionality of your design, as well as evaluate its size and speed quickly and easily.
- Generate time-limited device programming files for designs that include MegaCore functions.
- Program a device and verify your design in hardware.

You need to purchase a license for the megafunction only when you are completely satisfied with its functionality and performance, and want to take your design to production.

OpenCore Plus Time-Out Behavior

OpenCore Plus hardware evaluation can support the following two modes of operation:

- Untethered—the design runs for a limited time
- Tethered—requires a connection between your board and the host computer. If tethered mode is supported by all megafunctions in a design, the device can operate for a longer time or indefinitely

All megafunctions in a device time-out simultaneously when the most restrictive evaluation time is reached. If there is more than one megafunction in a design, a specific megafunction's time-out behavior may be masked by the time-out behavior of the other megafunctions.



For MegaCore functions, the untethered time-out is 1 hour; the tethered time-out value is indefinite.

Your design stops working after the hardware evaluation time expires and the `local_ready` output goes low.

Design Flow

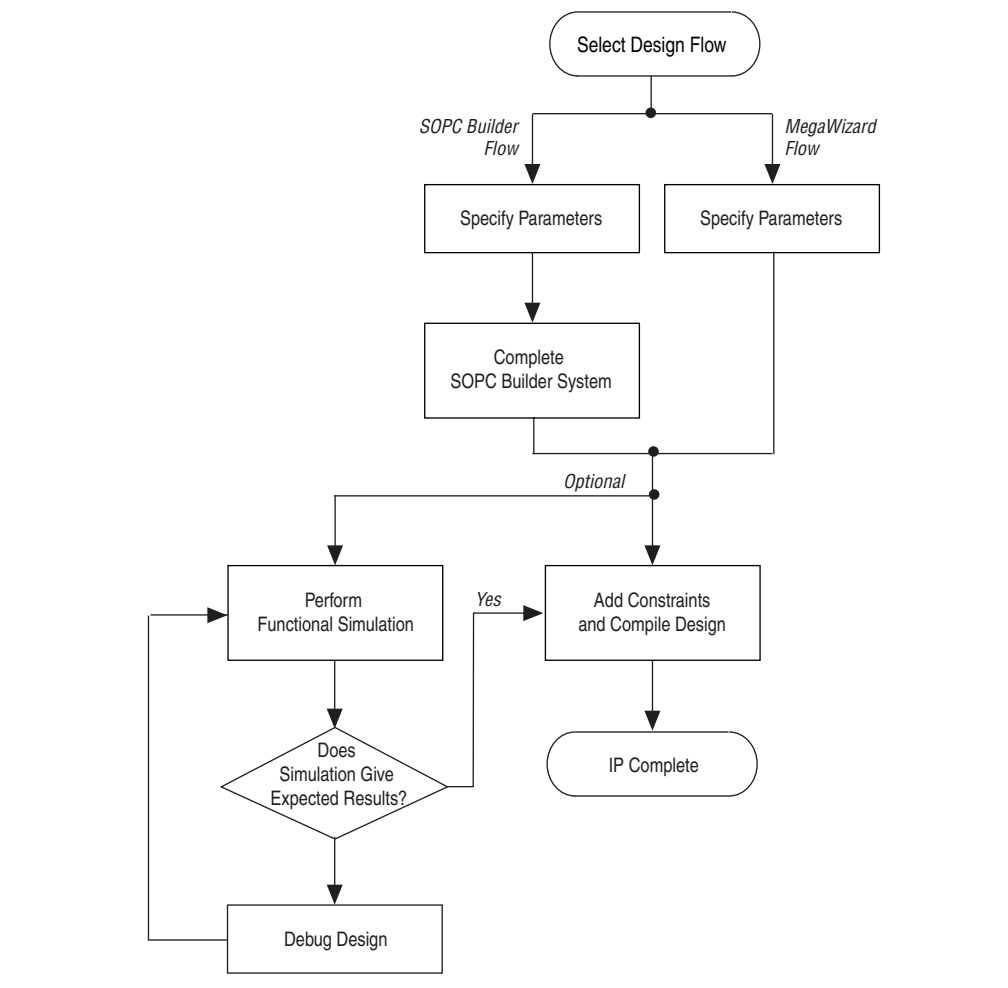
You can implement the DDR3 SDRAM Controller with ALTMEMPHY IP using either one of the following flows:

- SOPC Builder flow
- MegaWizard Plug-In Manager flow

You can only instantiate the ALTMEMPHY megafunction using the MegaWizard Plug-In Manager flow.

Figure 2–1 shows the stages for creating a system in the Quartus II software using either one of the flows.

Figure 2–1. Design Flow



The SOPC Builder flow offers the following advantages:

- Generates simulation environment
- Creates custom components and integrates them via the component wizard
- Interconnects all components with the Avalon-MM interface


The MegaWizard Plug-In Manager flow offers the following advantages:

- Allows you to design directly from the DDR3 SDRAM interface to peripheral device or devices
- Achieves higher-frequency operation

SOPC Builder Flow

The SOPC Builder flow allows you to add the DDR3 SDRAM Controller with ALTMEMPHY IP directly to a new or existing SOPC Builder system.

You can also easily add other available components to quickly create an SOPC Builder system with a DDR3 SDRAM controller, such as the Nios[®] II processor and scatter-gather direct memory access (SDMA) controllers. SOPC Builder automatically creates the system interconnect logic and system simulation environment.

 For more information about SOPC Builder, refer to [volume 4](#) of the *Quartus II Handbook*. For more information about how to use controllers with SOPC Builder, refer to the *ALTMEMPHY Design Tutorials* section in volume 6 of the *External Memory Interface Handbook*. For more information on the Quartus II software, refer to the Quartus II Help.


Specifying Parameters


To specify the parameters for the DDR3 SDRAM Controller with ALTMEMPHY IP using the SOPC Builder flow, perform the following steps:

1. In the Quartus II software, create a new Quartus II project with the **New Project Wizard**.
2. On the Tools menu, click **SOPC Builder**.
3. For a new system, specify the system name and language.
4. Add **DDR3 SDRAM Controller with ALTMEMPHY** to your system from the **System Contents** tab.

 The **DDR3 SDRAM Controller with ALTMEMPHY** is in the **SDRAM** folder under the **Memories and Memory Controllers** folder.

5. Specify the required parameters on all pages in the **Parameter Settings** tab.

 To avoid simulation failure, you must set **Local-to-Memory Address Mapping** to **CHP-BANK-ROW-COL** if you select **High Performance Controller II** for **Controller Architecture**.

 For detailed explanation of the parameters, refer to the [“Parameter Settings” on page 3–1](#).

- Click **Finish** to complete parameterizing the DDR3 SDRAM Controller with ALTMEMPHY IP and add it to the system.

Completing the SOPC Builder System

To complete the SOPC Builder system, perform the following steps:

- In the **System Contents** tab, select **Nios II Processor** and click **Add**.
- On the **Nios II Processor** page, in the **Core Nios II** tab, select **altmemddr** for **Reset Vector** and **Exception Vector**.
- Change the **Reset Vector Offset** and the **Exception Vector Offset** to an Avalon address that is not written to by the ALTMEMPHY megafunction during its calibration process.



The ALTMEMPHY megafunction performs memory interface calibration every time it is reset, and in doing so, writes to a range of addresses. If you want your memory contents to remain intact through a system reset, you should avoid using these memory addresses. This step is not necessary if you reload your SDRAM memory contents from flash every time you reset your system.

If you are upgrading your Nios system design from version 8.1 or previous, ensure that you change the **Reset Vector Offset** and the **Exception Vector Offset** to **AFI** mode.

To calculate the Avalon-MM address equivalent of the memory address range 0x0 to 0x47, multiply the memory address by the width of the memory interface data bus in bytes. Refer to [Table 2-1](#) for more Avalon-MM addresses.

Table 2-1. Avalon-MM Addresses for AFI Mode

External Memory Interface Width	Reset Vector Offset	Exception Vector Offset
8	0x60	0x80
16	0xA0	0xC0
32	0x120	0x140
64	0x240	0x260

- Click **Finish**.
- On the **System Contents** tab, expand **Interface Protocols** and expand **Serial**.
- Select **JTAG UART** and click **Add**.
- Click **Finish**.



If there are warnings about overlapping addresses, on the System menu, click **Auto Assign Base Addresses**.

If you enable ECC and there are warnings about overlapping IRQs, on the System menu click **Auto Assign IRQs**.

8. For this example system, ensure all the other modules are clocked on the `altmemddr_sysclk`, to avoid any unnecessary clock-domain crossing logic.

9. Click **Generate**.



Among the files generated by SOPC Builder is the Quartus II IP File (**.qip**). This file contains information about a generated IP core or system. In most cases, the **.qip** file contains all of the necessary assignments and information required to process the MegaCore function or system in the Quartus II compiler. Generally, a single **.qip** file is generated for each SOPC Builder system. However, some more complex SOPC Builder components generate a separate **.qip** file. In that case, the system **.qip** file references the component **.qip** file.

10. Compile your design, refer to [“Compiling and Simulating” on page 4-1](#).

MegaWizard Plug-In Manager Flow

The MegaWizard Plug-In Manager flow allows you to customize the DDR3 SDRAM Controller with ALTMEMPHY or the stand-alone PHY with the ALTMEMPHY megafunction, and manually integrate the function into your design.



For more information about the MegaWizard Plug-In Manager, refer to the Quartus II Help.

Specifying Parameters

To specify parameters using the MegaWizard Plug-In Manager flow, perform the following steps:

1. In the Quartus II software, create a new Quartus II project with the **New Project Wizard**.
2. On the Tools menu, click **MegaWizard Plug-In Manager** to start the MegaWizard Plug-In Manager.
 - The DDR3 SDRAM Controller with ALTMEMPHY is in the **Interfaces** folder under the **External Memory** folder.
 - The ALTMEMPHY megafunction is in the **I/O** folder.



The *<variation name>* must be a different name from the project name and the top-level design entity name.

3. Specify the parameters on all pages in the **Parameter Settings** tab.



For detailed explanation of the parameters, refer to the [“Parameter Settings” on page 3-1](#).

4. On the **EDA** tab, turn on **Generate simulation model** to generate an IP functional simulation model for the MegaCore function in the selected language.

An IP functional simulation model is a cycle-accurate VHDL or Verilog HDL model produced by the Quartus II software.



Use the simulation models only for simulation and not for synthesis or any other purposes. Using these models for synthesis creates a nonfunctional design.



Some third-party synthesis tools can use a netlist that contains only the structure of the MegaCore function, but not detailed logic, to optimize performance of the design that contains the MegaCore function. If your synthesis tool supports this feature, turn on **Generate netlist**.

When targeting a VHDL simulation model, the MegaWizard Plug-In Manager still generates the `<variation_name>_alt_mem_phy.v` file for the Quartus II synthesis. Do not use this file for simulation. Use the `<variation_name>.vho` file for simulation instead.

The ALTMEMPHY megafunction only supports functional simulation. You cannot perform timing or gate-level simulation when using the ALTMEMPHY megafunction.

5. On the **Summary** tab, select the files you want to generate. A gray checkmark indicates a file that is automatically generated. All other files are optional.
6. Click **Finish** to generate the MegaCore function and supporting files. A generation report appears.
7. If you generate the MegaCore function instance in a Quartus II project, you are prompted to add the **.qip** files to the current Quartus II project. When prompted to add the **.qip** files to your project, click **Yes**. The addition of the **.qip** files enables their visibility to Nativelink. Nativelink requires the **.qip** files to include libraries for simulation.



The **.qip** file is generated by the parameter editor, and contains information about the generated IP core. In most cases, the **.qip** file contains all of the necessary assignments and information required to process the MegaCore function or system in the Quartus II compiler. The parameter editor generates a single **.qip** file for each MegaCore function.

8. After you review the generation report, click **Exit** to close the MegaWizard Plug-In Manager.
9. For the high-performance controller (HPC or HPC II), set the `<variation name>_example_top.v` or `.vhd` file to be the project top-level design file.
 - a. On the File menu, click **Open**.
 - b. Browse to `<variation name>_example_top` and click **Open**.
 - c. On the Project menu, click **Set as Top-Level Entity**.

Generated Files

Table 2–2 shows the ALTMEMPHY generated files.

Table 2–2. ALTMEMPHY Generated Files (Part 1 of 2)

File Name	Description
alt_mem_phy_defines.v	Contains constants used in the interface. This file is always in Verilog HDL regardless of the language you chose in the MegaWizard Plug-In Manager.
<variation_name>.html	Lists the top-level files created and ports used in the megafunction.
<variation_name>.ppf	Pin planner file for your ALTMEMPHY variation.
<variation_name>.qip	Quartus II IP file for your ALTMEMPHY variation, containing the files associated with this megafunction.
<variation_name>.v/.vhd	Top-level file of your ALTMEMPHY variation, generated based on the language you chose in the MegaWizard Plug-In Manager.
<variation_name>.vho	Contains functional simulation model for VHDL only.
<variation_name>_alt_mem_phy_delay.vhd	Includes a delay module for simulation. This file is only generated if you choose VHDL as the language of your MegaWizard Plug-In Manager output files.
<variation_name>_alt_mem_phy_dq_dqs.vhd or .v	Generated file that contains DQ/DQS I/O atoms interconnects and instance. Arria II GX devices only.
<variation_name>_alt_mem_phy_dq_dqs_clearbox.txt	Specification file that generates the <variation_name>_alt_mem_phy_dq_dqs file using the clearbox flow. Arria II GX devices only.
<variation_name>_alt_mem_phy_pll.qip	Quartus II IP file for the PLL that your ALTMEMPHY variation uses that contains the files associated with this megafunction.
<variation_name>_alt_mem_phy_pll.v/.vhd	The PLL megafunction file for your ALTMEMPHY variation, generated based on the language you chose in the MegaWizard Plug-In Manager.
<variation_name>_alt_mem_phy_pll_bb.v/.cmp	Black box file for the PLL used in your ALTMEMPHY variation. Typically unused.
<variation_name>_alt_mem_phy_seq.vhd	Contains the sequencer used during calibration. This file is always in VHDL language regardless of the language you chose in the MegaWizard Plug-In Manager.
<variation_name>_alt_mem_phy_seq_wrapper.v/.vhd	A wrapper file, for compilation only, that calls the sequencer file, created based on the language you chose in the MegaWizard Plug-In Manager.
<variation_name>_alt_mem_phy_seq_wrapper.vo/.vho	A wrapper file, for simulation only, that calls the sequencer file, created based on the language you chose in the MegaWizard Plug-In Manager.

Table 2–2. ALTMEMPHY Generated Files (Part 2 of 2)

File Name	Description
<variation_name>_alt_mem_phy.v	Contains all modules of the ALTMEMPHY variation except for the sequencer. This file is always in Verilog HDL language regardless of the language you chose in the MegaWizard Plug-In Manager. The DDR3 SDRAM sequencer is included in the <variation_name>_alt_mem_phy_seq.vhd file.
<variation_name>_bb.v/.cmp	Black box file for your ALTMEMPHY variation, depending whether you are using Verilog HDL or VHDL language.
<variation_name>_ddr_pins.tcl	Contains procedures used in the <variation_name>_ddr_timing.sdc and <variation_name>_report_timing.tcl files.
<variation_name>_ddr_timing.sdc	Contains timing constraints for your ALTMEMPHY variation.
<variation_name>_pin_assignments.tcl	Contains I/O standard, drive strength, output enable grouping, DQ/DQS grouping, and termination assignments for your ALTMEMPHY variation. If your top-level design pin names do not match the default pin names or a prefixed version, edit the assignments in this file.
<variation_name>_report_timing.tcl	Script that reports timing for your ALTMEMPHY variation during compilation.

Table 2–3 shows the modules that are instantiated in the <variation_name>_alt_mem_phy.v/.vhd file. A particular ALTMEMPHY variation may or may not use any of the modules, depending on the memory standard that you specify.

Table 2–3. Modules in <variation_name>_alt_mem_phy.v File (Part 1 of 2)

Module Name	Usage	Description
<variation_name>_alt_mem_phy_addr_cmd	All ALTMEMPHY variations	Generates the address and command structures.
<variation_name>_alt_mem_phy_clk_reset	All ALTMEMPHY variations	Instantiates PLL, DLL, and reset logic.
<variation_name>_alt_mem_phy_dp_io	All ALTMEMPHY variations	Generates the DQ, DQS, DM, and QVLD I/O pins.
<variation_name>_alt_mem_phy_mimic	DDR3 SDRAM ALTMEMPHY variation	Creates the VT tracking mechanism for DDR3 SDRAM PHYs.
<variation_name>_alt_mem_phy_oct_delay	DDR3 SDRAM ALTMEMPHY variation when dynamic OCT is enabled.	Generates the proper delay and duration for the OCT signals.
<variation_name>_alt_mem_phy_postamble	DDR3 SDRAM ALTMEMPHY variations	Generates the postamble enable and disable scheme for DDR3 PHYs.
<variation_name>_alt_mem_phy_read_dp	All ALTMEMPHY variations (unused for Stratix III or Stratix IV devices)	Takes read data from the I/O through a read path FIFO buffer, to transition from the resynchronization clock to the PHY clock.

Table 2-3. Modules in <variation_name>_alt_mem_phy.v File (Part 2 of 2)

Module Name	Usage	Description
<variation_name>_alt_mem_phy_read_dp_group	DDR3 SDRAM ALTMEMPHY variations (Stratix III and Stratix IV devices only)	A per DQS group version of <variation_name>_alt_mem_phy_read_dp.
<variation_name>_alt_mem_phy_readata_valid	DDR3 SDRAM ALTMEMPHY variations	Generates read data valid signal to sequencer and controller.
<variation_name>_alt_mem_phy_sequencer_wrapper	All ALTMEMPHY variations	Generates sequencer for DDR3 SDRAM.
<variation_name>_alt_mem_phy_writedata_dp	All ALTMEMPHY variations	Generates the demultiplexing of data from half-rate to full-rate DDR data.

Table 2-4 through Table 2-6 show the additional files generated by the high-performance controllers, that may be in your project directory. The names and types of files specified in the MegaWizard Plug-In Manager report vary based on whether you created your design with VHDL or Verilog HDL.



In addition to the files in Table 2-4 through Table 2-6, the MegaWizard also generates the ALTMEMPHY files in Table 2-2, but with a `_phy` prefix. For example, `<variation_name>_alt_mem_phy_delay.vhd` becomes `<variation_name>_phy_alt_mem_phy_delay.vhd`.

Table 2-4. Controller Generated Files—All High-Performance Controllers

Filename	Description
<variation name>.bsf	Quartus II symbol file for the MegaCore function variation. You can use this file in the Quartus II block diagram editor.
<variation name>.html	MegaCore function report file.
<variation name>.v or .vhd	A MegaCore function variation file, which defines a VHDL or Verilog HDL top-level description of the custom MegaCore function. Instantiate the entity defined by this file inside of your design. Include this file when compiling your design in the Quartus II software.
<variation name>.qip	Contains Quartus II project information for your MegaCore function variations.
<variation name>.ppf	XML file that describes the MegaCore pin attributes to the Quartus II Pin Planner. MegaCore pin attributes include pin direction, location, I/O standard assignments, and drive strength. If you launch IP Toolbench outside of the Pin Planner application, you must explicitly load this file to use Pin Planner.
<variation name>_example_driver.v or .vhd	Example self-checking test generator that matches your variation.
<variation name>_example_top.v or .vhd	Example top-level design file that you should set as your Quartus II project top level. Instantiates the example driver and the controller.
<variation_name>_pin_assignments.tcl	Contains I/O standard, drive strength, output enable grouping, and termination assignments for your ALTMEMPHY variation. If your top-level design pin names do not match the default pin names or a prefixed version, edit the assignments in this file.

Table 2-5. Controller Generated Files—DDR3 High-Performance Controller (HPC)

Filename	Description
<variation name>_auk_ddr_hp_controller_wrapper.vo or .vho	VHDL or Verilog HDL IP functional simulation model.
<variation name>_auk_ddr_hp_controller_ecc_wrapper.vo or .vho	ECC functional simulation model.

Table 2-6. Controller Generated Files—DDR3 High-Performance Controller II (HPC II)

Filename	Description
<variation name>_alt_ddrx_controller_wrapper.v or .vho	A controller wrapper that instantiates the alt_ddrx_controller.v file and configures the controller accordingly by the wizard.
alt_ddrx_addr_cmd.v	Decodes the state machine outputs into the memory address and command signals.
alt_ddrx_afi_block.v	Generates the read and write control signals for the AFI.
alt_ddrx_bank_tracking.v	Tracks which row is open in which memory bank.
alt_ddrx_clock_and_reset.v	Contains the clock and reset logic.
alt_ddrx_cmd_queue.v	Contains the command queue logic.
alt_ddrx_controller.v	The controller top-level file that instantiates all the sub-blocks.
alt_ddrx_csr.v	Contains the control and status register interface logic.
alt_ddrx_ddr3_odt_gen.v	Generates the on-die termination (ODT) control signal for DDR3 memory interfaces.
alt_ddrx_avalon_if.v	Communicates with the Avalon-MM interface.
alt_ddrx_decoder_40.v	Contains the 40 bit version of the ECC decoder logic.
alt_ddrx_decoder_72.v	Contains the 72 bit version of the ECC decoder logic.
alt_ddrx_decoder.v	Instantiates the appropriate width ECC decoder logic.
alt_ddrx_encoder_40.v	Contains the 40 bit version of the ECC encoder logic.
alt_ddrx_encoder_72.v	Contains the 72 bit version of the ECC encoder logic.
alt_ddrx_encoder.v	Instantiates the appropriate width ECC encoder logic.
alt_ddrx_input_if.v	The input input interface block. It instantiates the alt_ddrx_cmd_queue.v , alt_ddrx_wdata_fifo.v , and alt_ddrx_avalon_if.v files.
alt_ddrx_odt_gen.v	Instantiates the alt_ddrx_ddr3_odt_gen.v file selectively. It also controls the ODT addressing scheme.
alt_ddrx_state_machine.v	The main state machine of the controller.
alt_ddrx_timers_fsm.v	The state machine that tracks the per-bank timing parameters.
alt_ddrx_timers.v	Instantiates alt_ddrx_timers_fsm.v and contains the rank specific timing tracking logic.
alt_ddrx_wdata_fifo.v	The write data FIFO logic. This logic buffers the write data and byte enables from the Avalon interface.
alt_avalon_half_rate_bridge_constraints.sdc	Contains timing constraints if your design has the Enable Half Rate Bridge option turned on.
alt_avalon_half_rate_bridge.v	The integrated half-rate bridge logic block.

HardCopy Device Migration Guidelines

In HardCopy III and HardCopy IV designs where higher core performance is required and I/O performance is not a limiting factor, you can prototype your HardCopy design in a faster speed grade companion FPGA. However, this practice introduces some restrictions and limitations. For example, if you target a HardCopy device with an FPGA device as a prototype, the Quartus II Fitter restricts the VCO operating range of the PLL to the mid speed grade frequency, regardless of the actual speed grade of the FPGA that the design is targeting.

Enabling Hardcopy Migration Performance Improvement with ALTMEMPHY

You can achieve improved performance when implementing an IP core for use with a HardCopy device by first generating your IP for a lower-speed FPGA to achieve optimal implementation, and then compiling your design for the higher-speed FPGA companion to your HardCopy device. This process is summarized below:

1. Generate your IP core, targeting a mid-speed grade FPGA.
2. Compile your design, targeting a faster speed grade FPGA.

The following sections discuss the above steps in greater detail.

Generating Your IP Core For a Mid-speed Grade FPGA

When you parameterize and generate your controller using the ALTMEMPHY parameter editor, the PHY, PLL, and DLL are parameterized and generated together with the controller logic. Robust calibration and operation require that all of these blocks operate with matched settings. To ensure that you have matched settings, any IP that includes hard blocks should be generated in the MegaWizard Plug-In Manager targeting a mid-speed grade FPGA rather than the C2 speed grade. By targeting a mid-speed grade FPGA, you ensure that any process-dependant settings are appropriately restricted when the IP core is generated, thereby maintaining a consistent post-fit implementation throughout the compilation process. You can then compile the design for either a mid- or high-speed grade FPGA, depending on whether you want speed enhancements.

The following example illustrates this situation. [Table 2-7](#) shows the key parameters.

Table 2-7. PHY Sequencer Parameters (Part 1 of 2)

Parameter	Setting
DLL_DELAY_BUFFER_MODE	HIGH
DLL_DELAY_CHAIN_LENGTH	10
DQS_DELAY_CTL_WIDTH	6
DQS_OUT_MODE	DELAY_CHAIN2
DQS_PHASE	7200
DQS_PHASE_SETTING	2
MEM_IF_CLK_PS	3300
MEM_IF_CLK_PS_STR	3300 ps
MEM_IF_MR_0	4641

Table 2-7. PHY Sequencer Parameters (Part 2 of 2)

Parameter	Setting
PLL_STEPS_PER_CYCLE	40
MEM_IF_ADDR_CMD_PHASE	240



The sequencer in this example is set up to operate with 40 PLL phase steps per clock cycle. (This information appears in the message panel of the ALTMEMPHY parameter editor during generation of the IP core.)

Compiling Your Design for a Faster Speed Grade FPGA

The ALTMEMPHY parameter editor generates PLL parameters that match the PHY requirement that the minimum PLL phase step size be one-eighth of the nominal VCO operating period. In a C2 speed grade FPGA, the VCO is configured to run at 1515 MHz with an associated phase step of 82 ps. Table 2-8 summarizes the generated PLL parameters. As shown, the PLL setup produces 40 phase steps per memory clock cycle, matching the sequencer setup. This analysis, however, does not apply when you select a HardCopy device.

Table 2-8. Generated PLL Parameters for a C2 speed grade FPGA

Parameter	Setting
VCO OPERATING FREQUENCY	1515 MHz
VCO PHASE SHIFT STEP	82 ps
MEMORY CLOCK PERIOD	3300 ps
PLL PHASE STEPS PER MEMCLK PERIOD	40

The HardCopy flow targets the center of the silicon process; therefore, all hard IP blocks within the prototype FPGA must be configured accordingly to guarantee functional equivalency. When a HardCopy device is selected, the Quartus II Fitter restricts the operating range of the PLL to match the HardCopy silicon capability, regardless of the speed grade of the selected FPGA. This restriction can alter the final configuration of the PLL, producing a mismatch between the generated sequencer setup stored in RTL, and the PLL behavior generated by the Quartus II Fitter. Table 2-9 summarizes the post-fit PLL setup when HardCopy migration is selected, regardless of the chosen FPGA speed grade.

Table 2-9. Post-fit PLL Parameters When Using a HardCopy Device

Parameter	Setting
VCO OPERATING FREQUENCY	1212.1 MHz
VCO PHASE SHIFT STEP	103 ps
MEMORY CLOCK PERIOD	3300 ps
PLL PHASE STEPS PER MEMCLK PERIOD	32

As shown in [Table 2-9](#), the Quartus II Fitter restricts the VCO operating range to 1212.1 MHz, rather than the 1515 MHz of [Table 2-8](#). This restriction produces a phase step mismatch between the PLL generated by the Quartus II Fitter and the PHY sequencer setup written in the RTL. Because the calibration process expects a common step size, the resulting design does not function properly in either the prototype FPGA or in the HardCopy device.

If you choose to prototype in a slower speed grade FPGA (C4) and target a HardCopy device, you must generate the ALTMEMPHY IP for the mid-speed grade FPGA to ensure that proper values are chosen for both the FPGA and HardCopy devices—this applies whether a performance improvement is desired or not.

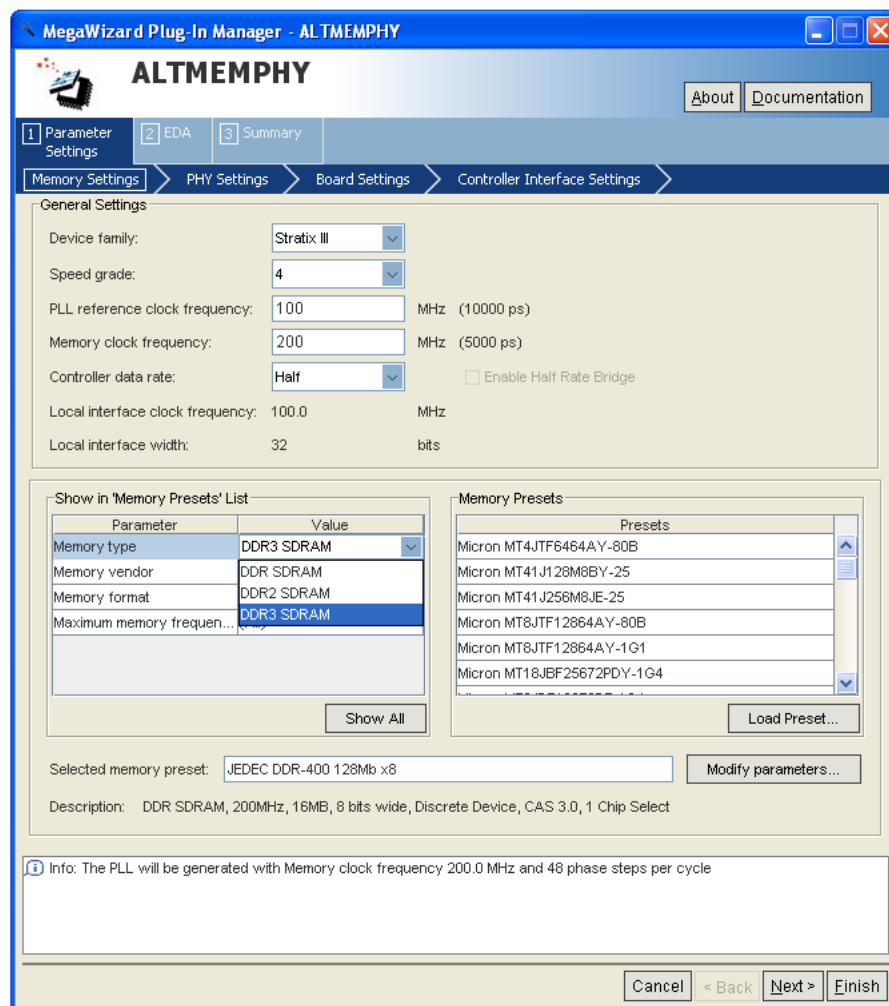
- For information about HardCopy issues such as vertical I/O overhang, PLLs adjacent to I/Os, performance improvement, and timing closure, refer to [HardCopy III Device I/O Features](#) in the *HardCopy III Device Handbook, Volume 1*, and [HardCopy IV Device I/O Features](#) in the *HardCopy IV Device Handbook, Volume 1*.

ALTMEMPHY Parameter Settings

The **Parameter Settings** page in the ALTMEMPHY parameter editor (Figure 3–1) allows you to parameterize the following settings:

- Memory Settings
- PHY Settings
- Board Settings

Figure 3–1. ALTMEMPHY Parameter Settings Page



The text window at the bottom of the MegaWizard Plug-In Manager displays information about the memory interface, warnings, and errors if you are trying to create something that is not supported. The **Finish** button is disabled until you correct all the errors indicated in this window.

The following sections describe the four tabs of the **Parameter Settings** page in more detail.

Memory Settings

In the **Memory Settings** tab, you can select a particular memory device for your system and choose the frequency of operation for the device. Under **General Settings**, you can choose the device family, speed grade, and clock information. In the middle of the page (left-side), you can filter the available memory device listed on the right side of the **Memory Presets** dialog box, refer to [Figure 3-1](#). If you cannot find the exact device that you are using, choose a device that has the closest specifications, then manually modify the parameters to match your actual device by clicking **Modify parameters**, next to the **Selected memory preset** field.

[Table 3-1](#) describes the **General Settings** available on the **Memory Settings** page of the ALTMEMPHY parameter editor.

Table 3-1. General Settings

Parameter Name	Description
Device family	Targets device family (for example, Stratix III). Table 1-2 on page 1-3 shows supported device families. The device family selected here must match the device family selected on the MegaWizard page 2a.
Speed grade	Selects a particular speed grade of the device (for example, 2, 3, or 4 for the Stratix III device family).
PLL reference clock frequency	Determines the clock frequency of the external input clock to the PLL. Ensure that you use three decimal points if the frequency is not a round number (for example, 166.667 MHz or 100 MHz) to avoid a functional simulation or a PLL locking problem.
Memory clock frequency	Determines the memory interface clock frequency. If you are operating a memory device below its maximum achievable frequency, ensure that you enter the actual frequency of operation rather than the maximum frequency achievable by the memory device. Also, ensure that you use three decimal points if the frequency is not a round number (for example, 333.333 MHz or 400 MHz) to avoid a functional simulation or a PLL locking issue.
Controller data rate	Selects the data rate for the memory controller. Sets the frequency of the controller to equal to either the memory interface frequency (full-rate) or half of the memory interface frequency (half-rate). The full-rate option is not available for DDR3 SDRAM devices.
Enable half rate bridge	This option is only available for HPC II full-rate controller. Turn on to keep the controller in the memory full clock domain while allowing the local side to run at half the memory clock speed, so that latency can be reduced.
Local interface clock frequency	Value that depends on the memory clock frequency and controller data rate, and whether or not you turn on the Enable Half Rate Bridge option.
Local interface width	Value that depends on the memory clock frequency and controller data rate, and whether or not you turn on the Enable Half Rate Bridge option.



When targeting a HardCopy device migration with performance improvement, the ALTMEMPHY IP should target the mid speed grade to ensure that the PLL and the PHY sequencer settings match. The compilation of the design can be executed in the faster speed grade.

Table 3–2 describes the options available to filter the **Memory Presets** that are displayed. This set of options is where you indicate whether you are creating a datapath for DDR3 SDRAM.

Table 3–2. Memory Presets List

Parameter Name	Description
Memory type	You can filter the type of memory to display, for example, DDR3 SDRAM.
Memory vendor	You can filter the memory types by vendor. JEDEC is also one of the options, allowing you to choose the JEDEC specifications. If your chosen vendor is not listed, you can choose JEDEC for the DDR3 SDRAM interfaces. Then, pick a device that has similar specifications to your chosen device and check the values of each parameter. Make sure you change the each parameter value to match your device specifications.
Memory format	You can filter the type of memory by format, for example, discrete devices or DIMM packages.
Maximum frequency	You can filter the type of memory by the maximum operating frequency.

Using the Preset Editor to Create a Custom Memory Preset

Pick a device in the **Memory Presets** list that is closest or the same as the actual memory device that you are using. Then, click the **Modify Parameters** button to parameterize the following settings in the **Preset Editor** dialog box:

- Memory attributes—These are the settings that determine your system's number of DQ, DQ strobe (DQS), address, and memory clock pins.
- Memory initialization options—These settings are stored in the memory mode registers as part of the initialization process.
- Memory timing parameters—These are the parameters that create and time-constrain the PHY.



Even though the device you are using is listed in **Memory Presets**, ensure that the settings in the **Preset Editor** dialog box are accurate, as some parameters may have been updated in the memory device datasheets.

You can change the parameters with a white background to reflect your system. You can also change the parameters with a gray background so the device parameters match the device you are using. These parameters in gray background are characteristics of the chosen memory device and changing them creates a new custom memory preset. If you click **Save As** (at the bottom left of the page) and save the new settings in the `<quartus_install_dir>\quartus\common\ip\altera\altmemphy\lib\` directory, you can use this new memory preset in other Quartus II projects created in the same version of the software.

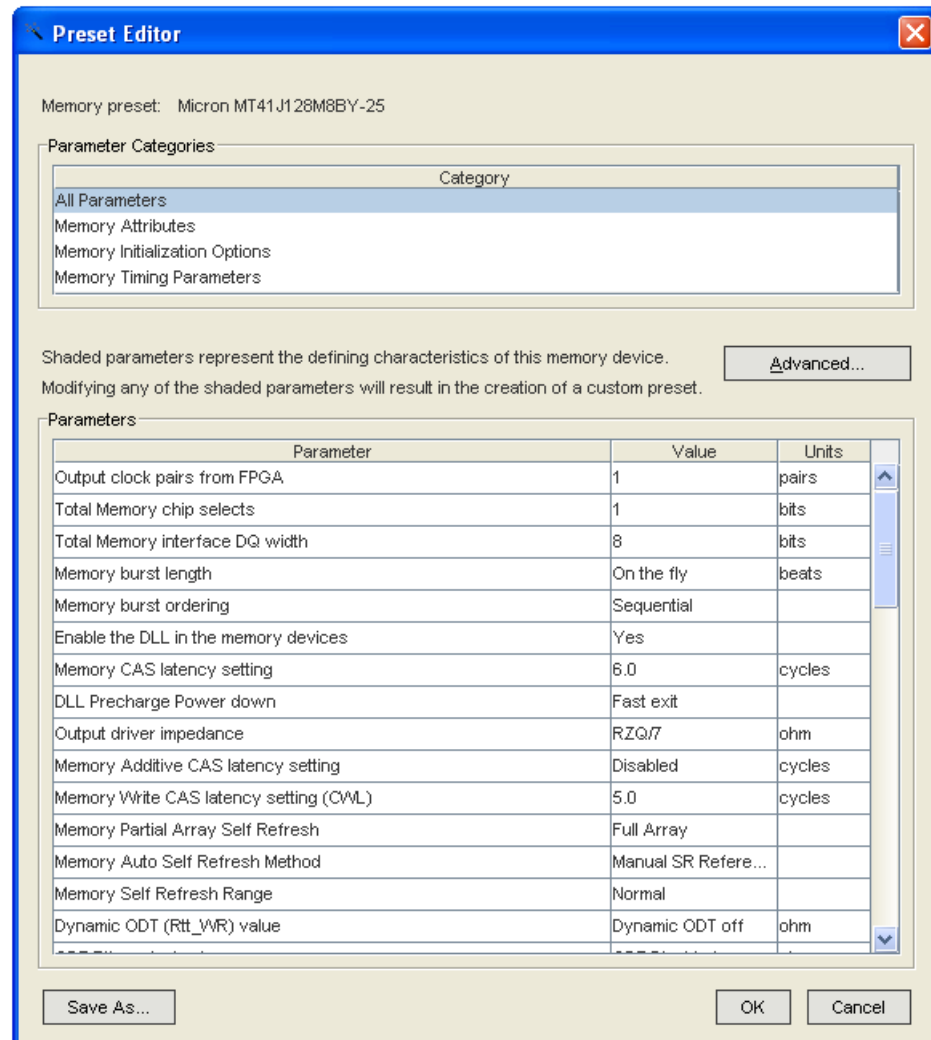
When you click **Save**, the new memory preset appears at the bottom of the **Memory Presets** list in the **Memory Settings** tab.



If you save the new settings in a directory other than the default directory, click **Load Preset** in the **Memory Settings** tab to load the settings into the **Memory Presets** list.

Figure 3-2 shows the **Preset Editor** dialog box for a DDR3 SDRAM.

Figure 3-2. DDR3 SDRAM Preset Editor



The **Advanced** option is only available for Arria II GX and Stratix IV devices. This option shows the percentage of memory specification that is calibrated by the FPGA. The percentage values are estimated by Altera based on the process variation.

Table 3-3 through Table 3-5 describe the DDR3 SDRAM parameters available for memory attributes, initialization options, and timing parameters.

Table 3-3. DDR3 SDRAM Attributes Settings (Part 1 of 2)

Parameter Name	Range (1)	Units	Description
Output clock pairs from FPGA	1-6	pairs	Defines the number of differential clock pairs driven from the FPGA to the memory. Memory clock pins use the signal splitter feature in Arria II GX, Stratix III, and Stratix IV devices for differential signaling. The ALTMEMPHY parameter editor displays an error on the bottom of the window if you choose more than one for DDR3 SDRAM interfaces.
Total Memory chip selects	1, 2, 4, or 8	bits	Sets the number of chip selects in your memory interface. The number of chip selects defines the depth of your memory. You are limited to the range shown as the local side binary encodes the chip select address.
Memory interface DQ width	4-288	bits	Defines the total number of DQ pins on the memory interface. If you are interfacing with multiple devices, multiply the number of devices with the number of DQ pins per device. Even though the GUI allows you to choose 288-bit DQ width, DDR3 SDRAM variations are only supported up to 80-bit width due to restrictions in the board layout which affects timing at higher data width. Furthermore, the interface data width is limited by the number of pins on the device. For best performance, have the whole interface on one side of the device.
Mirror addressing	—	—	On multiple rank DDR3 SDRAM DIMMs address signals are routed differently to each rank; referred to in the JEDEC specification as address mirroring. Enter ranks with mirrored addresses in this field. There is one bit per chip select. For example, for four chip selects, enter 1011 to mirror the address on chip select #3, #1, and #0.
Register Control Word 0-15 for Registered DIMMs	—	bits	Register Control Word values for the DDR3 registered DIMMs. The values are available in the memory data sheet of the respective registered DIMMs.
Memory vendor	Elpida, JEDEC, Micron, Samsung, Hynix, Nanya, other	—	Lists the name of the memory vendor for all supported memory standards.
Memory format	Discrete Device, Unbuffered DIMM	—	Specifies whether you are interfacing with devices or modules. SODIMM and MicroDIMM are supported under unbuffered DIMMs. The ALTMEMPHY megafunction for DDR3 SDRAM interfaces does not support registered DIMM format. Arria II GX devices only support DDR3 SDRAM components without leveling, for example, Discrete Device memory format.
Maximum memory frequency	See the memory device datasheet	MHz	Sets the maximum frequency supported by the memory.
Column address width	10-12	bits	Defines the number of column address bits for your interface.

Table 3-3. DDR3 SDRAM Attributes Settings (Part 2 of 2)

Parameter Name	Range (1)	Units	Description
Row address width	12–16	bits	Defines the number of row address bits for your interface. If your DDR3 SDRAM device's row address bus is 12-bit wide, set the row address width to 13 and set the 13 th bit to logic-level low (or leave the 13 th bit unconnected to the memory device) in the top-level file.
Bank address width	3	bits	Defines the number of bank address bits for your interface.
Chip selects per DIMM	1 or 2	bits	Defines the number of chip selects on each DIMM in your interface. Currently, calibration is done with all ranks but you can only perform timing analysis with one single-rank DIMM.
DQ bits per DQS bit	4 or 8	bits	Defines the number of data (DQ) bits for each data strobe (DQS) pin.
Drive DM pins from FPGA	Yes or No	—	Specifies whether you are using DM pins for write operation. Altera devices do not support DM pins with x4 mode.
Maximum memory frequency for CAS latency 5.0	80–700	MHz	Specifies the frequency limits from the memory data sheet per given CAS latency. The ALTMEMPHY MegaWizard Plug-In Manager generates a warning if the operating frequency with your chosen CAS latency exceeds this number. The lowest frequency supported by DDR3 SDRAM devices is 300 MHz.
Maximum memory frequency for CAS latency 6.0			
Maximum memory frequency for CAS latency 7.0			
Maximum memory frequency for CAS latency 8.0			
Maximum memory frequency for CAS latency 9.0			
Maximum memory frequency for CAS latency 10.0			

Note to Table 3-3:

(1) The range values depend on the actual memory device used.

Table 3-4. DDR3 SDRAM Initialization Options (Part 1 of 3)

Parameter Name	Range	Units	Description
Memory burst length	4, 8, on-the-fly	beats	Sets the number of words read or written per transaction.
Memory burst ordering	Sequential or Interleaved	—	Controls the order in which data is transferred between memory and the FPGA during a read transaction. For more information, refer to the memory device datasheet.
DLL precharge power down	Fast exit or Slow exit	—	Sets the mode register setting to disable (Slow exit) or enable (Fast exit) the memory DLL when CKE is disabled.

Table 3-4. DDR3 SDRAM Initialization Options (Part 2 of 3)

Parameter Name	Range	Units	Description
Enable the DLL in the memory devices	Yes or No	—	Enables the DLL in the memory device when set to Yes . You must always enable the DLL in the memory device as Altera does not guarantee any ALTMEMPHY operation when the DLL is turned off. All timings from the memory devices are invalid when the DLL is turned off.
ODT R_{tt} nominal value	ODT disable, RZQ/4, RZQ/2, RZQ/6	W	RZQ in DDR3 SDRAM interfaces are set to 240 Ω . Sets the on-die termination (ODT) value to either 60 Ω (RZQ/4), 120 Ω (RZQ/2), or 40 Ω (RZQ/6). Set this to ODT disable if you are not planning to use ODT. For a single-ranked DIMM, set this to RZQ/4 .
Dynamic ODT (R_{tt_WR}) value	Dynamic ODT off, RZQ/4, RZQ/2	W	RZQ in DDR3 SDRAM interfaces are set to 240 Ω . Sets the memory ODT value during write operations to 60 Ω (RZQ/4) or 120 Ω (RZQ/2). As ALTMEMPHY only supports single rank DIMMs, you do not need this option (set to Dynamic ODT off).
Output driver impedance	RZQ/6 (Reserved) or RZQ/7	W	RZQ in DDR3 SDRAM interfaces are set to 240 Ω . Sets the output driver impedance from the memory device. Some devices may not have RZQ/6 available as an option. Be sure to check the memory device datasheet before choosing this option.
Memory CAS latency setting	5.0, 6.0, 7.0, 8.0, 9.0, 10.0	cycles	Sets the delay in clock cycles from the read command to the first output data from the memory.
Memory additive CAS latency setting	Disable, CL – 1, CL – 2	cycles	Allows you to add extra latency in addition to the CAS latency setting.
Memory write CAS latency setting (CWL)	5.0, 6.0, 7.0, 8.0	cycles	Sets the delay in clock cycles from the write command to the first expected data to the memory.
Memory partial array self refresh	Full array Half array {BA[2:0]=000,001, 010,011}, Quarter array {BA[2:0]=000,001}, , Eighth array {BA[2:0]=000}, Three Quarters array {BA[2:0]=010,011, 100,101,110,111}, Half array {BA[2:0]=100,101, 110,111}, Quarter array {BA[2:0]=110, 111}, Eighth array {BA[2:0]=111}	—	Determine whether you want to self-refresh only certain arrays instead of the full array. According to the DDR3 SDRAM specification, data located in the array beyond the specified address range are lost if self refresh is entered when you use this. This option is not supported by the DDR3 SDRAM Controller with ALTMEMPHY IP, so set to Full Array if you are using the Altera controller.

Table 3-4. DDR3 SDRAM Initialization Options (Part 3 of 3)

Parameter Name	Range	Units	Description
Memory auto self refresh method	Manual SR reference (SRT) or ASR enable (Optional)	—	Sets the auto self-refresh method for the memory device. The DDR3 SDRAM Controller with ALTMEMPHY IP currently does not support the ASR option that you need for extended temperature memory self-refresh.
Memory self refresh range	Normal or Extended	—	Determines the temperature range for self refresh. You need to also use the optional auto self refresh option when using this option. The Altera controller currently does not support the extended temperature self-refresh operation.

Table 3-5. DDR3 SDRAM Timing Parameter Settings (Part 1 of 3) (Note 1)

Parameter Name	Range	Units	Description
Time to hold memory reset before beginning calibration	0–1000000	μ s	Minimum time to hold the reset after a power cycle before issuing the MRS commands during the DDR3 SDRAM device initialization process.
t_{INIT}	0.001–1000	μ s	Minimum memory initialization time. After reset, the controller does not issue any commands to the memory during this period.
t_{MRD}	2–39	ns	Minimum load mode register command period. The controller waits for this period of time after issuing a load mode register command before issuing any other commands. t_{MRD} is specified in ns in the DDR3 SDRAM high-performance controller and in terms of t_{CK} cycles in Micron's device datasheet. Convert t_{MRD} to ns by multiplying the number of cycles specified in the datasheet times t_{CK} , where t_{CK} is the memory operation frequency and not the memory device's t_{CK} .
t_{RAS}	8–200	ns	Minimum active to precharge time. The controller waits for this period of time after issuing an active command before issuing a precharge command to the same bank.
t_{RCD}	4–65	ns	Minimum active to read-write time. The controller does not issue read or write commands to a bank during this period of time after issuing an active command.
t_{RP}	4–65	ns	Minimum precharge command period. The controller does not access the bank for this period of time after issuing a precharge command.
t_{REFI}	1–65534	μ s	Maximum interval between refresh commands. The controller performs regular refresh at this interval unless user-controlled refresh is turned on.
t_{RFC}	14–1651	ns	Minimum autorefresh command period. The length of time the controller waits before doing anything else after issuing an auto-refresh command.
t_{WR}	4–65	ns	Minimum write recovery time. The controller waits for this period of time after the end of a write transaction before issuing a precharge command.

Table 3-5. DDR3 SDRAM Timing Parameter Settings (Part 2 of 3) (Note 1)

Parameter Name	Range	Units	Description
t_{WTR}	1-6	t_{CK}	Minimum write-to-read command delay. The controller waits for this period of time after the end of a write command before issuing a subsequent read command to the same bank. This timing parameter is specified in clock cycles and the value is rounded off to the next integer.
t_{AC}	0-750	ps	DQ output access time.
t_{DQSK}	50-750	ps	DQS output access time from CK/CK# signals.
t_{DQSQ}	50-500	ps	The maximum DQS to DQ skew; DQS to last DQ valid, per group, per access.
t_{DQSS}	0-0.3	t_{CK}	Positive DQS latching edge to associated clock edge.
t_{DH}	10-600	ps	DQ and DM input hold time relative to DQS, which has a derated value depending on the slew rate of the differential DQS and DQ/DM signals. Ensure that you are using the correct number and that the value entered is referenced to $V_{REF}(dc)$, not $V_{IH}(dc)$ min or $V_{IL}(dc)$ max. Refer to “Derating Memory Setup and Hold Timing” on page 3-10 for more information about how to derate this specification.
t_{DS}	10-600	ps	DQ and DM input setup time relative to DQS, which has a derated value depending on the slew rate of the differential DQS signals and DQ/DM signals. Ensure that you are using the correct number and that the value entered is referenced to $V_{REF}(dc)$, not $V_{IH}(ac)$ min or $V_{IL}(ac)$ max. Refer to “Derating Memory Setup and Hold Timing” on page 3-10 for more information about how to derate this specification.
t_{DSH}	0.1-0.5	t_{CK}	DQS falling edge hold time from CK.
t_{DSS}	0.1-0.5	t_{CK}	DQS falling edge to CK setup.
t_{IH}	50-1000	ps	Address and control input hold time, which has a derated value depending on the slew rate of the CK and CK# clocks and the address and command signals. Ensure that you are using the correct number and that the value entered is referenced to $V_{REF}(dc)$, not $V_{IH}(dc)$ min or $V_{IL}(dc)$ max. Refer to “Derating Memory Setup and Hold Timing” on page 3-10 for more information about how to derate this specification.
t_{IS}	65-1000	ps	Address and control input setup time, which has a derated value depending on the slew rate of the CK and CK# clocks and the address and command signals. Ensure that you are using the correct number and that the value entered is referenced to $V_{REF}(dc)$, not $V_{IH}(ac)$ min or $V_{IL}(ac)$ max. Refer to “Derating Memory Setup and Hold Timing” on page 3-10 for more information about how to derate this specification.
t_{QHS}	0-700	ps	The maximum data hold skew factor.
t_{QH}	0.1-0.6	t_{CK}	DQ output hold time.

Table 3-5. DDR3 SDRAM Timing Parameter Settings (Part 3 of 3) (Note 1)

Parameter Name	Range	Units	Description
t_{RRD}	2.06–64	ns	The activate to activate time, per device, RAS to RAS delay timing parameter.
t_{FAW}	7.69–256	ns	The four-activate window time, per device.
t_{RTP}	2.06–64	ns	Read to precharge time.

Note to Table 3-5:

- (1) See the memory device data sheet for the parameter range. Some of the parameters may be listed in a clock cycle (t_{CK}) unit. If the MegaWizard Plug-In Manager requires you to enter the value in a time unit (ps or ns), convert the number by multiplying it with the clock period of your interface (and not the maximum clock period listed in the memory data sheet).

Derating Memory Setup and Hold Timing

Because the base setup and hold time specifications from the memory device datasheet assume input slew rates that may not be true for Altera devices, derate and update the following memory device specifications in the **Preset Editor** dialog box:

- t_{DS}
- t_{DH}
- t_{IH}
- t_{IS}



For Arria II GX and Stratix IV devices, you need not derate using the Preset Editor. You only need to enter the parameters referenced to V_{REF} and the deration is done automatically when you enter the slew rate information on the **Board Settings** tab.

After derating the values, you then need to normalize the derated value because Altera input and output timing specifications are referenced to V_{REF} . When the memory device setup and hold time numbers are derated and normalized to V_{REF} , update these values in the **Preset Editor** dialog box to ensure that your timing constraints are correct.

The following memory device specifications and update the **Preset Editor** dialog box with the derated value:

For example, according to JEDEC, 533-MHz DDR3 SDRAM has the following specifications, assuming 1V/ns DQ slew rate rising signal and 2V/ns DQS-DQSn slew rate:

- Base $t_{DS} = 25$
- Base $t_{DH} = 100$
- $V_{IH}(ac) = V_{REF} + 0.175 \text{ V}$
- $V_{IH}(dc) = V_{REF} + 0.100 \text{ V}$
- $V_{IL}(ac) = V_{REF} - 0.175 \text{ V}$
- $V_{IL}(dc) = V_{REF} - 0.100 \text{ V}$

The V_{REF} referenced setup and hold signals for a rising edge are:

$$t_{DS}(V_{REF}) = \text{Base } t_{DS} + \text{delta } t_{DS} + (V_{IH(ac)} - V_{REF}) / \text{slew_rate} = 25 + 0 + 175 = 200 \text{ ps}$$

$$t_{DH}(V_{REF}) = \text{Base } t_{DH} + \text{delta } t_{DH} + (V_{IH(dc)} - V_{REF}) / \text{slew_rate} = 100 + 0 + 100 = 200 \text{ ps}$$

If the output slew rate of the write data is different from 1V/ns, you have to first derate the t_{DS} and t_{DH} values, then translate these AC/DC level specs to V_{REF} specification.

For a 2V/ns DQ slew rate rising signal and 2V/ns DQS-DQS_n slew rate:

$$t_{DS}(V_{REF}) = \text{Base } t_{DS} + \text{delta } t_{DS} + (V_{IH(ac)} - V_{REF}) / \text{slew_rate} = 25 + 88 + 87.5 = 200.5 \text{ ps}$$

$$t_{DH}(V_{REF}) = \text{Base } t_{DH} + \text{delta } t_{DH} + (V_{IH(dc)} - V_{REF}) / \text{slew_rate} = 100 + 50 + 50 = 200 \text{ ps}$$

For a 0.5V/ns DQ slew rate rising signal and 1V/ns DQS-DQS_n slew rate:

$$t_{DS}(V_{REF}) = \text{Base } t_{DS} + \text{delta } t_{DS} + (V_{IH(ac)} - V_{REF}) / \text{slew_rate} = 25 + 5 + 350 = 380 \text{ ps}$$

$$t_{DH}(V_{REF}) = \text{Base } t_{DH} + \text{delta } t_{DH} + (V_{IH(dc)} - V_{REF}) / \text{slew_rate} = 100 + 10 + 200 = 310 \text{ ps}$$

PHY Settings

Click **Next** or the **PHY Settings** tab to set the options described in [Table 3-6](#). The options are available if they apply to the target Altera device.

Table 3-6. ALTMEMPHY PHY Settings (Part 1 of 2)

Parameter Name	Applicable Device Families	Description
Use dedicated PLL outputs to drive memory clocks	HardCopy II and Stratix II (prototyping for HardCopy II)	This option is disabled for DDR3 SDRAM.
Dedicated memory clock phase	HardCopy II and Stratix II (prototyping for HardCopy II)	This option is disabled for DDR3 SDRAM.
Use differential DQS	Arria II GX, Stratix III, and Stratix IV	This option is disabled for DDR3 SDRAM.
Enable external access to reconfigure PLL prior to calibration	HardCopy II, Stratix III, and Stratix IV (prototyping for HardCopy II)	When enabling this option for HardCopy II, Stratix III, and Stratix IV devices, the inputs to the ALTPLL_RECONFIG megafunction are brought to the top level for debugging purposes. This option allows you to reconfigure the PLL before calibration to adjust, if necessary, the phase of the memory clock (<code>mem_clk_2x</code>) before the start of the calibration of the resynchronization clock on the read side. The calibration of the resynchronization clock on the read side depends on the phase of the memory clock on the write side.

Table 3-6. ALTMEMPHY PHY Settings (Part 2 of 2)

Parameter Name	Applicable Device Families	Description
Instantiate DLL externally	All supported device families.	Use this option with Stratix III, Stratix IV, HardCopy III, or HardCopy IV devices, if you want to apply a non-standard phase shift to the DQS capture clock. The ALTMEMPHY DLL offsetting I/O can then be connected to the external DLL and the Offset Control Block.
Enable dynamic parallel on-chip termination (OCT)	Stratix III and Stratix IV	This option provides I/O impedance matching and termination capabilities. The ALTMEMPHY megafunction enables parallel termination during reads and series termination during writes with this option checked. Only applicable for DDR3 SDRAM interfaces where DQ and DQS are bidirectional. Using the dynamic termination requires that you use the OCT calibration block, which may impose a restriction on your DQS/DQ pin placements depending on your R _{UP} /R _{DN} pin locations. For more information, refer to either the <i>External Memory Interfaces in Stratix III Devices</i> chapter in volume 1 of the <i>Stratix III Device Handbook</i> or the <i>External Memory Interfaces in Stratix IV Devices</i> chapter in volume 1 of the <i>Stratix IV Device Handbook</i> .
Clock phase	Arria II GX	Adjusting the address and command phase can improve the address and command setup and hold margins at the memory device to compensate for the propagation delays that vary with different loadings. You have a choice of 0°, 90°, 180°, and 270°, based on the rising and falling edge of the <code>phy_clk</code> and <code>write_clk</code> signals. In Stratix IV and Stratix III devices, the clock phase is set to dedicated .
Dedicated clock phase	Stratix III and Stratix IV	When you use a dedicated PLL output for address and command, you can choose any legal PLL phase shift to improve setup and hold for the address and command signals. You can set this value to between 180° and 359° (the default is 240°). However, generally PHY timing requires a value of greater than 240° for half-rate designs.
Board skew	All supported device families except Arria II GX and Stratix IV devices	Maximum skew across any two memory interface signals for the whole interface from the FPGA to the memory (either a discrete memory device or a DIMM). This parameter includes all types of signals (data, strobe, clock, address, and command signals). You need to input the worst-case skew, whether it is within a DQS/DQ group, or across all groups, or across the address and command and clocks signals. This parameter generates the timing constraints in the <code>.sdc</code> file.
Autocalibration simulation options	All supported device families	Choose between Full Calibration (long simulation time), Quick Calibration , or Skip Calibration . For more information, refer to the <i>Simulation</i> section in volume 4 of the <i>External Memory Interface Handbook</i> .

Board Settings

Click **Next** or the **Board Settings** tab to set the options described in [Table 3-7](#). The board settings parameters are set to model the board level effects in the timing analysis. The options are available if you choose Arria II GX or Stratix IV device for your interface. Otherwise, the options are disabled.

Table 3-7. ALTMEMPHY Board Settings

Parameter Name	Units	Description
Number of slots/discrete devices	—	Sets the single-rank or multi-rank configuration.
CK/CK# slew rate (differential)	V/ns	Sets the differential slew rate for the CK and CK# signals.
Addr/command slew rate	V/ns	Sets the slew rate for the address and command signals.
DQ/DQS# slew rate (differential)	V/ns	Sets the differential slew rate for the DQ and DQS# signals.
DQ slew rate	V/ns	Sets the slew rate for the DQ signals.
Addr/command eye reduction (setup)	ns	Sets the reduction in the eye diagram on the setup side due to the ISI on the address and command signals.
Addr/command eye reduction (hold)	ns	Sets the reduction in the eye diagram on the hold side due to the ISI on the address and command signals.
DQ eye reduction	ns	Sets the total reduction in the eye diagram on the setup side due to the ISI on the DQ signals.
Delta DQS arrival time	ns	Sets the increase of variation on the range of arrival times of DQS due to ISI.
Min CK/DQS skew to DIMM	ns	Sets the minimum skew between the CK signal and any DQS signal when arriving at the same DIMM over all DIMMs.
Max CK/DQS skew to DIMM	ns	Sets the maximum skew between the CK signal and any DQS signal when arriving at the same DIMM over all DIMMs.
Max skew between DIMMs/devices	ns	Sets the largest skew or propagation delay on the DQ signals between ranks, especially true for DIMMs in different slots.
Max skew within DQS group	ns	Sets the largest skew between the DQ pins in a DQS group.
Max skew between DQS groups	ns	Sets the largest skew between DQS signals in different DQS groups.
Addr/command to CK skew	ns	Sets the skew or propagation delay between the CK signal and the address and command signals. The positive values represent the address and command signals that are longer than the CK signals, and the negative values represent the address and command signals that are shorter than the CK signals.

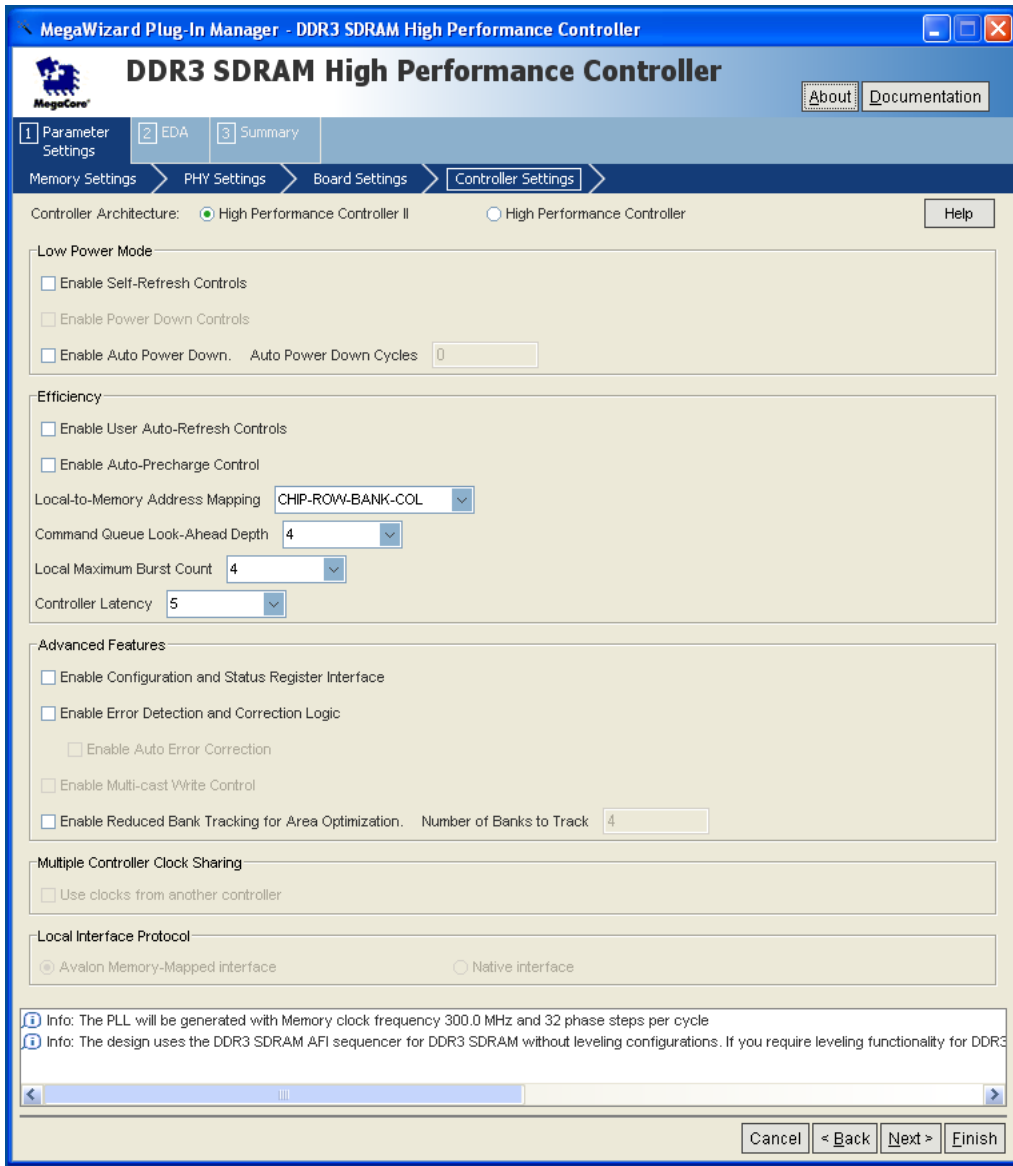
DDR3 SDRAM Controller with ALTMEMPHY Parameter Settings

The **Parameter Settings** page in the DDR3 SDRAM Controller with ALTMEMPHY parameter editor ([Figure 3-3](#)) allows you to parameterize the following settings:

- Memory Settings
- PHY Settings
- Board Settings
- Controller Settings

The **Memory Settings**, **PHY Settings**, and **Board Settings** tabs provide the same options as in the **ALTMEMPHY Parameter Settings** page.

Figure 3-3. DDR3 SDRAM Controller with ALTMEMPHY Settings



Controller Settings

Table 3-8 shows the options provided on the **Controller Settings** tab.

Table 3-8. Controller Settings (Part 1 of 3)

Parameter	Controller Architecture	Description
Controller architecture	—	Specifies the controller architecture.
Enable self-refresh controls	Both	Turn on to enable the controller to allow you to have control on when to place the external memory device in self-refresh mode, refer to “ User-Controlled Self-Refresh Logic ” on page 7-8 (HPC II).
Enable power down controls	HPC	Turn on to enable the controller to allow you to have control on when to place the external memory device in power-down mode.
Enable auto power down	HPC II	Turn on to enable the controller to automatically place the external memory device in power-down mode after a specified number of idle controller clock cycles is observed in the controller. You can specify the number of idle cycles after which the controller powers down the memory in the Auto Power Down Cycles field, refer to “ Automatic Power-Down with Programmable Time-Out ” on page 7-7.
Auto power down cycles	HPC II	Determines the desired number of idle controller clock cycles before the controller places the external memory device in a power-down mode. The legal range is 1 to 65,535. The auto power-down mode is disabled if you set the value to 0 clock cycles.
Enable user auto-refresh controls	Both	Turn on to enable the controller to allow you to issue a single refresh.
Enable auto-precharge control	HPC	Turn on to enable the auto-precharge control on the controller top level. Asserting the auto-precharge control signal while requesting a read or write burst allows you to specify whether or not the controller should close (auto-precharge) the current opened page at the end of the read or write burst.
Local-to-memory address mapping	HPC II	Allows you to control the mapping between the address bits on the Avalon interface and the chip, row, bank, and column bits on the memory interface. If your application issues bursts that are greater than the column size of the memory device, choose the Chip-Row-Bank-Column option. This option allows the controller to use its look-ahead bank management feature to hide the effect of changing the currently open row when the burst reaches the end of the column. On the other hand, if your application has several masters that each use separate areas of memory, choose the Chip-Bank-Row-Column option. This option allows you to use the top address bits to allocate a physical bank in the memory to each master. The physical bank allocation avoids different masters accessing the same bank which is likely to cause inefficiency, as the controller must then open and close rows in the same bank.
Command queue look-ahead depth	HPC II	Specifies a command queue look-ahead depth value to control the number of read or write requests the look-ahead bank management logic examines, refer to “ Command Queue ” on page 7-4.

Table 3-8. Controller Settings (Part 2 of 3)

Parameter	Controller Architecture	Description
Local maximum burst count	HPC II	Specifies a burst count to configure the maximum Avalon burst count that the controller slave port accepts.
Controller latency	HPC II	Specifies a latency for the controller. The default latency is 5 but you have the option to choose 4 to enhance the latency performance of your design at the expense of timing closure.
Enable configuration and status register interface	HPC II	Turn on to enable run-time configuration and status retrieval of the memory controller. Enabling this option adds an additional Avalon-MM slave port to the memory controller top level that allows run-time reconfiguration and status retrieving for memory timing parameters, memory address size and mode register settings, and controller features. If the Error Detection and Correction Logic option is enabled, the same slave port also allows you to control and retrieve the status of this logic. Refer to “Configuration and Status Register (CSR) Interface” on page 7-7 .
Enable error detection and correction logic	Both	Turn on to enable error correction coding (ECC) for single-bit error correction and double-bit error detection. Refer to “Error Correction Coding (ECC)” on page 6-5 for HPC, and “Error Correction Coding (ECC)” on page 7-7 for HPC II.
Enable auto error correction	HPC II	Turn on to allow the controller to perform auto correction when the ECC logic detects a single-bit error. Alternatively, you can turn off this option and schedule the error correction at a desired time for better system efficiency. Refer to “Error Correction Coding (ECC)” on page 7-7 .
Enable multi-cast write control	HPC II	Turn on to enable the multi-cast write control on the controller top level. Asserting the multi-cast write control when requesting a write burst causes the write data to be written to all the chip selects in the memory system. When you turn on this option together with the Enable User Auto-Refresh Controls option, the user refresh commands are issued to all chips. Multi-cast write is not supported for registered DIMM interfaces or when you turn on the Enable Error Detection and Correction Logic option.
Enable reduced bank tracking for area optimization	HPC II	Turn on to reduce the controller’s resource usage. By turning on this option, you reduce the number of bank tracking blocks in the controller. Refer to “Bank Management Logic” on page 7-4 for more information.
Number of banks to track	HPC II	Specifies the number of bank tracking blocks you want for your design. This option is only available if you turn on the Enable Reduced Bank Tracking for Area Optimization option. The value for this option depends on the value you specify for the Command Queue Look-Ahead Depth option. Refer to “Bank Management Logic” on page 7-4 for more information.

Table 3-8. Controller Settings (Part 3 of 3)

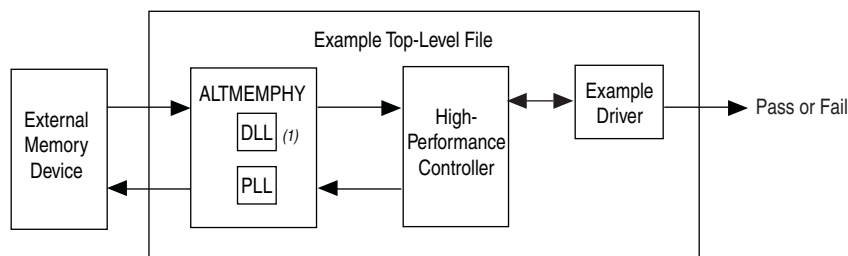
Parameter	Controller Architecture	Description
Multiple controller clock sharing	Both	This option is only available in SOPC Builder Flow. Turn on to allow one controller to use the Avalon clock from another controller in the system that has a compatible PLL. This option allows you to create SOPC Builder systems that have two or more memory controllers that are synchronous to your master logic.
Local interface protocol	HPC	Specifies the local side interface between the user logic and the memory controller. The Avalon-MM interface allows you to easily connect to other Avalon-MM peripherals. The HPC II architecture supports only the Avalon-MM interface.

After setting the parameters for the MegaCore function, you can now integrate the MegaCore function variation into your design, and compile and simulate your design. The following sections detail the steps you need to perform to compile and simulate your design.

Compiling the Design

Figure 4–1 shows the top-level view of the Altera high-performance controller design as an example of how your final design looks after you integrate the controller and the user logic.

Figure 4–1. High-Performance Controller System-Level Diagram



Note to Figure 4–1:

(1) When you choose **Instantiate DLL Externally**, DLL is instantiated outside the controller.

Before compiling a design with the ALTMEMPHY variation, you must edit some project settings, include the .sdc file, and make I/O assignments. I/O assignments include I/O standard, pin location, and other assignments, such as termination and drive strength settings. Some of these tasks are listed in the ALTMEMPHY **Generation** window. For most systems, Altera recommends that you use the **Advanced I/O Timing** feature by using the **Board Trace Model** command in the Quartus II software to set the termination and output pin loads for the device.

To use the Quartus II software to compile the example top-level file in the Quartus II software and perform post-compilation timing analysis, perform the following steps:

1. Set up the TimeQuest timing analyzer:
 - a. On the Assignments menu, click **Timing Analysis Settings**, select **Use TimeQuest Timing Analyzer during compilation**, and click **OK**.
 - b. Add the Synopsys Design Constraints (.sdc) file, `<variation name>_phy_dds_timing.sdc`, to your project. On the Project menu, click **Add/Remove Files in Project** and browse to select the file.
 - c. Add the .sdc file for the example top-level design, `<variation name>_example_top.sdc`, to your project. This file is only required if you are using the example as the top-level design.

2. You can either use the `<variation_name>_pin_assignments.tcl` or the `<variation_name>.ppf` file to apply the I/O assignments generated by the MegaWizard Plug-In Manager. Using the `.ppf` file and the Pin Planner gives you the extra flexibility to add a prefix to your memory interface pin names. You can edit the assignments either in the Assignment Editor or Pin Planner. Use one of the following procedures to specify the I/O standard assignments for pins:

- If you have a single SDRAM interface, and your top-level pins have default naming shown in the example top-level file, run `<variation name>_pin_assignments.tcl`.

or

- If your design contains pin names that do not match the design, edit the `<variation name>_pin_assignments.tcl` file before you run the script. To edit the `.tcl` file, perform the following steps:

- a. Open `<variation name>_pin_assignments.tcl` file.
- b. Based on the flow you are using, set the `sopc_mode` value to Yes or No.

- SOPC Builder System flow:

```
if {[info exists socp_mode]} {set socp_mode YES}
```

- MegaWizard Plug-In Manager flow:

```
if {[info exists socp_mode]} {set socp_mode NO}
```

- c. Type your preferred prefix in the `pin_prefix` variable. For example, to add the prefix `my_mem`, do the following:

```
if {[info exists set_prefix]}{set pin_prefix "my_mem_"}
```

After setting the prefix, the pin names are expanded as shown in the following:

- SOPC Builder System flow:

```
my_mem_cs_n_from_the_<your instance name>
```

- MegaWizard Plug-In Manager flow:

```
my_mem_cs_n[0]
```



If your top-level design does not use single bit bus notation for the single-bit memory interface signals (for example, `mem_dqs` rather than `mem_dqs[0]`), in the Tcl script you should change `set single_bit { [0] }` to `set single_bit {}`.

or

- Alternatively, to change the pin names that do not match the design, you can add a prefix to your pin names by performing the following steps:
 - a. On the Assignments menu, click **Pin Planner**.
 - b. On the Edit menu, click **Create/Import Megafunction**.
 - c. Select **Import an existing custom megafunction** and navigate to *<variation name>.ppf*.
 - d. Type the prefix you want to use in **Instance name**. For example, change **mem_addr** to **core1_mem_addr**.
3. Set the top-level entity to the top-level design.
 - a. On the File menu, click **Open**.
 - b. Browse to your SOPC Builder system top-level design or *<variation name>_example_top* if you are using MegaWizard Plug-In Manager, and click **Open**.
 - c. On the Project menu, click **Set as Top-Level Entity**.
4. Assign the DQ and DQS pin locations.
 - a. You should assign pin locations to the pins in your design, so the Quartus II software can perform fitting and timing analysis correctly.
 - b. Use either the Pin Planner or Assignment Editor to assign the clock source pin manually. Also choose which DQS pin groups should be used by assigning each DQS pin to the required pin. The Quartus II Fitter then automatically places the respective DQ signals onto suitable DQ pins within each group.



To avoid no-fit errors when you compile your design, ensure that you place the `mem_clk` pins to the same edge as the `mem_dq` and `mem_dqs` pins, and set an appropriate I/O standard for the non-memory interfaces, such as the clock source and the reset inputs, when assigning pins in your design. For example, for DDR3 SDRAM select **1.5 V**. Also select in which bank or side of the device you want the Quartus II software to place them.

The ×4 DIMM has the following mapping between DQS and DQ pins:

- DQS[0] maps to DQ[3:0]
- DQS[1] maps to DQ[7:4]
- DQS[2] maps to DQ[11:8]
- DQS[3] maps to DQ[15:12]

The DQS pin index in other ×4 DIMM configurations typically increases sequentially with the DQ pin index (DQS[0]: DQ[3:0]; DQS[1]: DQ[7:4]; DQS[2]: DQ[11:8])


5. For Stratix III and Stratix IV designs, if you are using advanced I/O timing, specify board trace models in the **Device & Pin Options** dialog box. If you are using any other device and not using advanced I/O timing, specify the output pin loading for all memory interface pins.

6. Select your required I/O driver strength (derived from your board simulation) to ensure that you correctly drive each signal or ODT setting and do not suffer from overshoot or undershoot.
7. To compile the design, on the Processing menu, click **Start Compilation**.

After you have compiled the example top-level file, you can perform RTL simulation or program your targeted Altera device to verify the example top-level file in hardware.

Simulating the Design

During system generation, SOPC Builder optionally generates a simulation model and testbench for the entire system, which you can use to easily simulate your system in any of Altera's supported simulation tools. The MegaWizard also generates a set of ModelSim[®] Tcl scripts and macros that you can use to compile the testbench, IP functional simulation models, and plain-text RTL design files that describe your system in the ModelSim simulation software (refer to “[Generated Files](#)” on page 2–6).

 For more information about simulating SOPC Builder systems, refer to [volume 4](#) of the *Quartus II Handbook* and *AN 351: Simulating Nios II Embedded Processor Designs*. For more information about how to include your board simulation results in the Quartus II software and how to assign pins using pin planners, refer to *ALTMEMPHY Design Tutorials* section in volume 6 of the *External Memory Interface Handbook*.

In ALTMEMPHY variations for DDR3 SDRAM with leveling and without leveling interfaces, you have the following three simulation options:


- Skip calibration—performs a static setup of the ALTMEMPHY megafunction to skip calibration and go straight into user mode.

Available for ×4 and ×8 DDR3 SDRAM. Skip calibration simulation is supported for 300 MHz through 400 MHz. There is no calibration in this simulation mode. As no phase calibration is performed, there must be no delays in the testbench.

The ALTMEMPHY megafunction is statically configured to provide the correct write and read latencies. Skip calibration provides the fastest simulation time for DDR3 SDRAM interfaces. Use the generated or vendor DDR3 SDRAM simulation models for this simulation option.

Skip calibration simulation between 300 MHz and 400 MHz supports CAS latency of 6 and a CAS write latency of 5.

 The additive latency and registered DIMMs must be disabled.

 Skip calibration is unavailable for DDR3 RDIMMs.

- Quick calibration—performs a calibration on a single pin and chip select.

Available for ×4 and ×8 DDR3 SDRAM. In quick calibration simulation mode, the sequencer only does clock cycle calibration. So there must be no delays (DDR3 DIMM modeling for example) in the testbench, because no phase calibration is performed. Quick calibration mode can be used between 300 MHz and 533 MHz. Both the generated or vendor DDR3 SDRAM simulation models support burst length on-the-fly changes during the calibration sequence.

- Full calibration—across all pins and chip selects. This option allows for longer simulation time.

Available for ×4 and ×8 DDR3 SDRAM between 300 MHz and 533 MHz. You cannot use the wizard-generated memory model, if you select **Full Calibration**. You must use a memory-vendor provided memory model that supports write leveling calibration.



If you are simulating your ALTMEMPHY-based design with a Denali model, Altera recommends that you use full calibration mode.



For more information about simulation, refer to the *Simulation* section in volume 4 of the *External Memory Interface Handbook*.

The ALTMEMPHY megafunction creates the datapath between the memory device and the memory controller, and user logic in various Altera devices. The ALTMEMPHY megafunction GUI helps you configure multiple variations of a memory interface. You can then connect the ALTMEMPHY megafunction variation with either a user-designed controller or with an Altera high-performance controller. In addition, the ALTMEMPHY megafunction and the Altera high-performance controllers are available for half-rate DDR3 SDRAM interfaces.



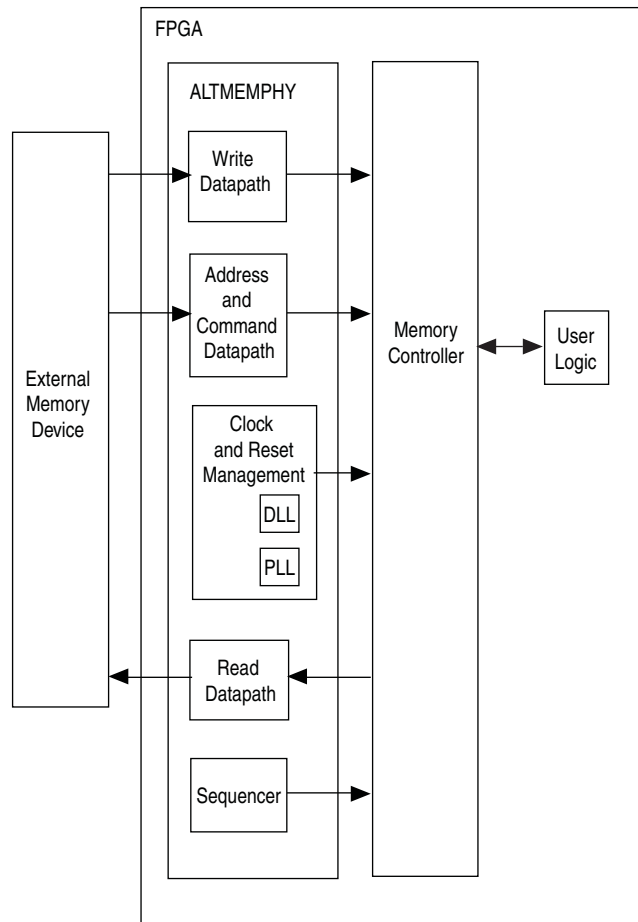
If the ALTMEMPHY megafunction does not meet your requirements, you can also create your own memory interface datapath using the ALTDLL and ALTDQ_DQS megafunctions, available in the Quartus II software. However, you are then responsible for every aspect of the interface, including timing analysis and debugging.

This chapter describes the DDR3 SDRAM ALTMEMPHY megafunction, which uses AFI as the interface between the PHY and the controller.

Block Description

Figure 5-1 on page 5-2 shows the major blocks of the ALTMEMPHY megafunction and how it interfaces with the external memory device and the controller. The ALTPLL megafunction is instantiated inside the ALTMEMPHY megafunction, so that you do not need to generate the clock to any of the ALTMEMPHY blocks.

Figure 5-1. ALTMEMPHY Megafunction Interfacing with the Controller and the External Memory



The ALTMEMPHY megafunction comprises the following blocks:

- Write datapath
- Address and command datapath
- Clock and reset management, including DLL and PLL
- Sequencer for calibration
- Read datapath

The major advantage of the ALTMEMPHY megafunction is that it supports an initial calibration sequence to remove process variations in both the Altera device and the memory device. In Arria series and Stratix series devices, the DDR3 SDRAM ALTMEMPHY calibration process centers the resynchronization clock phase into the middle of the captured data valid window to maximize the resynchronization setup and hold margin. During the user operation, the VT tracking mechanism eliminates the effects of VT variations on resynchronization timing margin.

Calibration

This section describes the calibration that the sequencer performs, to find the optimal clock phase for the memory interface. The calibration sequence is similar across families, but different depending on the following target memory interface:

- [DDR3 SDRAM Without Leveling](#)
- [DDR3 SDRAM With Leveling](#)

DDR3 SDRAM Without Leveling

The calibration process for the DDR3 SDRAM without leveling PHY includes the following steps:

- “Step 1: Memory Device Initialization”
- “Step 2: Write Training Patterns”
- “Step 3: Read Resynchronization (Capture) Clock Phase”
- “Step 4: Read and Write Datapath Timing”
- “Step 5: Address and Command Clock Cycle”
- “Step 6: Postamble”
- “Step 7: Prepare for User Mode”


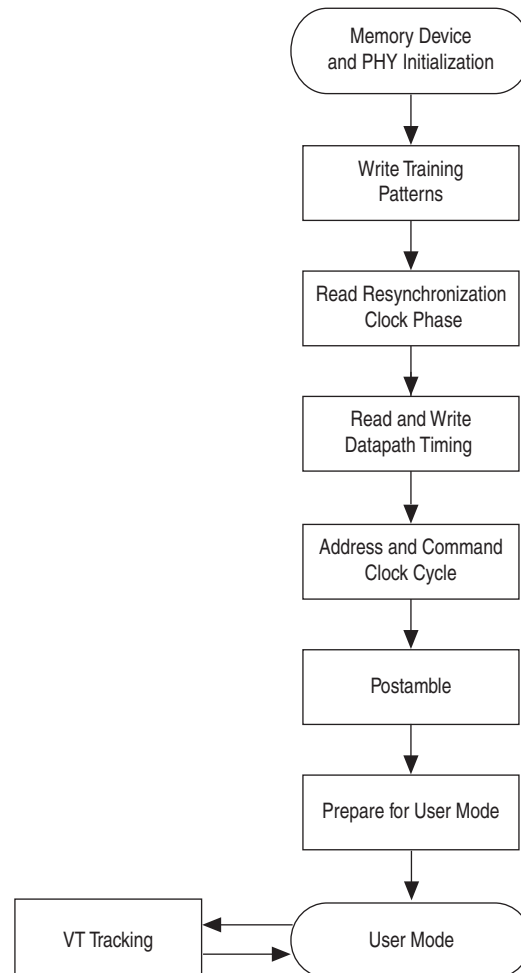
 For more detailed information about each calibration step, refer to the *Debugging* section in volume 4 of the *External Memory Interface Handbook*.

Figure 5-2 shows the calibration flow.

Figure 5-2. Calibration Flow—Without Leveling



Step 1: Memory Device Initialization

This step initializes the memory device according to the DDR3 SDRAM specification. The initialization procedure includes resetting the memory device, specifying the mode registers and memory device ODT setting, and initializing the memory device DLL. Calibration requires overriding some of the user-specified mode register settings, which are reverted in “Step 7: Prepare for User Mode”.


Step 2: Write Training Patterns

In this step, a pattern is written to the memory to be read in later calibration stages. The matched trace lengths to DDR3 SDRAM devices mean that after memory initialization, write capture functions. The pattern is 0x30F5 and comprises the following separately written patterns:

- All 0: 'b0000 - DDIO high and low bits held at 0
- All 1: 'b1111 - DDIO high and low bits held at 1
- Toggle: 'b0101 - DDIO high bits held at 0 and DDIO low bits held at 1

- Mixed: `'b0011` - DDIO high and low bits have to toggle

Loading a mixed pattern is complex, because write latency is unknown at this time. Two sets of write and read operations (single pin resynchronization (capture) clock phase sweeps, (“[Step 3: Read Resynchronization \(Capture\) Clock Phase](#)”) are required to accurately write the mixed pattern to memory.

 Memory bank 0, row 0, and column addresses 0 to 55 store calibration data.

Step 3: Read Resynchronization (Capture) Clock Phase

This step adjusts the phase of the resynchronization clock to determine the optimal phase that gives the greatest margin. The resynchronization clock captures the outputs of DQS capture registers (DQS is the capture clock).

To correctly calibrate resynchronization clock phase, based on a data valid window, requires 720° of phase sweep.

Step 4: Read and Write Datapath Timing

In this step, the sequencer calculates the calibrated write latency (the `ctl_wlat` signal) between write commands and write data. The sequencer also calculates the calibrated read latency (the `ctl_rlat` signal) between the issue of a read command and valid read data. Both read and write latencies are output to a controller. In addition to advertising the read latency, the sequencer calibrates a read data valid signal to the delay between a controller issuing a read command and read data returning. The controller can use the read data valid signal in place of the advertised read latency, to determine when the read data is valid.

Step 5: Address and Command Clock Cycle

This step optionally adds an additional memory clock cycle of delay from the address and command path. This delay aligns the write data to the memory commands given in the controller clock domain. If you require this delay, this step reruns the calibration (“[Step 2: Write Training Patterns](#)” to “[Step 4: Read and Write Datapath Timing](#)”) to calibrate to the new setting.

Step 6: Postamble

This step sets the correct clock cycle for the postamble path. The aim of the postamble path is to eliminate false DQ data capture because of postamble glitches on the DQS signal, through an override on DQS. This step ensures the correct clock cycle timing of the postamble enable (override) signal.

Step 7: Prepare for User Mode

In this step, the PHY applies user mode register settings and performs periodic VT tracking.

VT Tracking

VT tracking is a background process that tracks the voltage and temperature variations to maintain the relationship between the resynchronization or capture clock and the data valid window that are achieved at calibration.

When the data calibration phase is completed, the sequencer issues the mimic calibration sequence every 128 ms.

During initial calibration, the mimic path is sampled using the measure clock (measure_clk has a _1x or _2x suffix, depending whether the ALTMEMPHY is a full-rate or half-rate design). The sampled value is then stored by the sequencer. After a sample value is stored, the sequencer uses the PLL reconfiguration logic to change the phase of the measure clock by one VCO phase tap. The control sequencer then stores the sampled value for the new mimic path clock phase. This sequence continues until all mimic path clock phase steps are swept. After the control sequencer stores all the mimic path sample values, it calculates the phase which corresponds to the center of the high period of the mimic path waveform. This reference mimic path sampling phase is used during the VT tracking phase.

In user mode, the sequencer periodically performs a tracking operation as defined in the tracking calibration description. At the end of the tracking calibration operation, the sequencer compares the most recent optimum tracking phase against the reference sampling phase. If the sampling phases do not match, the mimic path delays have changed due to voltage and temperature variations.

When the sequencer detects that the mimic path reference and most recent sampling phases do not match, the sequencer uses the PLL reconfiguration logic to change the phase of the resynchronization clock by the VCO taps in the same direction. This allows the tracking process to maintain the near-optimum capture clock phase setup during data tracking calibration as voltage and temperature vary over time.

The relationship between the resynchronization or capture clock and the data valid window is maintained by measuring the mimic path variations due to the VT variations and applying the same variation to the resynchronization clock.

Mimic Path

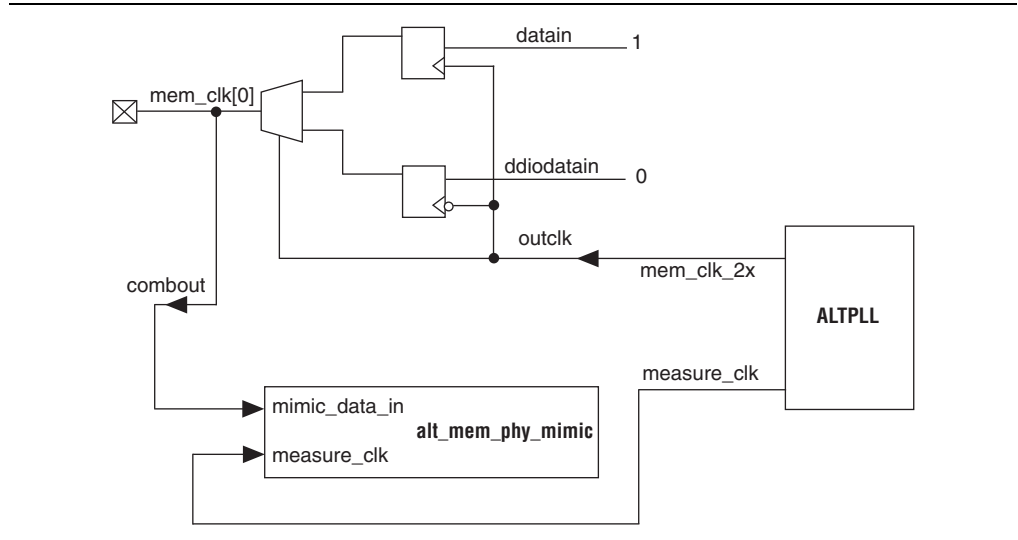
The mimic path mimics the FPGA elements of the round-trip delay, which enables the calibration sequencer to track delay variation due to VT changes during the memory read and write transactions without interrupting the operation of the ALTMEMPHY megafunction.

The assumption made about the mimic path is that the VT variation on the round trip delay path that resides outside of the FPGA is accounted for in the board skew and memory parameters entered in the MegaWizard Plug-In Manager. For the write direction, any VT variation in the memory devices is accounted for by timing analysis.

Figure 5-3 shows the mimic path in Stratix II and Stratix II GX devices, which mimics the delay of the clock outputs to the memory as far as the pads of the FPGA and the delay from the input DQS pads to a register in the FPGA core. During the tracking operation, the sequencer measures the delay of the mimic path by varying the phase of the measure clock. Any change in the delay of the mimic path indicates a corresponding change in the round-trip delay, and a corresponding adjustment is made to the phase of the resynchronization or capture clock.

The mimic path in Arria II GX, Stratix III and Stratix IV devices is similar to Figure 5-3. The only difference is that the `mem_clk[0]` pin is generated by DDIO register; `mem_clk_n[0]` is generated by signal splitter.

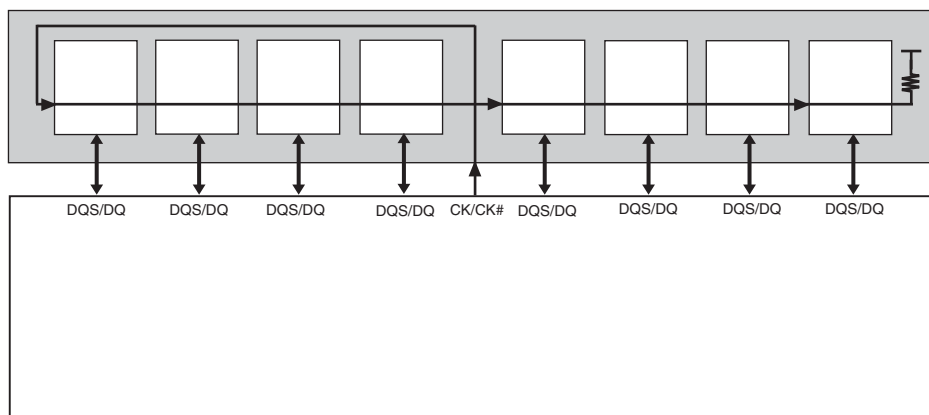
Figure 5-3. Mimic Path



DDR3 SDRAM With Leveling

The calibration process for the DDR3 SDRAM PHY (with leveling) assumes an interface in an unbuffered DIMM format, where the clock uses a fly-by termination, refer to Figure 5-4.

Figure 5-4. DDR3 SDRAM Unbuffered Module Clock Topology



With fly-by termination, each DDR3 SDRAM device on the DIMM sees the CK/CKn edges at different times. Therefore, the sequencer must adjust the clock to launch the DQS/DQSn and DQ signals so that it is appropriately aligned to the CK/CKn signals on each device.

The DDR3 SDRAM leveling sequencer during calibration writes to the following locations:

- Banks 0, 1, and 2
- Row 0
- All columns

Bank 0 is written to for the block training pattern and clock cycle calibration (DQ_1T and AC_1T). Bank 1 is written to for write deskew (DQ). Bank 2 is written to for write deskew (DM). For each bank, only row 0 is accessed. The number of columns accessed can vary, but you should avoid writing to all columns in these banks and row 0.

The calibration process for the DDR3 SDRAM PHY with leveling includes the following steps:

- “Step 1: Memory Device Initialization”
- “Step 2: Write Leveling”
- “Step 3: Write Training Patterns”
- “Step 4: Read Resynchronization”
- “Step 5: Address and Command Path Clock Cycle”
- “Step 7: Write Clock Path Setup”
- “Step 8: Prepare for User Mode”



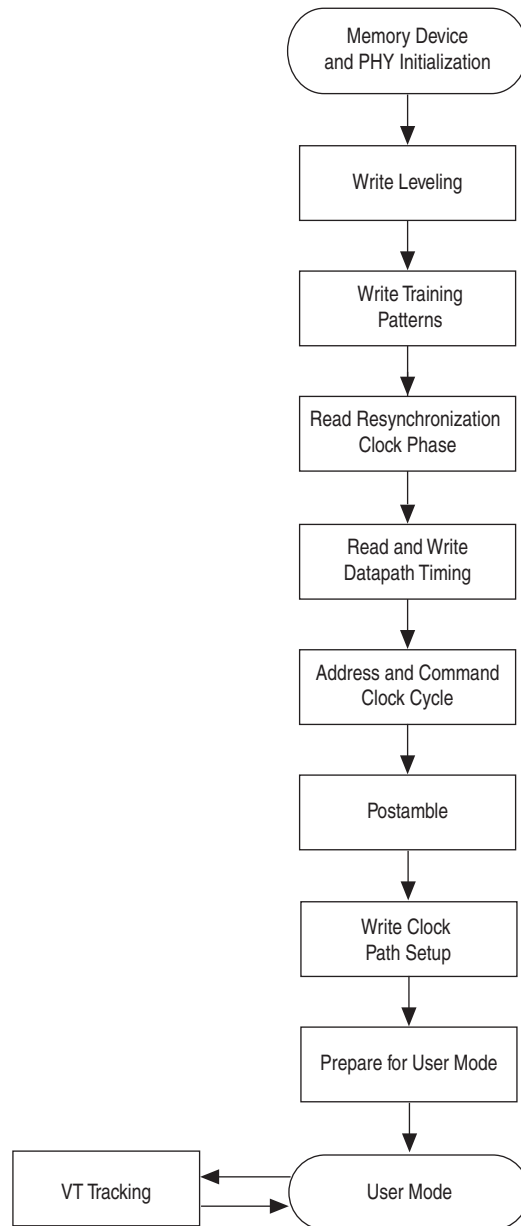
No steps can be bypassed. Therefore, even if you are using only one DDR3 SDRAM DIMM, all the calibration sequences are performed.

The calibration assumes that the skew for all the DQS launch times is one clock period maximum.

The VT tracking portion of the DDR3 SDRAM sequencer is similar to that of the DDR or DDR2 SDRAM sequencer.



Figure 5-5 shows the calibration flow.

Figure 5-5. Calibration Flow—DDR3 SDRAM (with leveling)



Step 1: Memory Device Initialization

This step initializes the memory device per the DDR3 SDRAM specification. The initialization procedure includes resetting the memory device, specifying the mode registers and memory device ODT setting, and initializing the memory device DLL. Some of these settings may be different to those you set; however, these are changed to the correct values (at the end of calibration) in “Step 8: Prepare for User Mode”.

-  On multiple rank DDR3 SDRAM DIMMs, address signals are routed differently to each rank (referred to in the JEDEC specification as address mirroring). Ranks with address mirroring can be specified in the memory Preset Editor in the **Mirror addressing** field.
-  RTL simulation of address mirroring is not currently supported by the memory model generated with the example testbench. To simulate successfully, you need a DDR3 DIMM model compatible with address mirroring.

Step 2: Write Leveling

This step aligns the DQS edge with the CK edge at each memory device in the DIMM, which includes calibrating the write-leveling delay chains, programmable output delay chain, and using the t_{DQSS} -margin register in the DDR3 SDRAM to monitor the relationship between the DQS edge and the CK edge. The calibration uses one DQ pin per DQS group (prime DQ) for write leveling calibration.

Step 3: Write Training Patterns

This step only allows you to write a pattern to be read later to calibrate the read path.

To satisfy the DDR3 SDRAM JEDEC specification, DQ is held constant during this step to ensure that there are no DQ timing violations. The DQS is then toggled, followed by a write command. A combination of burst length of four and burst length of eight operations ensure that it is correctly written. There are three different DQ patterns written in this step:

- All 0: 0×00, 0×00, 0×00, 0×00, 0×00, 0×00, 0×00, 0×00
- All 1: 0×FF, 0×FF, 0×FF, 0×FF, 0×FF, 0×FF, 0×FF, 0×FF
- Mixed: 0×00, 0×00, 0×00, 0×00, 0×FF, 0×FF, 0×FF, 0×FF

Step 4: Read Resynchronization

This step adjusts the phase of the resynchronization clock to determine the optimal clock phase that gives the most margin, similar to the resynchronization calibration done in DDR and DDR2 SDRAM PHYs.

This step uses the read-leveling delay chain and the PLL reconfigurable clock output to adjust the resynchronization clock phase for each DQS group.

Step 5: Address and Command Path Clock Cycle

This step word-aligns the read data within and between each DQS group so that data can be presented in one clock cycle.

Step 6: Postamble

This step sets the correct clock cycle and clock phase shift for the postamble path. With the read resynchronization process, the sequencer can approximate when the postamble enable must be asserted. The sequencer then tries to incrementally assert the postamble enable signal (per DQS group) earlier until there is a read failure. This ensures the optimal clock phase for the system's postamble enable signal.

Step 7: Write Clock Path Setup


After the sequencer has the optimum settings for read capture and resynchronization setup, the sequencer calibrates the write datapath by configuring the alignment registers in the IOE and the DQ and DQS phase shift per DQS group. This step ensures that the write data can be presented on the same clock cycle from controller, but launched at the appropriate time for each DQS group to the DDR3 SDRAM memory devices.

Step 8: Prepare for User Mode

In this step, the sequencer sends the calibrated write latency between command and write data (the `ctl_wlat` signal) to the controller. The PHY then applies user mode register settings and performs setup for periodic VT tracking.

 Deskew is automatically enabled above 400.000 MHz.

VT Tracking

 For information on VT tracking for DDR3 SDRAM with leveling, refer to “VT Tracking” on page 5-5.

Mimic Path

 For information on mimic path for DDR3 SDRAM with leveling, refer to “Mimic Path” on page 5-6.

Address and Command Datapath

This topic discusses the address and command datapath.

Arria II GX Devices

The address and command datapath is responsible for taking the address and command outputs from the controller and converting them from half-rate clock to full-rate clock. Two types of addressing are possible:

- 1T (full rate)—the duration of the address and command is a single memory clock cycle (`mem_clk_2x`, [Figure 5-6](#)). This applies to all address and command signals in full-rate designs or `mem_cs_n`, `mem_cke`, and `mem_odt` signals in half-rate designs.
- 2T (half rate)—the duration of the address and command is two memory clock cycles. For half-rate designs, the ALTMEMPHY megafunction supports only a burst size of four, which means the burst size on the local interface is always set to 1. The size of the data is $4n$ -bits wide on the local side and is n -bits wide on the memory side. To transfer all the $4n$ -bits at the double data rate, two memory-clock cycles are required. The new address and command can be issued to memory every two clock cycles. This scheme applies to all address and command signals, except for `mem_cs_n`, `mem_cke`, and `mem_odt` signals in half-rate mode.


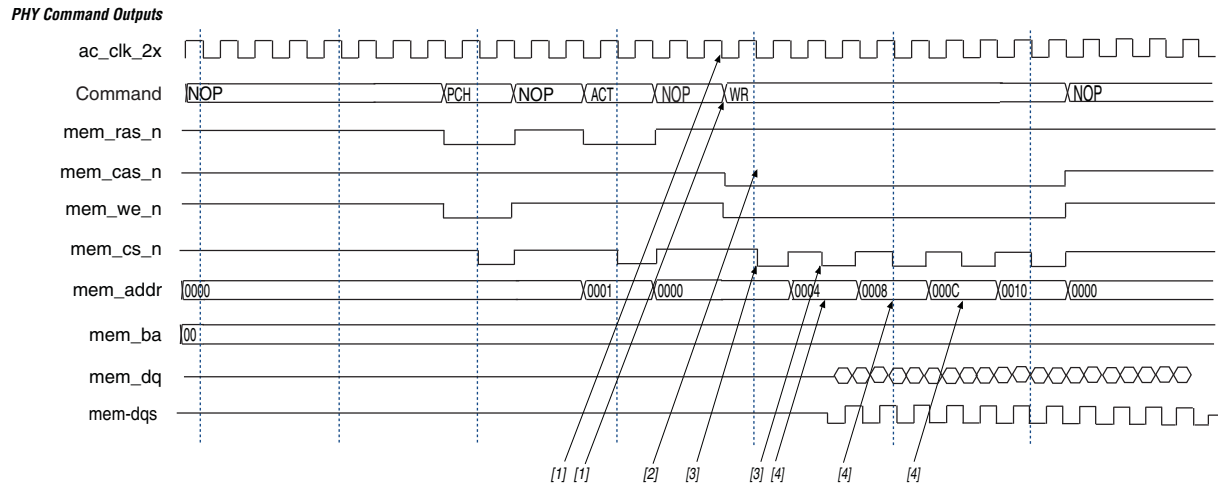
 Refer to [Table 5-1 on page 5-14](#) to see the frequency relationship of `mem_clk_2x` with the rest of the clocks.

Figure 5-6 shows a 1T chip select signal (`mem_cs_n`), which is active low, and disables the command in the memory device. All commands are masked when the chip-select signal is inactive. The `mem_cs_n` signal is considered part of the command code.


Figure 5-6. Arria II GX Address and Command Datapath




The command interface is made up of the signals `mem_ras_n`, `mem_cas_n`, `mem_we_n`, `mem_cs_n`, `mem_cke`, and `mem_odt`.

The waveform in Figure 5-6 shows a NOP command followed by five back-to-back write commands. The following sequence corresponds with the numbered items in Figure 5-6.

1. The commands are asserted either on the rising edge of `ac_clk_2x`. The `ac_clk_2x` is derived from either `mem_clk_2x` (0°), `write_clk_2x` (270°), or the inverted variations of those two clocks (for 180° and 90° phase shifts). This depends on the setting of the address and command clock in the ALTMEMPHY parameter editor. Refer to “Address and Command Datapath” on page 5-11 for illustrations of this clock in relation to the `mem_clk_2x` or `write_clk_2x` signals.
2. All address and command signals (except for `mem_cs_n`, `mem_cke`, and `mem_odt` signals) remain asserted on the bus for two clock cycles, allowing sufficient time for the signals to settle.
3. The `mem_cs_n`, `mem_cke`, and `mem_odt` signals are asserted during the second cycle of the address/command phase. By asserting the chip-select signal in alternative cycles, back-to-back read or write commands can be issued.
4. The address is incremented every other `ac_clk_2x` cycle.

 The `ac_clk_2x` clock is derived from either `mem_clk_2x` (when you choose 0° or 180° phase shift) or `write_clk_2x` (when you choose 90° or 270° phase shift).

 The address and command clock can be 0 , 90 , 180 , or 270° from the system clock.

Stratix III and Stratix IV Devices

The address and command clock is one of the PLL dedicated clock outputs whose phase can be adjusted to meet the setup and hold requirements of the memory clock. The Stratix III address and command clock, `ac_clk_1x`, is half rate. The command and address pins use the DDIO output circuitry to launch commands from either the rising or falling edges of the clock. The chip select (`mem_cs_n`), clock enable (`mem_cke`), and `mem_odt` pins are enabled on one memory clock cycle basis and can be launched from either the rising or falling edge of the `ac_clk_1x` signal, while the address and other command pins are enabled for two memory clock cycles and can also be launched from either the rising or falling edge of `ac_clk_1x` signal. It is the responsibility of the controller to maintain the relative timing of the signals.

The DDR3 SDRAM PHY generates a write latency output `ctl_wlat` that indicates the number of `ctl_clk` cycles between the write command being issued, `ctl_cs_n` asserted, and `ctl_dqs_burst` being asserted. This `ctl_wlat` signal is only valid when calibration has been successfully completed by the ALTMEMPHY sequencer and does not change at any point during normal user mode operation. The value on `ctl_wlat` includes the effect of the following as determined during calibration:

- CAS write latency (CWL)
- Additive latency
- Datapath latencies and relative phases
- Board and memory module layout
- Address and command path latency and 1T register setting which is dynamically set up to take into account any leveling effects

Clock and Reset Management

The clocking and reset block is responsible for clock generation, reset management, and phase shifting of clocks. It also has control of clock network types that route the clocks, which is handled in the `<variation_name>_alt_mem_phy_clk_reset` module in the `<variation_name>_alt_mem_phy.v/.vhd` file.

Clock Management

The clock management feature allows the ALTMEMPHY megafunction to work out the optimum phase during calibration, and to track voltage and temperature variation relies on phase shifting the clocks relative to each other.



Certain clocks require phase shifting during the ALTMEMPHY megafunction operation.


You can implement clock management circuitry using PLLs and DLLs.

The ALTMEMPHY MegaWizard Plug-In Manager automatically generates an ALTPLL megafunction instance. The ALTPLL megafunction generates the different clock frequencies and relevant phases used within the ALTMEMPHY megafunction.

The available device families have different PLL capabilities. The minimum PHY requirement is to have 16 phases of the highest frequency clock. The PLL uses **With No Compensation** option to minimize jitter. Changing the PLL compensation to a different operation mode may result in inaccurate timing results.

The input clock to the PLL does not have any other fan-out to the PHY, so you do not have to use a global clock resource for the path between the clock input pin to the PLL. You must use the PLL located in the same device quadrant or side as the memory interface and the corresponding clock input pin for that PLL, to ensure optimal performance and accurate timing results from the Quartus II software.

You must choose a PLL and PLL input clock pin that are located on the same side of the device as the memory interface to ensure minimal jitter. Also, ensure that the input clock to the PLL is stable before the PLL locks. If not, you must perform a manual PLL reset (by driving the `global_reset_n` signal low) and relock the PLL to ensure that the phase relationship between all PLL outputs is properly set.

 If the design cascades PLLs, the source (upstream) PLL should have a low-bandwidth setting, and the destination (downstream) PLL should have a high-bandwidth setting. Adjacent PLLs cascading is recommended to reduce clock jitter.

Cross-device cascading PLLs are only allowed in Stratix III devices with the following conditions:

- Upstream PLL: 0.59 MHz \leq upstream PLL bandwidth $<$ 1 MHz. The upstream PLL should use the **With No Compensation** operation mode.
- Downstream PLL: downstream PLL bandwidth $>$ 2 MHz.


 For more information about the VCO frequency range and the available phase shifts, refer to the *Clock Networks and PLLs* chapter in the respective device family handbook.

Table 5-1 shows the clock outputs that Arria II GX devices use.

Table 5-1. DDR3 SDRAM Clocking in Arria II GX Devices (Part 1 of 2)

Clock Name (1)	Postscale Counter	Phase (Degrees)	Clock Rate	Clock Network Type	Notes
phy_clk_1x and aux_half_rate_clk	C0	0°	Half-Rate	Global	The only clocks parameterizable for the ALTMEMPHY megafunction. These clocks also feed into a divider circuit to provide the PLL <code>scan_clk</code> signal (for reconfiguration) that must be lower than 100 MHz.
mem_clk_2x and aux_full_rate_clk	C1	0°	Full-Rate	Global	This clock is for clocking DQS and as a reference clock for the memory devices.
mem_clk_1x	C2	0°	Half-Rate	Global	This clock is for clocking DQS and as a reference clock for the memory devices.
write_clk_2x	C3	-90°	Full-Rate	Global	This clock is for clocking the data out of the DDR I/O (DDIO) pins in advance of the DQS strobe (or equivalent). As a result, its phase leads that of the <code>mem_clk_2x</code> by 90°.

Table 5-1. DDR3 SDRAM Clocking in Arria II GX Devices (Part 2 of 2)

Clock Name ⁽¹⁾	Postscale Counter	Phase (Degrees)	Clock Rate	Clock Network Type	Notes
ac_clk_2x	C3	-90°	Full-Rate	Global	Address and command clock. The ac_clk_2x clock is derived from either mem_clk_2x (when you choose 0° or 180° phase shift) or write_clk_2x (when you choose 90° or 270° phase shift). Refer to “Address and Command Datapath” on page 5-11 for illustrations of the address and command clock relationship with the mem_clk_2x or write_clk_2x signals.
cs_n_clk_2x	C3	-90°	Full-Rate	Global	Memory chip-select clock. The cs_n_clk_2x clock is derived from ac_clk_2x.
resync_clk_2x	C4	Calibrated	Full-Rate	Global	Clocks the resynchronization registers after the capture registers. Its phase is adjusted to the center of the data valid window across all the DQS-clocked DDIO groups.
measure_clk_2x	C5	Calibrated	Full-Rate	Global	This clock is for VT tracking. This free-running clock measures relative phase shifts between the internal clock(s) and those being fed back through a mimic path. As a result, the ALTMEMPHY megafunction can track VT effects on the FPGA and compensate for the effects.

Note to Table 5-1:

(1) The _1x clock represents a frequency that is half of the memory clock frequency; the _2x clock represents the memory clock frequency.

Table 5-2 shows the PLL outputs and their usage for Stratix III and Stratix IV devices.

Table 5-2. DDR3 SDRAM Clocking Stratix IV and Stratix III Devices (Part 1 of 2)

Clock Name (1)	Postscale Counter	Phase (Degrees)	Clock Rate	Clock Network Type	Notes
phy_clk_1x and aux_half_rate_clk	C0	-40° (with leveling) 30° (without leveling)	Half-Rate	Global	The only clock parameterizable for the ALTMEMPHY megafunction. With phy_clk_1x the sequencer generates another sc_clk_dp clock with this clock that programs the scan chains of the I/O elements. For more information on changing the clock network type, refer to the <i>ALTMEMPHY Design Tutorials</i> section in volume 6 of the <i>External Memory Interface Handbook</i> .
mem_clk_2x	C1	0	Full-Rate	Special	Generates mem_clk that provides the reference clock for the DLL. A dedicated routing resource exists from the PLL to the DLL, which you select with the regional routing resource for the mem_clk using the following attribute in the HDL: (-name global_signal dual_regional_clock; -to dll~DFFIN -name global_signal off). If you use an external DLL, apply this attribute similarly to the external DLL.
aux_full_rate_clk	C2	0° (with leveling) 60° (without leveling)	Full-Rate	None	A copy of mem_clk_2x that you can use in other parts of your design.
write_clk_2x	C3	0° (with leveling) -90° (without leveling)	Full-Rate	Regional	This clock feeds the write leveling delay chains that generate the DQ, DM, DQS, and mem_clk signals.
resync_clk_2x	C4	Calibrated	Full-Rate	Regional	This clock feeds the I/O clock divider that then reads the data out of the DDIO pins. Its phase is adjusted in the calibration process. The design uses an inverted version of this clock for postamble clocking.
measure_clk_1x	C5	Calibrated	Half-Rate	Regional (2)	This clock is for VT tracking. This free-running clock measures relative phase shifts between the internal clock(s) and those being fed back through a mimic path. As a result, you can track VT effects on the FPGA and compensate for the effects.

Table 5-2. DDR3 SDRAM Clocking Stratix IV and Stratix III Devices (Part 2 of 2)

Clock Name (1)	Postscale Counter	Phase (Degrees)	Clock Rate	Clock Network Type	Notes
ac_clk_1x	C6	Set in the GUI	Half-Rate	Regional	Address and command clock.

Notes to Table 5-2:

- (1) In full-rate designs a `_1x` clock may run at full-rate clock rate.
- (2) This clock should be of the same clock network clock as the `resync_clk_1x` clock.

The phase-shift inputs on the PLL perform the PLL reconfiguration. The PLL reconfiguration megafunction is not required.

Reset Management

Figure 5-8 and Figure 5-9 show the main features of the reset management block for the DDR3 SDRAM PHY. You can use the `pll_ref_clk` input to feed the optional `reset_request_n` edge detect and reset counter module. However, this requires the `pll_ref_clk` signal to use a global clock network resource.

There is a unique reset metastability protection circuit for the clock divider circuit because the `phy_clk` domain reset metastability protection registers have fan-in from the `soft_reset_n` input so these registers cannot be used.

Figure 5-7. ALTMEMPHY Reset Management Block for Arria II GX Devices

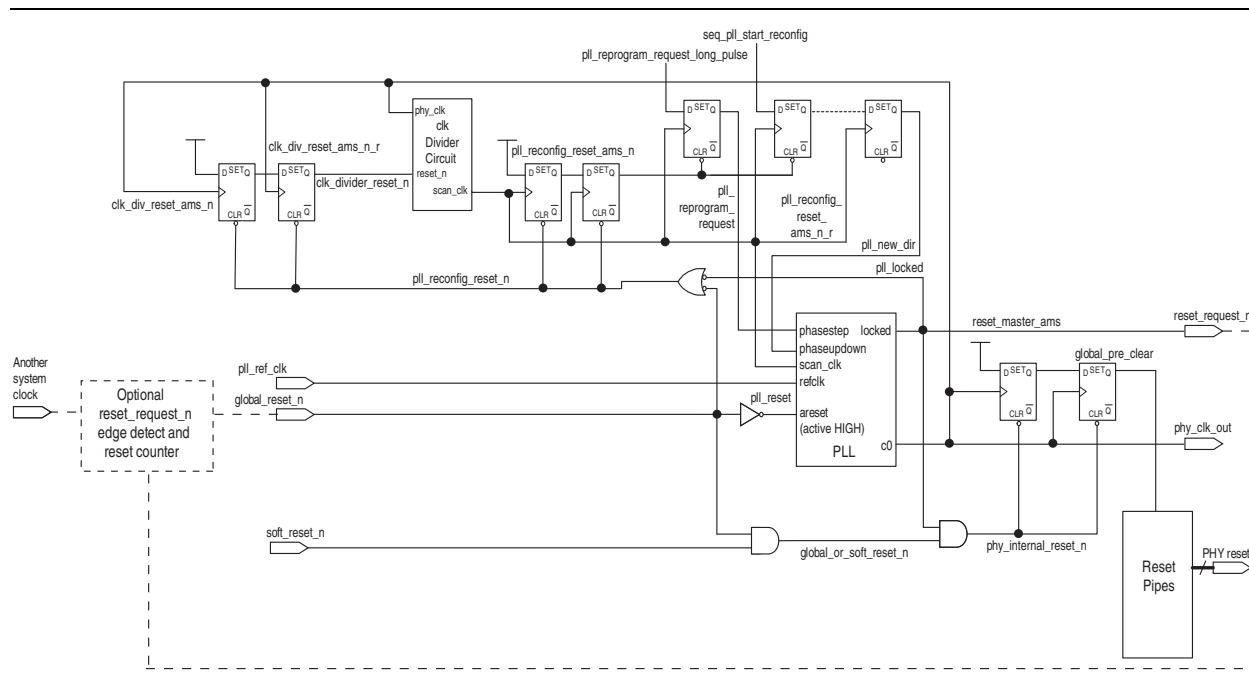
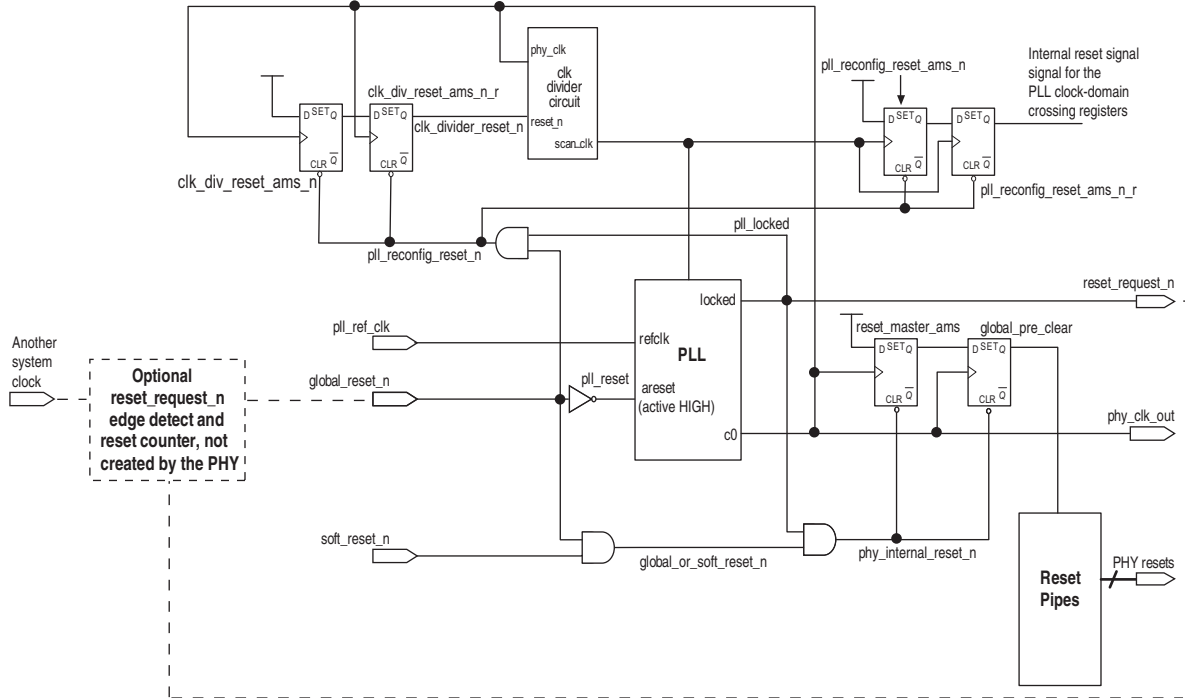


Figure 5-8. ALTMEMPHY Reset Management Block for Stratix IV and Stratix III Devices



Read Datapath

This topic discusses the read datapath.

Arria II GX Devices

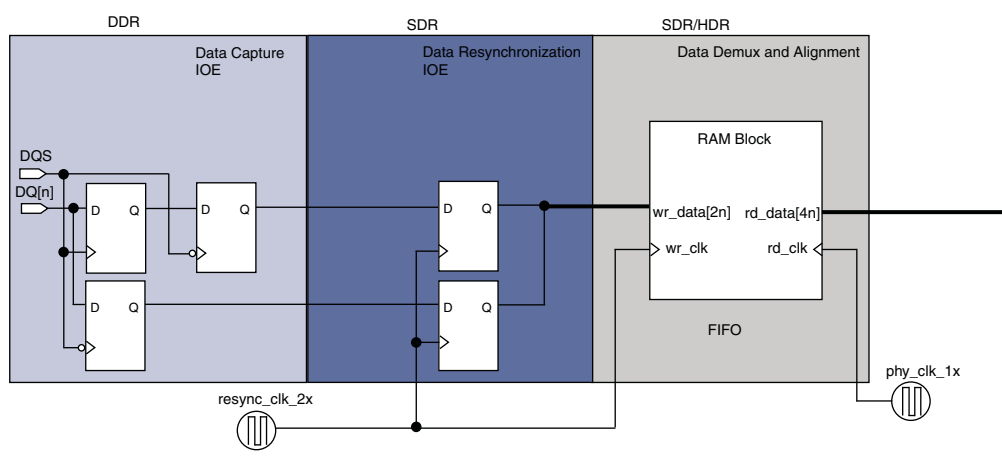
The read datapath logic captures data sent by the memory device and subsequently aligns the data back to the system clock domain. The read datapath for DDR3 SDRAM consists of the following three main blocks:

- Data capture
- Data resynchronization
- Data demultiplexing and alignment

As the DQS/DQSn signal is not continuous, the PHY also has postamble protection logic to ensure that any glitches on the DQS input signals at the end of the read postamble time do not cause erroneous data to be captured as a result of postamble glitches.

Figure 5-9 shows the order of the functions performed by the read datapath and the frequency at which the read data is handled.

Figure 5-9. DDR3 SDRAM Read Datapath in Arria II GX Devices



Data Capture and Resynchronization

The data capture and resynchronization registers for Arria II GX devices are implemented in the I/O element (IOE) to achieve maximum performance. Data capture and resynchronization is the process of capturing the read data (DQ) with the DQS/DQSn strobes and resynchronizing the captured data to an internal free-running full-rate clock supplied by the enhanced PLL. The resynchronization clock is an intermediate clock whose phase shift is determined during the calibration stage. The captured data (`rdata_p_captured` and `rdata_n_captured`) is synchronized to the resynchronization clock (`resync_clk_2x`), refer to Figure 5-9. For Arria II GX devices, the ALTMEMPHY instances an ALTDQ_DQS megafunction that instantiates the required IOEs for all the DQ and DQS pins.

Data Demultiplexing

Data demultiplexing is the process of changing the SDR data into HDR data. Data demultiplexing is required to bring the frequency of the resynchronized data down to the frequency of the system clock, so that data from the external memory device can ultimately be brought into the FPGA controller clock domain. Before data capture, the data is DDR and n -bit wide. After data capture, the data is SDR and $2n$ -bit wide. After data demuxing, the data is HDR of width $4n$ -bits wide. The system clock frequency is half the frequency of the memory clock. Demultiplexing is achieved using a dual-port memory with a $2n$ -bit wide write-port operating on the resynchronization clock (SDR) and a $4n$ -bit wide read-port operating on the PHY clock (HDR). The basic principle of operation is that data is written to the memory at the SDR rate and read from the memory at the HDR rate while incrementing the read- and write-address pointers. As the SDR and HDR clocks are generated, the read and write pointers are continuously incremented by the same PLL, and the $4n$ -bit wide read data follows the $2n$ -bit wide write data with a constant latency

Read Data Alignment

Data alignment is the process controlled by the sequencer to ensure the correct captured read data is present in the same half-rate clock cycle at the output of the read data DPRAM. Data alignment is implemented using memory blocks in the core of devices.

Postamble Protection

A dedicated postamble register controls the gating of the shifted DQS signal that clocks the DQ input registers at the end of a read operation. Any glitches on the DQS input signals at the end of the read postamble time do not cause erroneous data to be captured as a result of postamble glitches. The postamble path is also calibrated to determine the correct clock cycle, clock phase shift, and delay chain settings.

Stratix III and Stratix IV Devices

The DDR3 SDRAM controller asserts `ctl_doing_rd` to indicate that a read command is requested. The `ctl_doing_rd` signal is then used for the following purposes:

- Control of the postamble circuit
- Generation of `ctl_rdata_valid` from one bit to two bits
- Dynamic OCT control timing

The DDR3 SDRAM ALTMEMPHY then asserts the `ctl_rdata_valid` signal to indicate that the data on the read data bus is valid. The `ctl_rdata_valid` signal is two bits wide to allow controllers to issue reads and writes that are aligned to either the half-cycle of the half-rate clock.

When calibration is over, the read latency of the PHY (the `ctl_rlat` signal) is sent back to the controller to indicate how long it takes in `ctl_clk` clock cycles from assertion of the `ctl_doing_read` signal to the valid read data returning on the `ctl_rdata` bus. The `ctl_rlat` signal is only valid when calibration has successfully completed and never changes values during normal user mode operation.

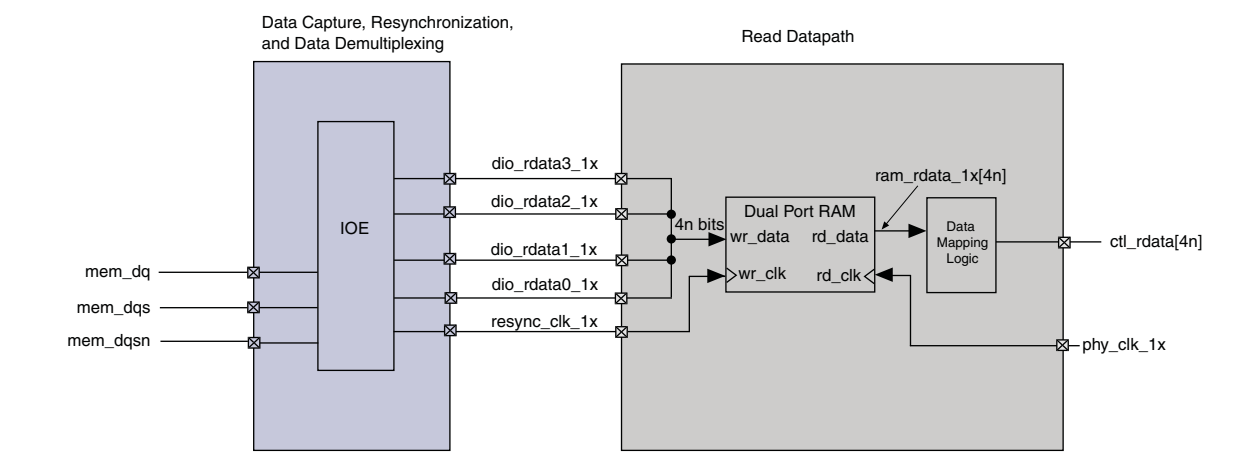
The read datapath for DDR3 SDRAM consists of two main blocks:

- Read data capture, resynchronization, and demultiplexing (in the `dp_io_siii` module)
- Read data alignment logic (in the `read_dp` module) to transfer data from the `resync_clk_2x` (half-rate resynchronization) clock domain to the `phy_clk` clock domain.

As the DQS/DQSn signal is not continuous, the PHY also has postamble protection logic to ensure that any glitches on the DQS input signals at the end of the read postamble time do not cause erroneous data to be captured as a result of postamble glitches.

Figure 5-10 shows the order of the functions performed by the read datapath and the frequency at which the read data is handled.

Figure 5-10. DDR3 SDRAM Data Capture and Read Data Mapping in Stratix IV and Stratix III Devices



Data Capture, Resynchronization, and Demultiplexing

The IOE in Stratix III and Stratix IV devices performs the following tasks during read operation:

- Captures the data
- Resynchronizes the captured data from the DQS domain to the resynchronization clock (`resync_clk_1x`) domain
- Converts the resynchronized data into HDR data

This operation is performed by feeding the resynchronized data into the HDR conversion block within the IOE, which is clocked by the half-rate resynchronization clock (`resync_clk_1x`). The `resync_clk_1x` signal is generated from the I/O clock divider module, based on the `resync_clk_2x` signal from the PLL.

Read Data Storage Logic

The read block performs the following two tasks:

- Transfers the captured read data (`rd_data[n]_1x`) from the half-rate resynchronization clock (`resync_clk_1x`) domain to the half-rate system clock (`phy_clk_1x`) domain using DPRAM. Resynchronized data from the DPRAM is shown as `ram_data_1x`.
- Reorders the resynchronized data (`ram_rdata_1x`) into `ctl1_mem_rdata`, to be presented in the user clock domain in the same clock cycle.

Postamble Protection

A dedicated postamble register controls the gating of the shifted DQS signal that clocks the DQ input registers at the end of a read operation. This ensures that any glitches on the DQS input signals at the end of the read postamble time do not cause erroneous data to be captured as a result of postamble glitches.

The postamble path is also calibrated to determine the correct clock cycle, clock phase shift, and delay chain settings. You can see the process in simulation if you choose **Full calibration** (long simulation time) mode in the MegaWizard Plug-In Manager.

Write Datapath

This topic discusses the write datapath.

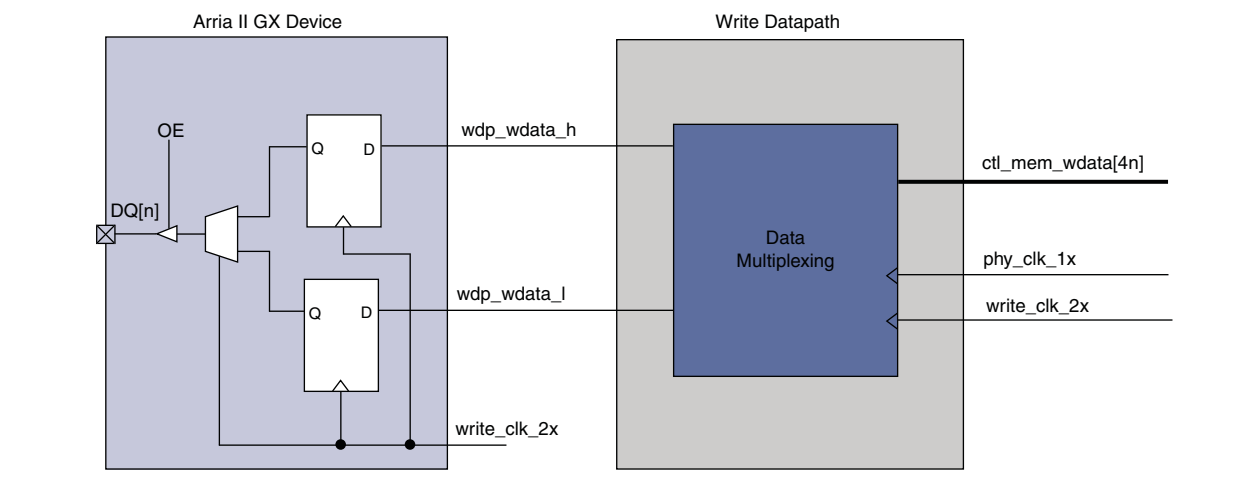
Arria II GX Devices

The write datapath logic efficiently transfers data from the HDR memory controller to DDR3 SDRAM. The write datapath logic consists of:

- DQ and DQ output-enable logic
- DQS/DQSn and DQS/DQSn output-enable logic
- DM logic

The memory controller interface outputs $4n$ -bit wide data ($ctl_wdata[4n]$) at half-rate frequency. Figure 5-4 shows that the HDR write data ($ctl_wdata[4n]$) is clocked by the half-rate clock phy_clk_1x (ctl_clk) and is converted into SDR, which is represented by wdp_wdata_h and wdp_wdata_l and clocked by the full-rate clock $write_clk_2x$. The DQ IOEs convert $2n$ SDR bits to n -DDR bits.

Figure 5–11. DDR3 SDRAM Write Datapath in Arria II GX Devices

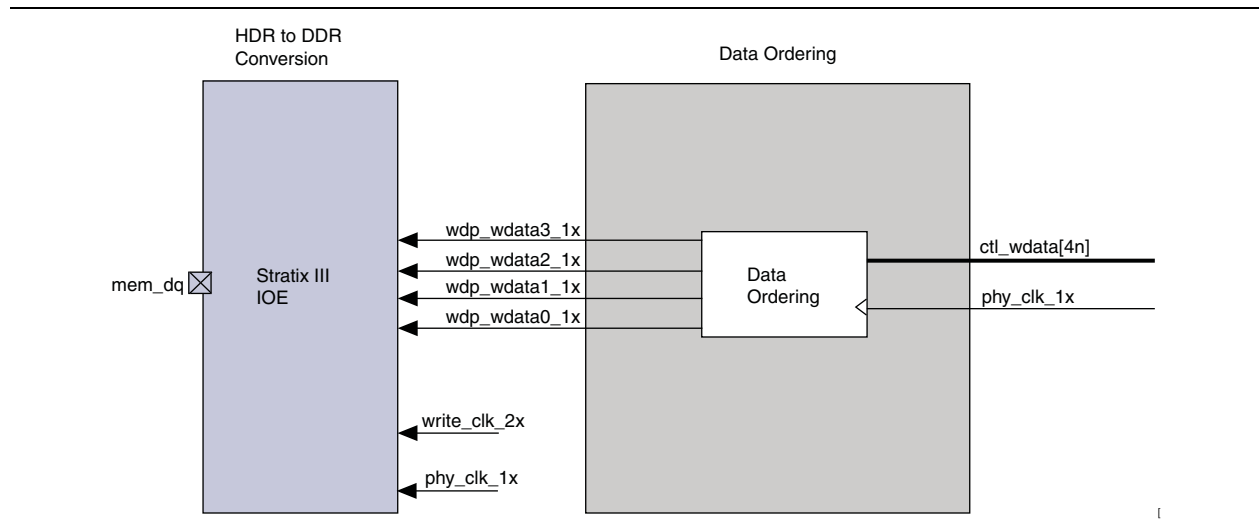


Stratix III and Stratix IV Devices

The memory controller interface outputs four n -bit wide data (ctl_wdata) at phy_clk_1x frequency. The write data is clocked by the system clock phy_clk_1x at half-data rate (HDR) and reordered into HDR of width four with n -bits each, represented in Figure 5–12 by wdp_wdata3_1x , wdp_wdata2_1x , wdp_wdata1_1x , and wdp_wdata0_1x .

Figure 5-12 shows the reordered or the reordered-and-delayed HDR data is then converted to DDR data within the IOE element using both the half-rate and full-rate clocks.

Figure 5-12. DDR3 SDRAM Write Datapath in Stratix IV and Stratix III Devices

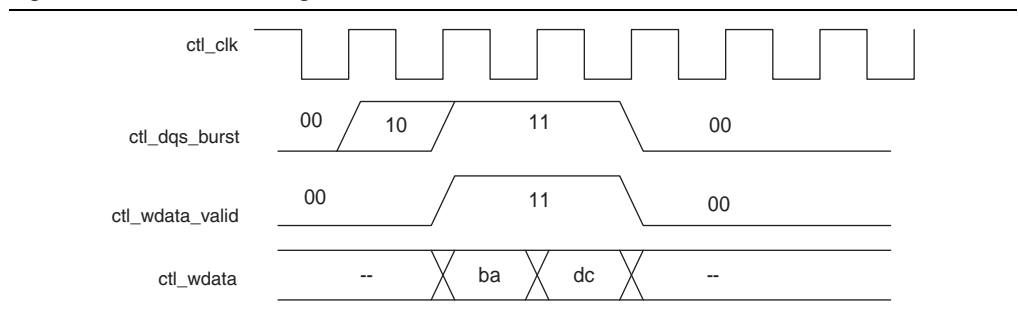


The write datapath DDIO registers are clocked by the `phy_clk_1x` clock. The `write_clk_2x` signal then clocks the alignment registers.

For more information about the I/O structure, refer to the *External Memory Interface* chapter in the respective device family handbook.

Figure 5-13 shows how the write data, `ctl_wdata` signals should be aligned from the controller during a (half rate, normally aligned) write operation. The PHY then issues the write data as ABCD where a is the first data to be written to the memory. (ABCD represent two beats of data each.) The `ctl_wdata_valid` signal in Figure 5-13 shows the output enable for the DQ and DM pins.


Figure 5-13. Write Data Alignment from the DDR3 SDRAM Controller



ALTMEMPHY Signals

This section describes the ALMEMPHY megafunction signals for DDR3 SDRAM variants.

Table 5-3 through Table 5-5 show the signals.

 Signals with the prefix `mem_` connect the PHY with the memory device; ports with the prefix `ctl_` connect the PHY with the controller.

The signal lists include the following signal groups:

- I/O interface to the SDRAM devices
- Clocks and resets
- External DLL signals
- User-mode calibration OCT control
- Write data interface
- Read data interface
- Address and command interface
- Calibration control and status interface
- Debug interface

Table 5-3. Interface to the DDR3 SDRAM Devices (Note 1)

Signal Name	Type	Width (2)	Description
<code>mem_addr</code>	Output	<code>MEM_IF_ROWADDR_WIDTH</code>	The memory row and column address bus.
<code>mem_ba</code>	Output	<code>MEM_IF_BANKADDR_WIDTH</code>	The memory bank address bus.
<code>mem_cas_n</code>	Output	1	The memory column address strobe.
<code>mem_cke</code>	Output	<code>MEM_IF_CS_WIDTH</code>	The memory clock enable.
<code>mem_clk</code>	Bidirectional	<code>MEM_IF_CLK_PAIR_COUNT</code>	The memory clock, positive edge clock. (3)
<code>mem_clk_n</code>	Bidirectional	<code>MEM_IF_CLK_PAIR_COUNT</code>	The memory clock, negative edge clock.
<code>mem_cs_n</code>	Output	<code>MEM_IF_CS_WIDTH</code>	The memory chip select signal.
<code>mem_dm</code>	Output	<code>MEM_IF_DM_WIDTH</code>	The optional memory DM bus.
<code>mem_dq</code>	Bidirectional	<code>MEM_IF_DWIDTH</code>	The memory bidirectional data bus.
<code>mem_dqs</code>	Bidirectional	<code>MEM_IF_DWIDTH/</code> <code>MEM_IF_DQ_PER_DQS</code>	The memory bidirectional data strobe bus.
<code>mem_dqs_n</code>	Bidirectional	<code>MEM_IF_DWIDTH/</code> <code>MEM_IF_DQ_PER_DQS</code>	The memory bidirectional data strobe bus.
<code>mem_odt</code>	Output	<code>MEM_IF_CS_WIDTH</code>	The memory on-die termination control signal.
<code>mem_ras_n</code>	Output	1	The memory row address strobe.
<code>mem_reset_n</code>	Output	1	The memory reset signal. This signal is derived from the PHY's internal reset signal, which is generated by gating the global reset, soft reset, and the PLL locked signal.
<code>mem_we_n</code>	Output	1	The memory write enable signal.
<code>mem_ac_parity (4)</code>	Output	1	The address or command parity signal generated by the PHY and sent to the DIMM.
<code>parity_error_n (4)</code>	Output	1	The active-low signal that is asserted when a parity error occurs and stays asserted until the PHY is reset.

Table 5-3. Interface to the DDR3 SDRAM Devices (Note 1)

Signal Name	Type	Width (2)	Description
mem_err_out_n (4)	Input	1	The signal sent from the DIMM to the PHY to indicate that a parity error has occurred for a particular cycle.

Notes to Table 5-3:

- (1) Connected to I/O pads.
- (2) Refer to Table 5-6 for parameter description.
- (3) Output is for memory device, and input path is fed back to ALTMEMPHY megafunction for VT tracking.
- (4) This signal is for Registered DIMMs only.

Table 5-4. AFI Signals (Part 1 of 3)

Signal Name	Type	Width (1)	Description
Clocks and Resets			
pll_ref_clk	Input	1	The reference clock input to the PHY PLL.
global_reset_n	Input	1	Active-low global reset for PLL and all logic in the PHY. A level set reset signal, which causes a complete reset of the whole system. The PLL may maintain some state information.
soft_reset_n	Input	1	Edge detect reset input intended for SOPC Builder use or to be controlled by other system reset logic. Causes a complete reset of PHY, but not the PLL used in the PHY.
reset_request_n	Output	1	Directly connected to the locked output of the PLL and is intended for optional use either by automated tools such as SOPC Builder or could be manually ANDed with any other system-level signals and combined with any edge detect logic as required and then fed back to the global_reset_n input. Reset request output that indicates when the PLL outputs are not locked. Use this as a reset request input to any system-level reset controller you may have. This signal is always low while the PLL is locking (but not locked), and so any reset logic using it is advised to detect a reset request on a falling-edge rather than by level detection.
ctl_clk	Output	1	Half-rate clock supplied to controller and system logic. The same signal as the non-AFI phy_clk.
ctl_reset_n	Output	1	Reset output on ctl_clk clock domain.
Other Signals			
aux_half_rate_clk	Output	1	In half-rate designs, a copy of the phy_clk_1x signal that you can use in other parts of your design, same as phy_clk port.
aux_full_rate_clk	Output	1	In full-rate designs, a copy of the mem_clk_2x signal that you can use in other parts of your design.

Table 5-4. AFI Signals (Part 2 of 3)

Signal Name	Type	Width (1)	Description
aux_scan_clk	Output	1	Low frequency scan clock supplied primarily to clock any user logic that interfaces to the PLL and DLL reconfiguration interfaces.
aux_scan_clk_reset_n	Output	1	This reset output asynchronously asserts (drives low) when global_reset_n is asserted and de-assert (drives high) synchronous to aux_scan_clk when global_reset_n is de-asserted. It allows you to reset any external circuitry clocked by aux_scan_clk.
Write Data Interface			
ctl_dqs_burst	Input	$\text{MEM_IF_DQS_WIDTH} \times \text{DWIDTH_RATIO} / 2$	When asserted, mem_dqs is driven. The ctl_dqs_burst signal must be asserted before the ctl_wdata_valid signal and must be driven for the correct duration to generate a correctly timed mem_dqs signal.
ctl_wdata_valid	Input	$\text{MEM_IF_DQS_WIDTH} \times \text{DWIDTH_RATIO} / 2$	Write data valid. Generates ctl_wdata and ctl_dm output enables.
ctl_wdata	Input	$\text{MEM_IF_DWIDTH} \times \text{DWIDTH_RATIO}$	Write data input from the controller to the PHY to generate mem_dq.
ctl_dm	Input	$\text{MEM_IF_DM_WIDTH} \times \text{DWIDTH_RATIO}$	DM input from the controller to the PHY.
ctl_wlat	Output	5	Required write latency between address/command and write data that is issued to ALTMEMPHY controller local interface. This signal is only valid when the ALTMEMPHY sequencer successfully completes calibration, and does not change at any point during normal operation. The legal range of values for this signal is 0 to 31; and the typical values are between 0 and ten, 0 mostly for low CAS latency DDR memory types.
Read Data Interface			
ctl_doing_rd	Input	$\text{MEM_IF_DQS_WIDTH} \times \text{DWIDTH_RATIO} / 2$	Doing read input. Indicates that the DDR3 SDRAM controller is currently performing a read operation. The controller generates ctl_doing_rd to the ALTMEMPHY megafunction. The ctl_doing_rd signal is asserted for one phy_clk cycle for every read command it issues. If there are two read commands, ctl_doing_rd is asserted for two phy_clk cycles. The ctl_doing_rd signal also enables the capture registers and generates the ctl_mem_rdata_valid signal. The ctl_doing_rd signal should be issued at the same time the read command is sent to the ALTMEMPHY megafunction.
ctl_rdata	Output	$\text{DWIDTH_RATIO} \times \text{MEM_IF_DWIDTH}$	Read data from the PHY to the controller.

Table 5-4. AFI Signals (Part 3 of 3)

Signal Name	Type	Width (1)	Description
ctl_rdata_valid	Output	DWIDTH_RATIO/2	Read data valid indicating valid read data on <code>ctl_rdata</code> . This signal is two-bits wide (as only half-rate or DWIDTH_RATIO = 4 is supported) to allow controllers to issue reads and writes that are aligned to either the half-cycle of the half-rate clock.
ctl_rlat	Output	READ_LAT_WIDTH	Contains the number of clock cycles between the assertion of <code>ctl_doing_rd</code> and the return of valid read data (<code>ctl_rdata</code>). This signal is unused by the Altera high-performance controllers.
Address and Command Interface			
ctl_addr	Input	MEM_IF_ROWADDR_WIDTH × DWIDTH_RATIO / 2	Row address from the controller.
ctl_ba	Input	MEM_IF_BANKADDR_WIDTH × DWIDTH_RATIO / 2	Bank address from the controller.
ctl_cke	Input	MEM_IF_CS_WIDTH × DWIDTH_RATIO / 2	Clock enable from the controller.
ctl_cs_n	Input	MEM_IF_CS_WIDTH × DWIDTH_RATIO / 2	Chip select from the controller.
ctl_odt	Input	MEM_IF_CS_WIDTH × DWIDTH_RATIO / 2	On-die-termination control from the controller.
ctl_ras_n	Input	DWIDTH_RATIO / 2	Row address strobe signal from the controller.
ctl_we_n	Input	DWIDTH_RATIO / 2	Write enable.
ctl_cas_n	Input	DWIDTH_RATIO / 2	Column address strobe signal from the controller.
ctl_rst_n	Input	DWIDTH_RATIO / 2	Reset from the controller.
Calibration Control and Status Interface			
ctl_mem_clk_disable	Input	MEM_IF_CLK_PAIR_COUNT	When asserted, <code>mem_clk</code> and <code>mem_clk_n</code> are disabled.
ctl_cal_success	Output	1	A 1 indicates that calibration was successful.
ctl_cal_fail	Output	1	A 1 indicates that calibration has failed.
ctl_cal_req	Input	1	When asserted, a new calibration sequence is started. Currently not supported.
ctl_cal_byte_lane_sel_n	Input	MEM_IF_DQS_WIDTH × MEM_CS_WIDTH	Indicates which DQS groups should be calibrated. Not supported.

Note to Table 5-3:

(1) Refer to Table 5-6 for parameter descriptions.

Table 5-5. Other Interface Signals (Part 1 of 4)

Signal Name	Type	Width	Description
External DLL Signals			
dqs_delay_ctrl_export	Output	DQS_DELAY_CTL_WIDTH	Allows sharing DLL in this ALTMEMPHY instance with another ALTMEMPHY instance. Connect the <code>dqs_delay_ctrl_export</code> port on the ALTMEMPHY instance with a DLL to the <code>dqs_delay_ctrl_import</code> port on the other ALTMEMPHY instance.

Table 5-5. Other Interface Signals (Part 2 of 4)

Signal Name	Type	Width	Description
dqs_delay_ctrl_import	Input	DQS_DELAY_CTL_WIDTH	Allows the use of DLL in another ALTMEMPHY instance in this ALTMEMPHY instance. Connect the dqs_delay_ctrl_export port on the ALTMEMPHY instance with a DLL to the dqs_delay_ctrl_import port on the other ALTMEMPHY instance.
dqs_offset_delay_ctrl_width	Input	DQS_DELAY_CTL_WIDTH	Connects to the DQS delay logic when dll_import_export is set to IMPORT. Only connect if you are using a DLL offset, which can otherwise be tied to zero. If you are using a DLL offset, connect this input to the offset_ctrl_out output of the dll_offset_ctrl block.
dll_reference_clk	Output	1	Reference clock to feed to an externally instantiated DLL. This clock is typically from one of the PHY PLL outputs.
User-Mode Calibration OCT Control Signals			
oct_ctl_rs_value	Input	14	OCT RS value port for use with ALT_OCT megafunction if you want to use OCT with user-mode calibration.
oct_ctl_rt_value	Input	14	OCT RT value port for use with ALT_OCT megafunction if you want to use OCT with user-mode calibration.
Debug Interface Signals (Note 1), (Note 2)			
dbg_clk	Input	1	Debug interface clock.
dbg_reset_n	Input	1	Debug interface reset.
dbg_addr	Input	DBG_A_WIDTH	Address input.
dbg_wr	Input	1	Write request.
dbg_rd	Input	1	Read request.
dbg_cs	Input	1	Chip select.
dbg_wr_data	Input	32	Debug interface write data.
dbg_rd_data	Output	32	Debug interface read data.
dbg_waitrequest	Output	1	Wait signal.
PLL Reconfiguration Signals—Stratix III and Stratix IV Devices			
pll_reconfig_enable	Input	1	This signal enables the PLL reconfiguration I/O, and is used if the user requires some custom PLL phase reconfiguration. It should otherwise be tied low.
pll_phasecounterselect	Input	4	When pll_reconfig_enable is asserted, this input is directly connected to the PLL's phasecounterselect input. Otherwise this input has no effect.
pll_phaseupdown	Input	1	When pll_reconfig_enable is asserted, this input is directly connected to the PLL's phaseupdown input. Otherwise this input has no effect.
pll_phasestep	Input	1	When pll_reconfig_enable is asserted, this input is directly connected to the PLL's phasestep input. Otherwise this input has no effect.
pll_phase_done	Output	1	Directly connected to the PLL's phase_done output.
I/O Delay Chain Signals—Stratix III, HardCopy III, and HardCopy IV Devices			

Table 5-5. Other Interface Signals (Part 3 of 4)

Signal Name	Type	Width	Description
hc_scan_enable_access	Input	1	This signal switches the control of the levelling delay chains from the sequencer to the hc_scan_ signals. It should normally be tied low.
hc_scan_enable_dq	Input	MEM_IF_DWIDTH	When hc_scan_enable_access is asserted, this bus directly connects to the ena inputs on the IO_CONFIG atoms for every DQ pin. Otherwise, this input has no effect.
hc_scan_enable_dm	Input	MEM_IF_DM_DWIDTH	When hc_scan_enable_access is asserted, this bus directly connects to the ena inputs on the IO_CONFIG atoms for every DM pin. Otherwise, this input has no effect.
hc_scan_enable_dqs	Input	MEM_IF_DQS_DWIDTH	When hc_scan_enable_access is asserted, this bus directly connects to the ena inputs on the IO_CONFIG atoms for every DQS pin. Otherwise, this input has no effect.
hc_scan_enable_dqs_config	Input	MEM_IF_DQS_CONFIG_DWIDTH	When hc_scan_enable_access is asserted, this bus directly connects to the ena inputs on the DQS_CONFIG atoms for every DQS pin. Otherwise, this input has no effect.
hc_scan_din	Input	MEM_IF_DQS_DWIDTH	When hc_scan_enable_access is asserted, this bus directly connects to the datain inputs on the IO_CONFIG and DQS_CONFIG atoms for every DQ, DM, and DQS pin. Otherwise, this input has no effect.
hc_scan_update	Input	MEM_IF_DQS_DWIDTH	When hc_scan_enable_access is asserted, this bus directly connects to the update inputs on the IO_CONFIG and DQS_CONFIG atoms for every DQ, DM, and DQS pin. Otherwise, this input has no effect.
hc_scan_ck	Input	1	When hc_scan_enable_access is asserted, this bus directly connects to the clk inputs on the IO_CONFIG and DQS_CONFIG atoms for every DQ, DM, and DQS pin. Otherwise, this input has no effect.
hc_scan_dout	Output	MEM_IF_DWIDTH	When hc_scan_enable_access is asserted, a multiplexer connects this bus to the relevant dataout outputs of the IO_CONFIG or DQS_CONFIG atoms for the signal group which is currently being selected via the hc_scan_enable_ signals. Otherwise, this input has no effect.
Calibration Interface Signals—without leveling only			
rsv_codvw_phase	Output	—	The sequencer sweeps the phase of a resynchronization clock across 360° or 720° of a memory clock cycle. Data reads from the DIMM are performed for each phase position, and a data valid window is located, which is the set of resynchronization clock phase positions where data is successfully read. The final resynchronization clock phase is set at the center of this range: the center of the data valid window or CODVW. This output is set to the current calculated value for the CODVW, and represents how many phase steps were performed by the PLL to offset the resynchronization clock from the memory clock.
rsv_codvw_size	Output	—	The final centre of data valid window size (rsv_codvw_size) is the number of phases where data was successfully read in the calculation of the resynchronization clock centre of data valid window phase (rsv_codvw_phase).

Table 5-5. Other Interface Signals (Part 4 of 4)

Signal Name	Type	Width	Description
rsu_read_latency	Output	—	The rsu_read_latency output is then set to the read latency (in phy_clk cycles) using the rsu_codvw_phase resynchronization clock phase. If calibration is unsuccessful then this signal is undefined.
rsu_no_dvw_err	Output	—	If the sequencer sweeps the resynchronization clock across every phase and does not see any valid data at any phase position, then calibration fails and this output is set to 1.
rsu_grt_one_dvw_err	Output	—	If the sequencer sweeps the resynchronization clock across every phase and sees multiple data valid windows, this is indicative of unexpected read data (random bit errors) or an incorrectly configured PLL that must be resolved. Calibration has failed and this output is set to 1.

Notes to Table 5-5:

- (1) The debug interface uses the simple Avalon-MM interface protocol.
- (2) These ports exist in the Quartus II software, even though the debug interface is for Altera's use only.

Table 5-6 shows the parameters that Table 5-3 through Table 5-5 refer to.

Table 5-6. Parameters

Parameter Name	Description
DWIDTH_RATIO	The data width ratio from the local interface to the memory interface. DWIDTH_RATIO of 2 means full rate, while DWIDTH_RATIO of 4 means half rate.
LOCAL_IF_DWIDTH	The width of the local data bus must be quadrupled for half-rate and doubled for full-rate.
MEM_IF_DWIDTH	The data width at the memory interface. MEM_IF_DWIDTH can have values that are multiples of MEM_IF_DQ_PER_DQS.
MEM_IF_DQS_WIDTH	The number of DQS pins in the interface.
MEM_IF_ROWADDR_WIDTH	The row address width of the memory device.
MEM_IF_BANKADDR_WIDTH	The bank address with the memory device.
MEM_IF_CS_WIDTH	The number of chip select pins in the interface. The sequencer only calibrates one chip select pin.
MEM_IF_DM_WIDTH	The number of mem_dm pins on the memory interface.
MEM_IF_DQ_PER_DQS	The number of mem_dq[] pins per mem_dqs pin.
MEM_IF_CLK_PAIR_COUNT	The number of mem_clk/mem_clk_n pairs in the interface.

PHY-to-Controller Interfaces

The following section describes the typical modules that are connected to the ALTMEMPHY variation and the port name prefixes each module uses. This section also describes using a custom controller. This section describes the AFI.

The AFI standardizes and simplifies the interface between controller and PHY for all Altera memory designs, thus allowing you to easily interchange your own controller code with Altera's high-performance controllers. The AFI PHY includes an administration block that configures the memory for calibration and performs necessary mode registers accesses to configure the memory as required (these calibration processes are different). Figure 5-14 shows an overview of the connections between the PHY, the controller, and the memory device.


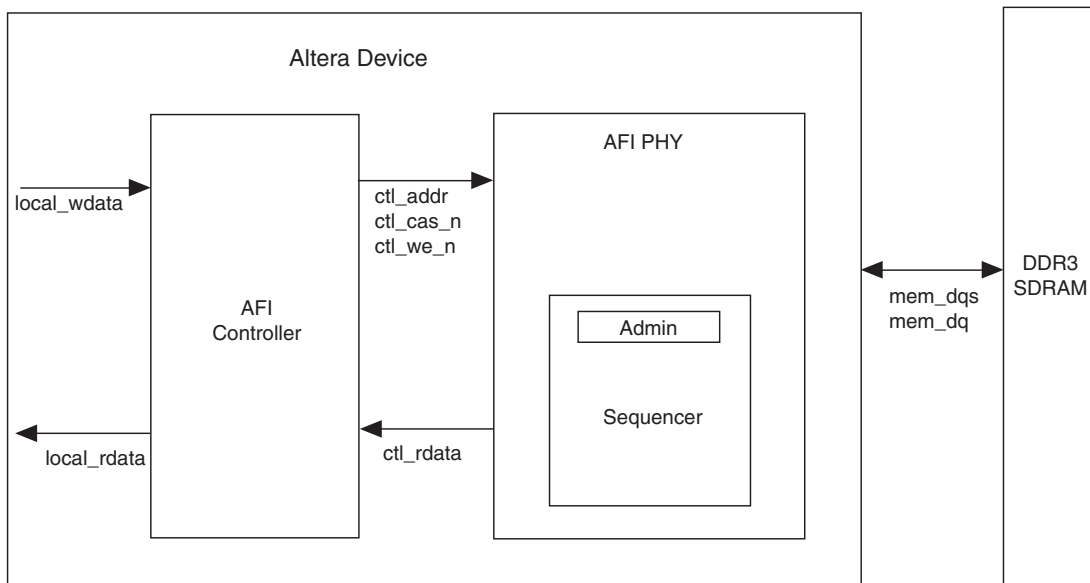
 Altera recommends that you use the AFI for new designs.

Figure 5-14. AFI PHY Connections



For half-rate designs, the address and command signals in the ALTMEMPHY megafunction are asserted for one `mem_clk` cycle (1T addressing), such that there are two input bits per address and command pin in half-rate designs. If you require a more conservative 2T addressing, drive both input bits (of the address and command signal) identically in half-rate designs.

For DDR3 SDRAM with the AFI, the read and write control signals are on a per-DQS group basis. The controller can calibrate and use a subset of the available DDR3 SDRAM devices. For example, the controller can calibrate and use two devices out of a 64- or 72-bit DIMM for better debugging mechanism.

For half-rate designs, the AFI allows the controller to issue reads and writes that are aligned to either half-cycle of the half-rate `phy_clk`, which means that the datapaths can support multiple data alignments—word-unaligned and word-aligned writes and reads. [Figure 5-15](#) and [Figure 5-16](#) display the half-rate write operation.

Figure 5-15. Half-Rate Write with Word-Unaligned Data

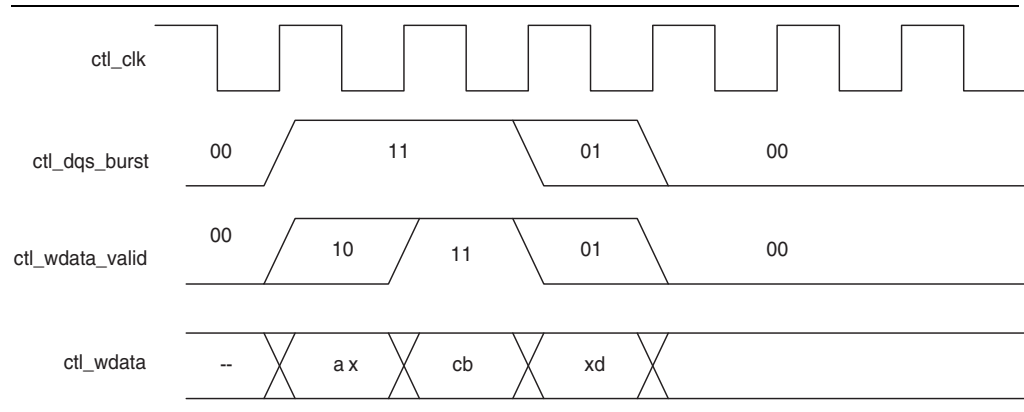
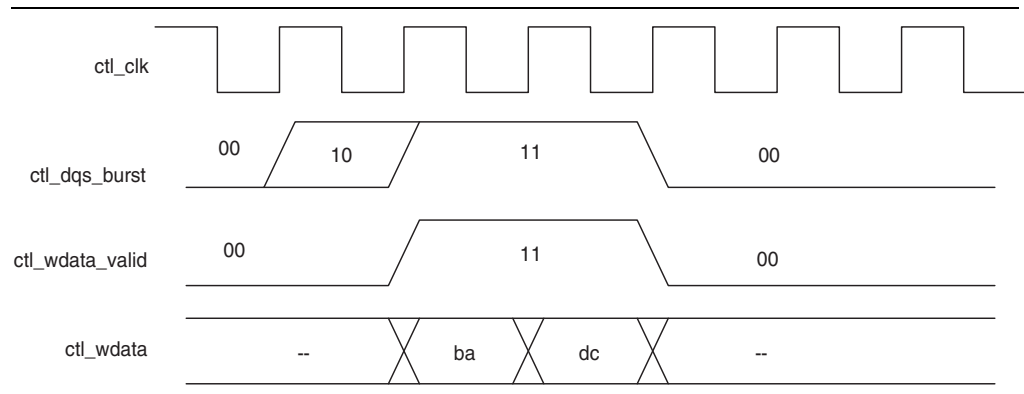


Figure 5-16. Half-Rate Write with Word-Aligned Data



After calibration process is complete, the sequencer sends the write latency in number of clock cycles to the controller.


[Figure 5-17](#) and [Figure 5-18](#) show word-aligned writes and reads. In the following read and write examples the data is written to and read from the same address. In each example, `ctl_rdata` and `ctl_wdata` are aligned with controller clock (`ctl_clk`) cycles. All the data in the bit vector is valid at once. For comparison, refer [Figure 5-19](#) and [Figure 5-20](#) that show the word-unaligned writes and reads.




The `ctl_doing_rd` is represented as a half-rate signal when passed into the PHY. Therefore, the lower half of this bit vector represents one memory clock cycle and the upper half the next memory clock cycle. [Figure 5-20 on page 5-37](#) shows separated word-unaligned reads as an example of two `ctl_doing_rd` bits are different. Therefore, for each x16 device, at least two `ctl_doing_rd` bits need to be driven, and two `ctl_rdata_valid` bits need to be interpreted.


The AFI has the following conventions:


- With the AFI, high and low signals are combined in one signal, so for a single chip select (`ctl_cs_n`) interface, `ctl_cs_n[1:0]`, where location 0 appears on the memory bus on one `mem_clk` cycle and location 1 on the next `mem_clk` cycle.

 This convention is maintained for all signals so for an 8 bit memory interface, the write data (`ctl_wdata`) signal is `ctl_wdata[31:0]`, where the first data on the DQ pins is `ctl_wdata[7:0]`, then `ctl_wdata[15:8]`, then `ctl_wdata[23:16]`, then `ctl_wdata[31:24]`.

- Word-aligned and word-unaligned reads and writes have the following definitions:
 - Word-aligned for the single chip select is active (low) in location 1 (`_1`). `ctl_cs_n[1:0] = 01` when a write occurs. This alignment is the easiest alignment to design with.
 - Word-unaligned is the opposite, so `ctl_cs_n[1:0] = 10` when a read or write occurs and the other control and data signals are distributed across consecutive `ctl_clk` cycles.

 The Altera high-performance controllers use word-aligned data only.

 The timing analysis script does not support word-unaligned reads and writes.

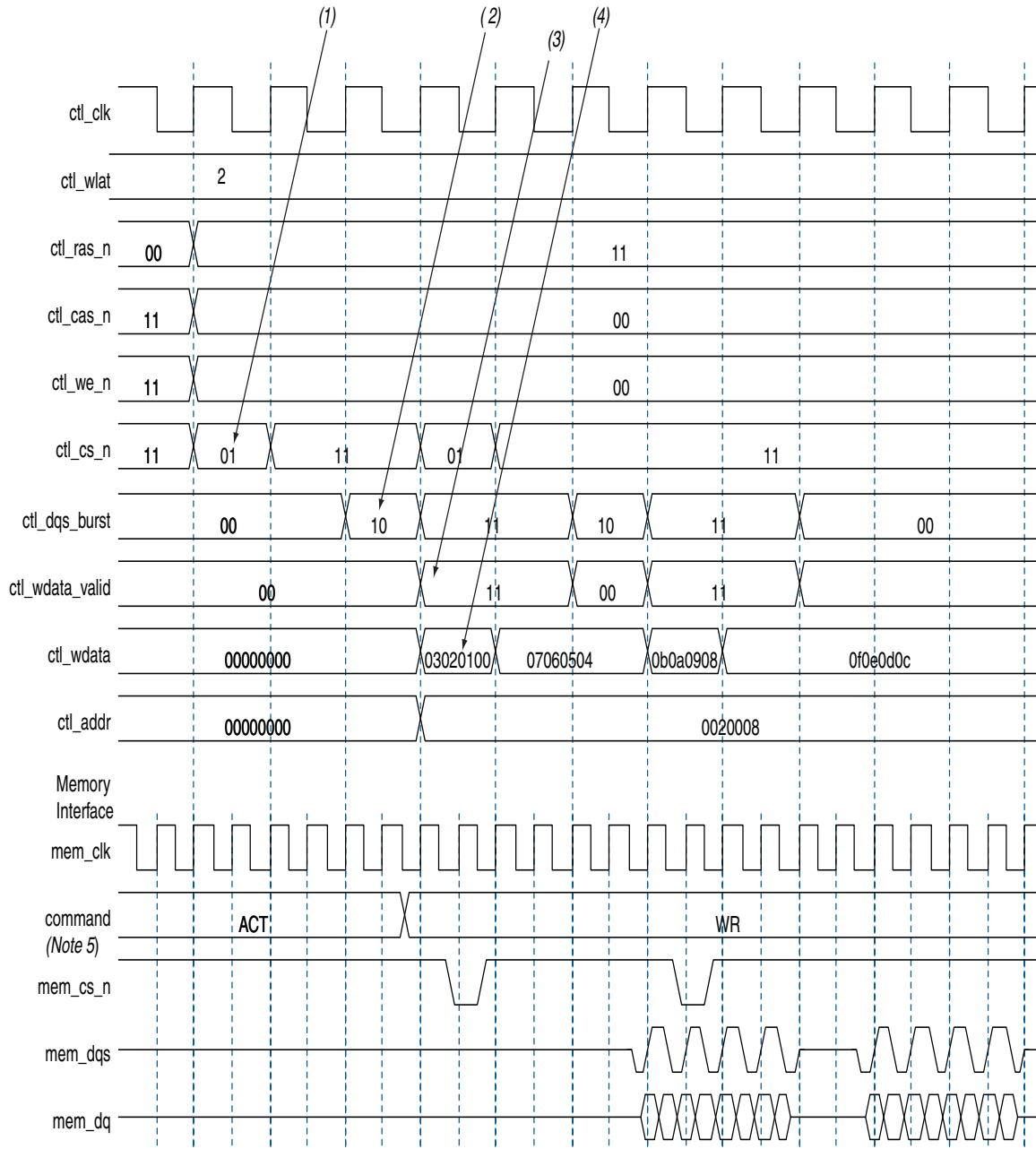
 Word-unaligned reads and writes are only supported on Stratix III and Stratix IV devices.

- Spaced reads and writes have the following definitions:
 - Spaced writes—write commands separated by a gap of one controller clock (`ctl_clk`) cycle
 - Spaced reads—read commands separated by a gap of one controller clock (`ctl_clk`) cycle

Figure 5-17 through Figure 5-20 assume the following general points:

- The burst length is four. A DDR2 SDRAM is used—the interface timing is identical for DDR3 devices.
- An 8-bit interface with one chip select.
- The data for one controller clock (`ctl_clk`) cycle represents data for two memory clock (`mem_clk`) cycles (half-rate interface).

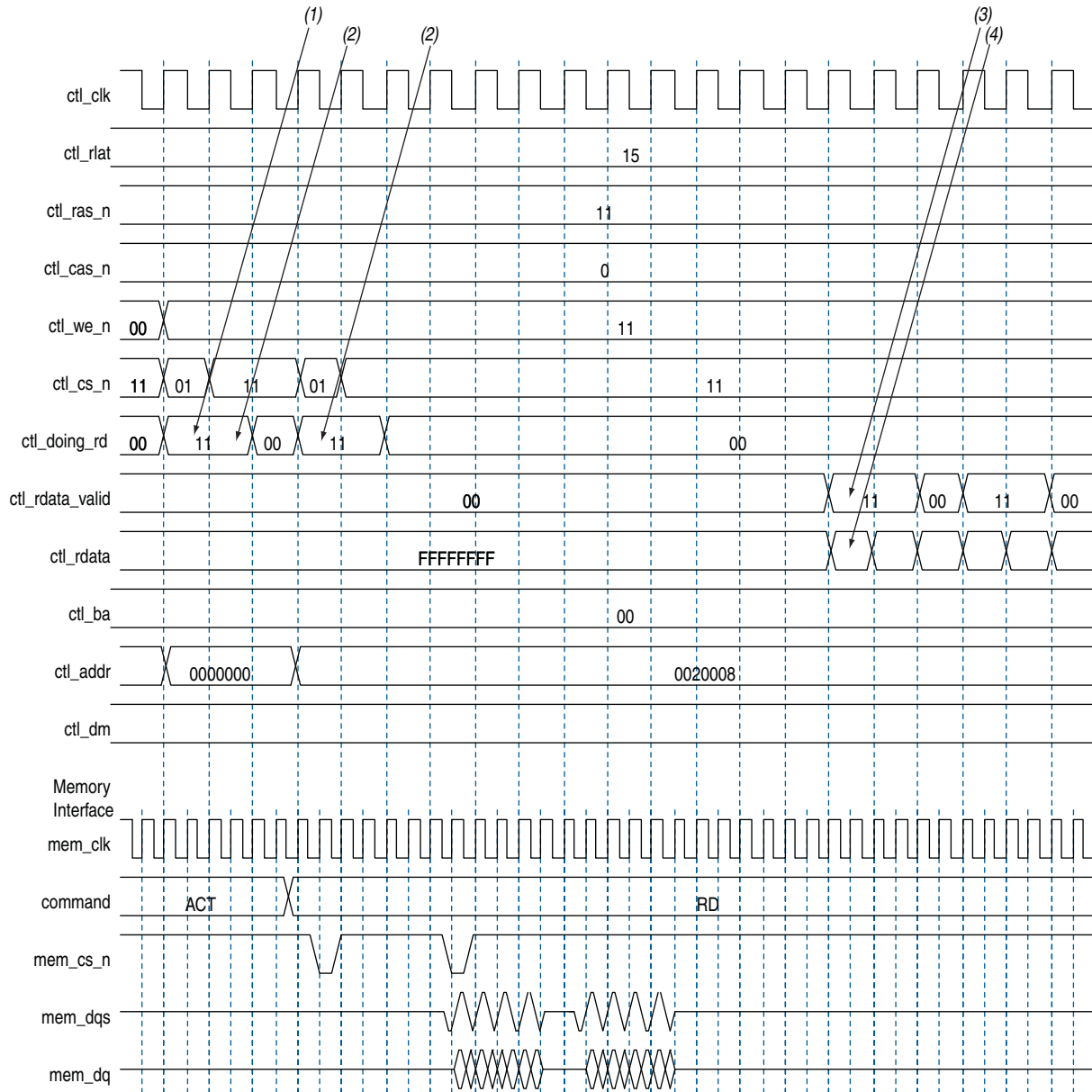
Figure 5-17. Word-Aligned Writes



Notes to Figure 5-17:

- (1) To show the even alignment of `ctl_cs_n`, expand the signal (this convention applies for all other signals).
- (2) The `ctl_dqs_burst` must go high one memory clock cycle before `ctl_wdata_valid`. Compare with the word-unaligned case.
- (3) The `ctl_wdata_valid` is asserted two `ctl_wlat` controller clock (`ctl_clk`) cycles after chip select (`ctl_cs_n`) is asserted. The `ctl_wlat` indicates the required write latency in the system. The value is determined during calibration and is dependant upon the relative delays in the address and command path and the write datapath in both the PHY and the external DDR SDRAM subsystem. The controller must drive `ctl_cs_n` and then wait `ctl_wlat` (two in this example) `ctl_clks` before driving `ctl_wdata_valid`.
- (4) Observe the ordering of write data (`ctl_wdata`). Compare this to data on the `mem_dq` signal.
- (5) In all waveforms a command record is added that combines the memory pins `ras_n`, `cas_n` and `we_n` into the current command that is issued. This command is registered by the memory when chip select (`mem_cs_n`) is low. The important commands in the presented waveforms are WR = write, ACT = activate.

Figure 5-18. Word-Aligned Reads

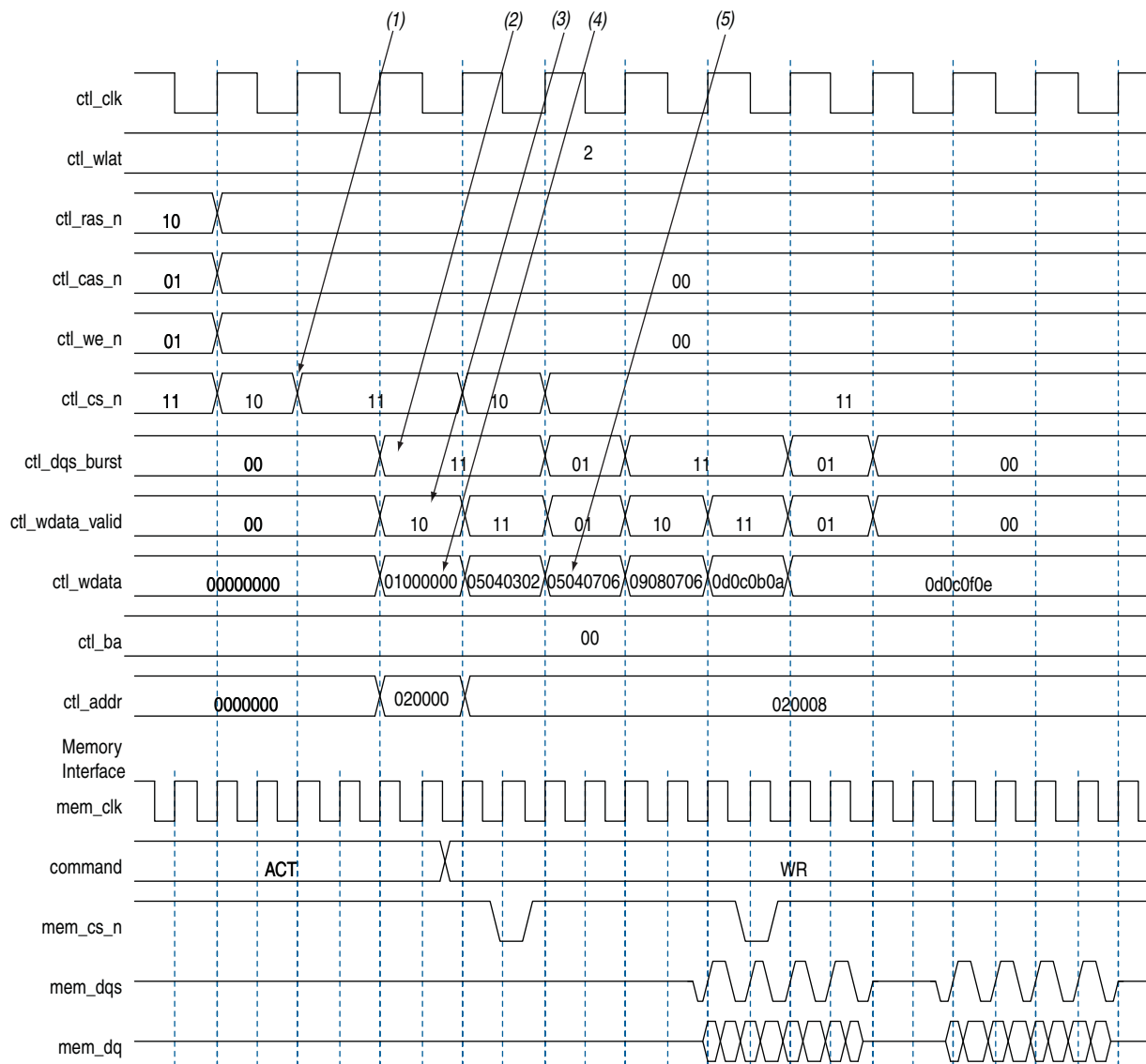


Notes to Figure 5-18:

- (1) For AFI, `ctl_doing_rd` is required to be asserted one memory clock cycle before chip select (`ctl_cs_n`) is asserted. In the half-rate `ctl_clk` domain, this requirement manifests as the controller driving 11 (as opposed to the 01) on `ctl_doing_rd`.
- (2) AFI requires that `ctl_doing_rd` is driven for the duration of the read. In this example, it is driven to 11 for two half-rate `ctl_clks`, which equates to driving to 1, for the four memory clock cycles of this four-beat burst.
- (3) The `ctl_rdata_valid` returns 15 (`ctl_rlat`) controller clock (`ctl_clk`) cycles after `ctl_doing_rd` is asserted. Returned is when the `ctl_rdata_valid` signal is observed at the output of a register within the controller. A controller can use the `ctl_rlat` value to determine when to register returned data, but this is unnecessary as the `ctl_rdata_valid` is provided for the controller to use as an enable when registering read data.
- (4) Observe the alignment of returned read data with respect to data on the bus.

Figure 5-19 and Figure 5-20 show spaced word-unaligned writes and reads.

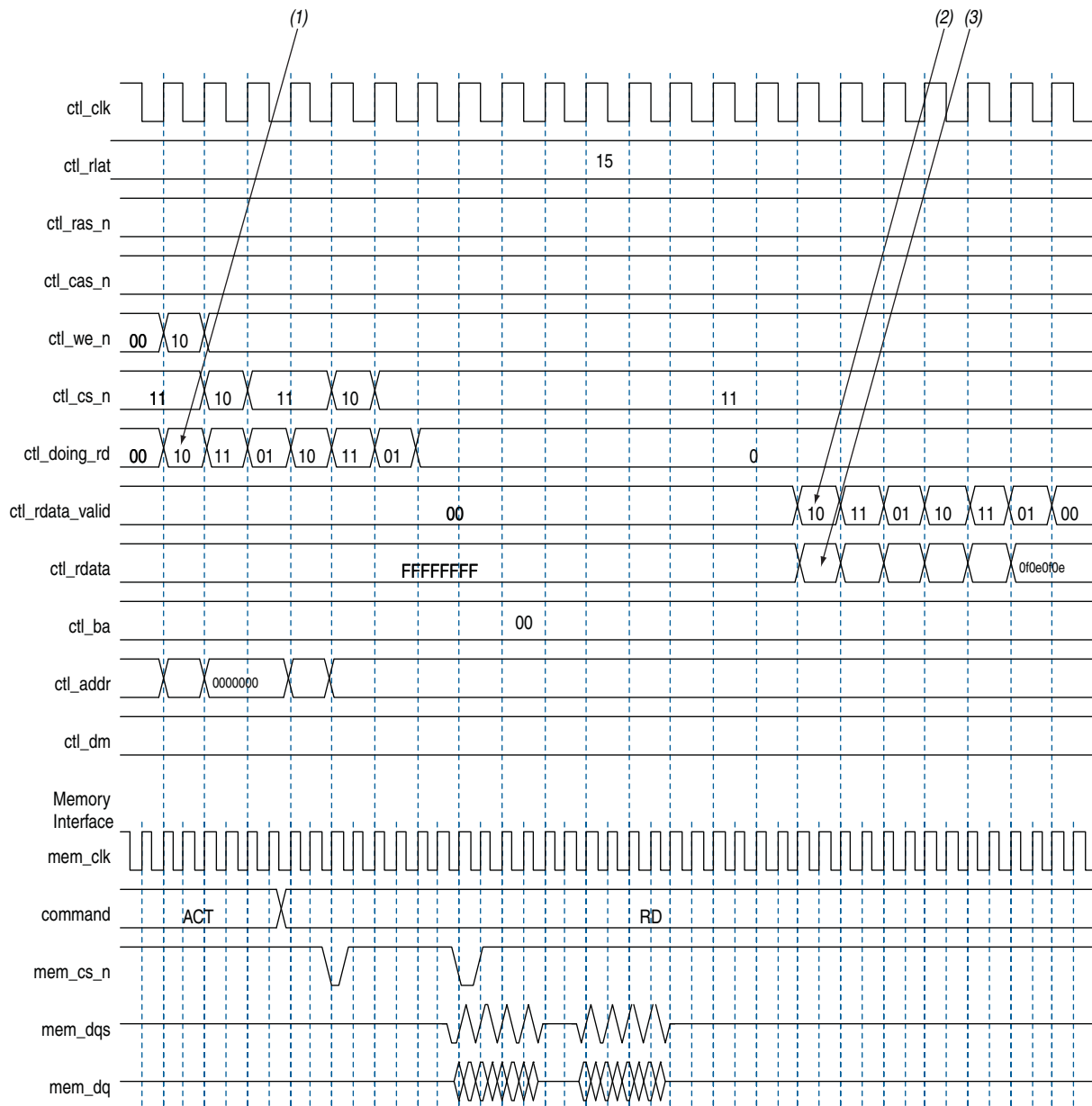
Figure 5-19. Word-Unaligned Writes



Notes to Figure 5-19:

- (1) Alternative word-unaligned chip select (`ctl_cs_n`).
- (2) As with word-aligned writes, `ctl_dqs_burst` is asserted one memory clock cycle before `ctl_wdata_valid`. You can see `ctl_dqs_burst` is 11 in the same cycle where `ctl_wdata_valid` is 10. The LSB of these two becomes the first value the signal takes in the `mem_clk` domain. You can see that `ctl_dqs_burst` has the necessary one `mem_clk` cycle lead on `ctl_wdata_valid`.
- (3) The latency between `ctl_cs_n` being asserted and `ctl_wdata_valid` going high is effectively `ctl_wlat` (in this example, two) controller clock (`ctl_clk`) cycles. This can be thought of in terms of relative memory clock (`mem_clk`) cycles, in which case the latency is four `mem_clk` cycles.
- (4) Only the upper half is valid (as the `ctl_wdata_valid` signal demonstrates, there is one `ctl_wdata_valid` bit to two 8-bit words). The write data bits go out on the bus in order, least significant byte first. So for a continuous burst of write data on the DQ pins, the most significant half of write data is used, which goes out on the bus last and is therefore contiguous with the following data. The converse is true for the end of the burst. Write data is spread across three controller clock (`ctl_clk`) cycles, but still only four memory clock (`mem_clk`) cycles. However, in relative memory clock cycles the latency is equivalent in the word-aligned and word-unaligned cases.
- (5) The 0504 here is residual from the previous clock cycle. In the same way that only the upper half of the write data is used for the first beat of the write, only the lower half of the write data is used in the last beat of the write. These upper bits can be driven to any value in this alignment.

Figure 5-20. Word-Unaligned Reads



Notes to Figure 5-20:

- (1) Similar to word-aligned reads, **ctl_doing_rd** is asserted one memory clock cycle before chip select (**ctl_cs_n**) is asserted, which for a word-unaligned read is in the previous controller clock (**ctl_clk**) cycle. In this example the **ctl_doing_rd** signal is now spread over three controller clock (**ctl_clk**) cycles, the high bits in the sequence '10','11','01','10','11','01' providing the required four memory clock cycles of assertion for **ctl_doing_rd** for the two 4-beat reads in the full-rate memory clock domain, '011110','011110'.
- (2) The return pattern of **ctl_rdata_valid** is a delayed version of **ctl_doing_rd**. Advertised read latency (**ctl_rlat**) is the number of controller clock (**ctl_clk**) cycles delay inserted between **ctl_doing_rd** and **ctl_rdata_valid**.
- (3) The read data (**ctl_rdata**) is spread over three controller clock cycles and in the pointed to vector only the upper half of the **ctl_rdata** bit vector is valid (denoted by **ctl_rdata_valid**).

Using a Custom Controller

The ALTMEMPHY megafunction can be integrated with your own controller. This section describes the interface requirement and the handshake mechanism for efficient read and write transactions.

Preliminary Steps

Perform the following steps to generate the ALTMEMPHY megafunction:

1. If you are creating a custom DDR3 SDRAM controller, generate the Altera high-performance controller targeting your chosen Altera and memory devices.
2. Compile and verify the timing. This step is optional; refer to “[Compiling and Simulating](#)” on page 4-1.
3. If targeting a DDR3 SDRAM device, simulate the high-performance controller design so you can determine how to drive the PHY signals using your own controller.
4. Integrate the top-level ALTMEMPHY design with your controller. If you started with the high-performance controller, the PHY variation name is `<controller_name>_phy.v/.vhd`. Details about integrating your controller with Altera’s ALTMEMPHY megafunction are described in the following sections.
5. Compile and simulate the whole interface to ensure that you are driving the PHY properly and that your commands are recognized by the memory device.

Design Considerations

This section discusses the important considerations for implementing your own controller with the ALTMEMPHY megafunction. This section describes the design considerations for AFI variants.



Simulating the high-performance controller is useful if you do not know how to drive the PHY signals.

Clocks and Resets

The ALTMEMPHY megafunction automatically generates a PLL instance, but you must still provide the reference clock input (`pll_ref_clk`) with a clock of the frequency that you specified in the MegaWizard Plug-In Manager. An active-low global reset input is also provided, which you can deassert asynchronously. The clock and reset management logic synchronizes this reset to the appropriate clock domains inside the ALTMEMPHY megafunction.

A clock output, half the memory clock frequency for a half-rate controller, is provided and all inputs and outputs of the ALTMEMPHY megafunction are synchronous to this clock. For AFIs, this signal is called `ctl_clk`.

There is also an active-low synchronous reset output signal provided, `ctl_reset_n`. This signal is synchronously de-asserted with respect to the `ctl_clk` or `phy_clk` clock domain and it can reset any additional user logic on that clock domain.

Calibration Process Requirements

When the global `reset_n` is released the ALTMEMPHY handles the initialization and calibration sequence automatically. The sequencer calibrates memory interfaces by issuing reads to multiple ranks of DDR3 SDRAM (multiple chip select). Timing margins decrease as the number of ranks increases. It is impractical to supply one dedicated resynchronization clock for each rank of memory, as it consumes PLL resources for the relatively small benefit of improved timing margin. When calibration is complete `ctl_cal_success` goes high if successful; `ctl_cal_fail` goes high if calibration fails. Calibration can be repeated by the controller using the `soft_reset_n` signal, which when asserted puts the sequencer into a reset state and when released the calibration process begins again.

Other Local Interface Requirements

The memory burst length for DDR3 SDRAM devices can be set at either four or eight; but when using the Altera high-performance controller, only burst length eight is supported. For a half-rate controller, the memory clock runs twice as fast as the clock provided to the local interface, so data buses on the local interface are four times as wide as the memory data bus.

Address and Command Interfacing

Address and command signals are automatically sized for 1T operation, such that for full-rate designs there is one input bit per pin (for example, one `cs_n` input per chip select configured); for half-rate designs there are two. If you require a more conservative 2T address and command scheme, use a full-rate design and drive the address/command inputs for two clock cycles, or in a half-rate design drive both address/command bits for a given pin identically.



Although the PHY inherently supports 1T addressing, the high-performance controllers support only 2T addressing, so PHY timing analysis is performed assuming 2T address and command signals.

Handshake Mechanism Between Read Commands and Read Data

When performing a read, a high-performance controller with the AFI asserts `ctl_doing_read` to indicate that a read command is requested and the byte lanes that it expects valid data to return on. ALTMEMPHY uses `ctl_doing_read` for the following actions:

- Control of the postamble circuit
- Generation of `ctl_rdata_valid`
- Dynamic termination (R_t) control timing

The read latency, `ctl_rlat`, is advertised back to the controller. This signal indicates how long it takes in `ctl_clk` clock cycles from assertion of `ctl_doing_read` to valid read data returning on `ctl_rdata`. The `ctl_rlat` signal is only valid when calibration has successfully completed and never changes values during normal user mode operation.

The ALTMEMPHY provides a signal, `ctl_rdata_valid`, to indicate that the data on read data bus is valid. The width of this signal varies between half-rate and full-rate designs to support the option to indicate that the read data is not word aligned.

Figure 5-21 and Figure 5-22 show these relationships.

Figure 5-21. Address and Command and Read-Path Timing—Full-Rate Design

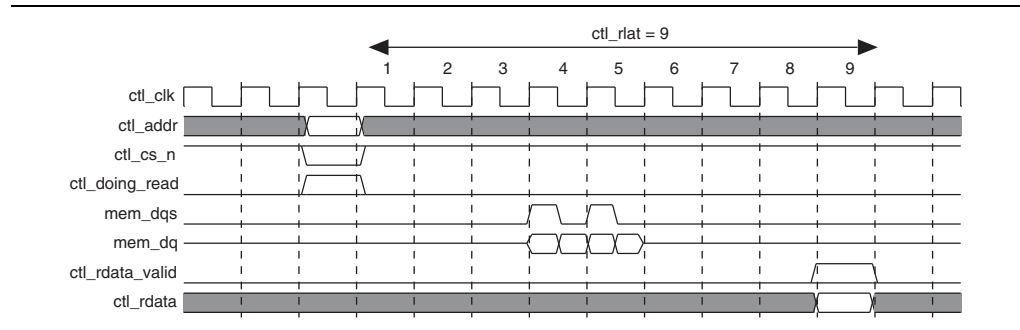
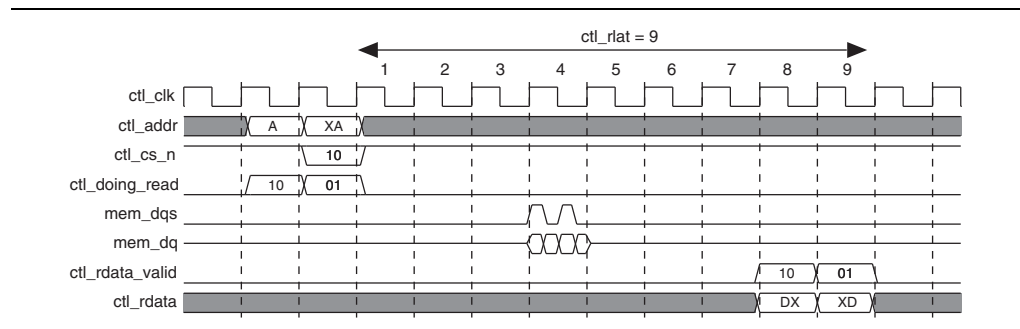


Figure 5-22. Second Read Alignment—Half-Rate Design



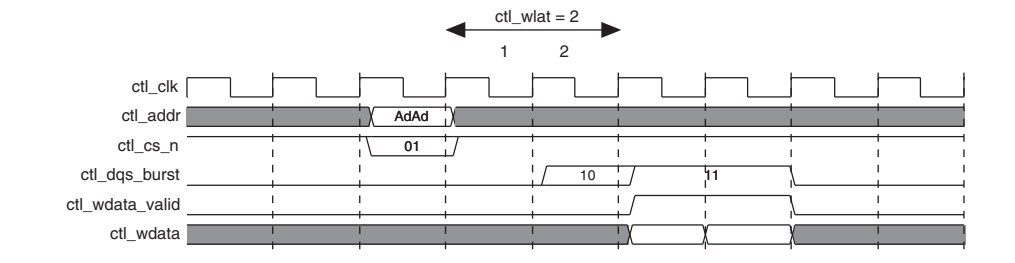
Handshake Mechanism Between Write Commands and Write Data

In the AFI, the ALTMEMPHY output `ctl_wlat` gives the number of `ctl_clk` cycles between the write command that is issued `ctl_cs_n` asserted and `ctl_dqs_burst` asserted. The `ctl_wlat` signal considers the following actions to provide a single value in `ctl_clk` clock cycles:

- CAS write latency
- Additive latency
- Datapath latencies and relative phases
- Board layout
- Address and command path latency and 1T register setting, which is dynamically setup to take into account any leveling effects

The `ctl_wlat` signal is only valid when the calibration has been successfully completed by the ALTMEMPHY sequencer and does not change at any point during normal user mode operation. Figure 5-23 shows the operation of `ctl_wlat` port.

Figure 5-23. Timing for `ctl_dqs_burst`, `ctl_wdata_valid`, Address, and Command—Half-Rate Design



For a half-rate design `ctl_cs_n` is 2 bits, not 1. Also the `ctl_dqs_burst` and `ctl_wdata_valid` waveforms indicate a half-rate design. This write results in a burst of 8 at the DDR. Where `ctl_cs_n` is driven $2'b01$, the LSB (1) is the first value driven out of `mem_cs_n`, and the MSB (0) follows on the next `mem_clk`. Similarly, for `ctl_dqs_burst`, the LSB is driven out of `mem_dqs` first (0), then a 1 follows on the next clock cycle. This sequence produces the continuous DQS pulse as required. Finally, the `ctl_addr` bus is twice `MEM_IF_ADDR_WIDTH` bits wide and so the address is concatenated to result in an address phase two `mem_clk` cycles wide.

Partial Writes

As part of the DDR3 SDRAM memory specifications, you have the option for partial write operations by asserting the DM pins for part of the write signal.

For designs targeting the Arria II and Stratix III devices, deassert the `ctl_wdata_valid` signal during partial writes, when the write data is invalid, to save power by not driving the DQ outputs.

For designs targeting other devices, use only the DM pins if you require partial writes. Assert the `ctl_dqs_burst` and `ctl_wdata_valid` signals as for full write operations, so that the DQ and DQS pins are driven during partial writes.

The I/O difference between Stratix III devices and other devices, and the preamble difference for DDR3 SDRAM on Arria II GX devices make it only possible to use the `ctl_dqs_burst` signal for the DQS enable in Stratix III devices.

The high-performance controller (HPC) architecture instantiates encrypted control logic and the ALTMEMPHY megafunction. The controller accepts read and write requests from the user on its local interface, using either the Avalon-MM interface protocol or the native interface protocol. It converts these requests into the necessary SDRAM commands, including any required bank management commands. Each read or write request on the Avalon-MM or native interface maps to one SDRAM read or write command.

The half-rate DDR3 SDRAM HPC accepts requests of size 1 or 2 on the local interface. If you request a burst size of 1, the controller issues a memory burst of 4 using the DDR3 SDRAM on-the-fly burst chop (waits for two cycles before issuing the next read or write command). If you request a burst size of 2, the controller issues a memory burst of 8 (issues the next read or write command back to back). Requests of size 2 on the local interface produce better throughput because DDR3 SDRAMs cannot accept back-to-back bursts of size 4.

The bank management logic in the controller keeps a row open in every bank in the memory system. For example, a controller configured for a dual-rank, 8-bank DDR3 SDRAM DIMM keeps an open row in each of the 16 banks. The controller allows you to request an auto-precharge read or auto-precharge write, allowing control over whether to keep that row open after the request. You can achieve maximum efficiency when you issue reads and writes to the same bank, with the last access to that bank being an auto-precharge read or write. The controller does not do any access reordering.

Block Description

Figure 6–1 on page 6–1 shows the top-level block diagram of the DDR3 SDRAM HPC.

Figure 6–1. DDR3 SDRAM HPC Block Diagram

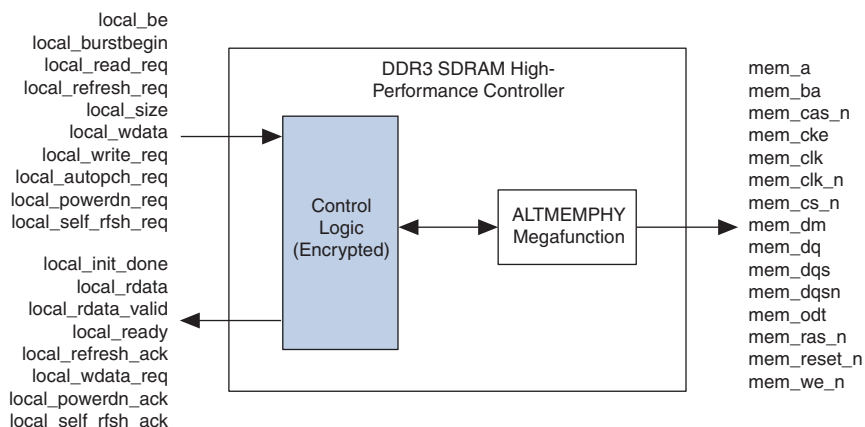
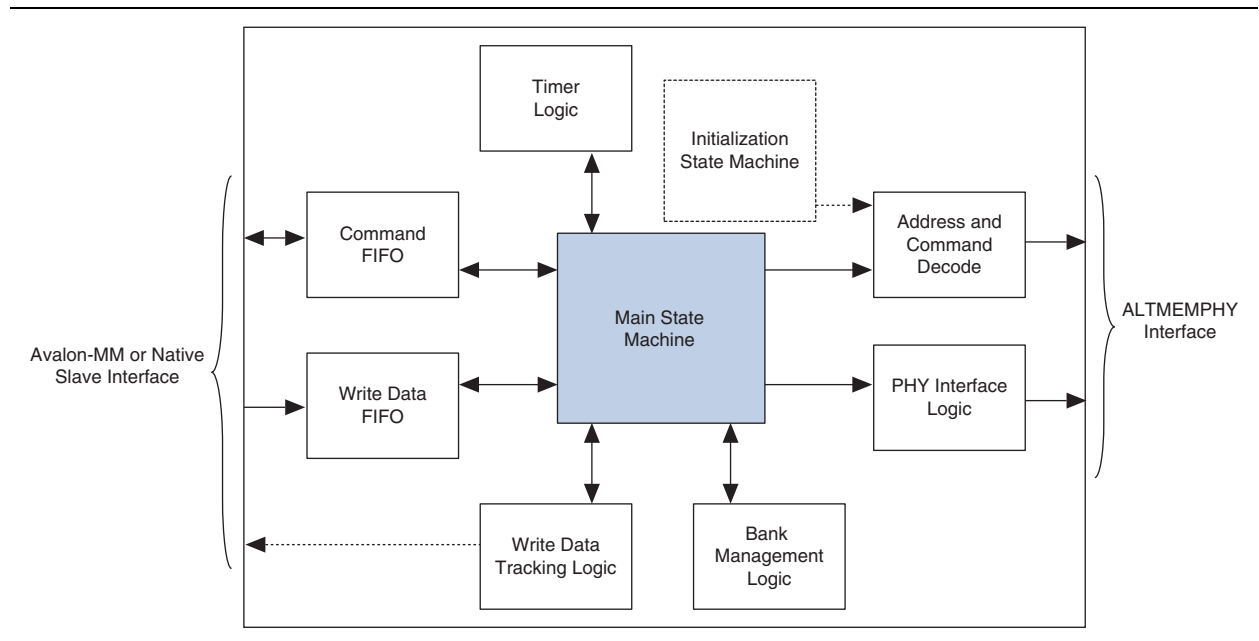


Figure 6-2 shows a block diagram of the DDR3 SDRAM HPC architecture.

Figure 6-2. DDR3 SDRAM HPC Architecture Block Diagram



The blocks in Figure 6-2 on page 6-2 are described in the following sections.

 For information on the Avalon interface, refer to *Avalon Interface Specifications*.

Command FIFO Buffer

This FIFO buffer allows the controller to buffer up to four consecutive read or write commands. It is built from logic elements, and stores the address, read or write flag, and burst count information. If this FIFO buffer fills up, the `local_ready` signal to the user is deasserted until the main state machine takes a command from the FIFO buffer.

Write Data FIFO Buffer

The write data FIFO buffer holds the write data from the user until the main state machine can send it to the ALTMEMPHY megafunction, which does not have a write data buffer. In the Avalon-MM interface mode, the user logic presents a write request, address, burst count, and one or more beats of data. The write data beats are placed into the FIFO buffer until they are needed. In the native interface mode, the user logic presents a write request, address, and burst count. The controller then requests the correct number of write data beats from the user via the `local_wdata_req` signal, and the user logic must return the write data in the clock cycle after the write data request signal.

This FIFO buffer is sized to be deeper than the command FIFO buffer to prevent it from filling up and interrupting streaming writes.

Write Data Tracking Logic

The write data tracking logic keeps track of the number of write data beats in the FIFO buffer. In native interface mode, this logic manages how much more data to request from the user logic and issues the `local_wdata_req` signal.

Main State Machine

The main state machine decides what DDR commands to issue based on inputs from the command FIFO buffer, the bank management logic, and the timer logic.

Bank Management Logic

The bank management logic keeps track the current state of each bank. It can keep a row open in every bank in your memory system. The state machine uses the information provided by this logic to decide whether it needs to issue bank management commands before it reads or writes to the bank. The controller always leaves the bank open unless the user requests an auto-precharge read or write. The periodic refresh process also causes all the banks to be closed.

Timer Logic

The timer logic tracks whether the required minimum number of clock cycles has passed since the last relevant command was issued. For example, the timer logic records how many cycles have elapsed since the last activate command so that the state machine knows it is safe to issue a read or write command (t_{RCD}). The timer logic also counts the number of clock cycles since the last periodic refresh command and sends a high priority alert to the state machine if the number of clock cycles has expired.

Initialization State Machine

The initialization state machine issues the appropriate sequence of command to initialize the memory devices. It is specific to DDR3 as each memory type requires a different sequence of initialization commands.

With the AFI, the `ALTMEMPHY` megafunction initializes the memory, otherwise the controller is responsible for initializing the memory.

Address and Command Decode

When the state machine wants to issue a command to the memory, it asserts a set of internal signals. The address and command decode logic turns these into the DDR-specific RAS, CAS, and WE commands.

PHY Interface Logic

When the main state machine issues a write command to the memory, the write data for that write burst has to be fetched from the write data FIFO buffer. The relationship between write command and write data depends on the memory type, ALTMEMPHY interface type, CAS latency, and the full-rate or half-rate setting. The PHY interface logic adjusts the timing of the write data FIFO read request signal so that the data arrives on the external memory interface DQ pins at the correct time.

ODT Generation Logic

The ODT generation logic (not shown in [Figure 6-2](#)) calculates when and for how long to enable the ODT outputs. It also decides which ODT bit to enable, based on the number of chip selects in the system.

- 1 DIMM (1 or 2 chip selects)

In the case of a single DIMM, the ODT signal is only asserted during writes. The ODT signal on the DIMM at `mem_cs[0]` is always used, even if the write command on the bus is to `mem_cs[1]`. In other words, `mem_odt[0]` is always asserted even if there are two ODT signals.

- 2 or more DIMMs

In the multiple DIMM case, the appropriate ODT bit is asserted for both read and writes. [Table 6-1](#) shows which ODT signal on the adjacent DIMM is enabled.

Table 6-1. ODT

Write or Read On	ODT Enabled
<code>mem_cs[0] OR cs[1]</code>	<code>mem_odt[2]</code>
<code>mem_cs[2] OR cs[3]</code>	<code>mem_odt[0]</code>
<code>mem_cs[4] OR cs[5]</code>	<code>mem_odt[6]</code>
<code>mem_cs[6] OR cs[7]</code>	<code>mem_odt[4]</code>

Low-Power Mode Logic

The low-power mode logic (not shown in [Figure 6-2](#)) monitors the `local_powerdn_req` and `local_self_rfsh_req` request signals. This logic also informs the user of the current low-power state via the `local_powerdn_ack` and `local_self_rfsh_ack` acknowledge signals.



HPC supports only precharge power-down mode and not active power-down mode.

Control Logic

Bus commands control SDRAM devices using combinations of the `mem_ras_n`, `mem_cas_n`, and `mem_we_n` signals. For example, on a clock cycle where all three signals are high, the associated command is a no operation (NOP). A NOP command is also indicated when the chip select signal is not asserted. Table 6-2 shows the standard SDRAM bus commands.

Table 6-2. Bus Commands

Command	Acronym	ras_n	cas_n	we_n
No operation	NOP	High	High	High
Active	ACT	Low	High	High
Read	RD	High	Low	High
Write	WR	High	Low	Low
Precharge	PCH	Low	High	Low
Auto refresh	ARF	Low	Low	High
Load mode register	LMR	Low	Low	Low

The DDR3 SDRAM HPC must open SDRAM banks before it accesses the addresses in that bank. The row and bank to be opened are registered at the same time as the active (ACT) command. The DDR3 SDRAM HPC closes the bank and opens it again if it needs to access a different row. The precharge (PCH) command closes only a bank.

The primary commands used to access SDRAM are read (RD) and write (WR). When the WR command is issued, the initial column address and data word is registered. When a RD command is issued, the initial address is registered. The initial data appears on the data bus 5 to 11 clock cycles later. This delay is the column address strobe (CAS) latency and is due to the time required to read the internal DRAM core and register the data on the bus. The CAS latency (of 6) depends on the speed of the SDRAM and the frequency of the memory clock. In general, the faster the clock, the more cycles of CAS latency are required. After the initial RD or WR command, sequential reads and writes continue until the burst length is reached. DDR3 SDRAM devices support fixed burst lengths of 4 or 8 data cycles or an on-the-fly mode where the controller can request a burst of 4 or 8 for each read or write command. This on-the-fly mode is the only mode supported. The auto-refresh command (ARF) is issued periodically to ensure data retention. This function is performed by the DDR3 SDRAM HPC.

The load mode register command (LMR) configures the SDRAM mode register. This register stores the CAS latency, burst length, and burst type.



For more information, refer to the specification of the SDRAM that you are using.

Error Correction Coding (ECC)

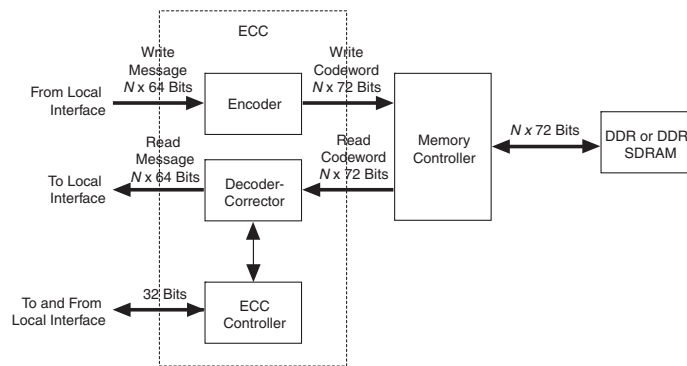
The optional ECC logic comprises an encoder and a decoder-corrector, which can detect and correct single-bit errors and detect double-bit errors. The ECC logic uses an 8-bit ECC for each 64-bit message. The ECC logic has the following features:

- Hamming code ECC logic that encodes every 64-bits of data into 72-bits of codeword with 8-bits of Hamming code parity bits

- Latency:
 - Maximum of 1 or 2 clock delay during writes
 - Minimum 1 or 3 clock delay during reads
- Detects and corrects all single-bit errors. Also the ECC logic sends an interrupt when the user-defined threshold for a single-bit error is reached.
- Detects all double-bit errors. Also, the ECC logic counts the number of double-bit errors and sends an interrupt when the user-define threshold for double-bit error is reached.
- Accepts partial writes
- Creates forced errors to check the functioning of the ECC logic
- Powers up to a ready state

Figure 6-3 shows the ECC block diagram.

Figure 6-3. ECC Block Diagram



The ECC comprises the following blocks:

- The encoder—encodes the 64-bit message to a 72-bit codeword
- The decoder-corrector—decodes and corrects the 72-bit codeword if possible

- The ECC controller—controls multiple encoder and decoder-correctors, so that the ECC can handle different bus widths. Also, it controls the following functions of the encoder and decoder-corrector:
 - Interrupts:
 - Detected and corrected single-bit error
 - Detected double-bit error
 - Single-bit error counter threshold exceeded
 - Double-bit error counter threshold exceeded
 - Configuration registers:
 - Single-bit error detection counter threshold
 - Double-bit error detection counter threshold
 - Capture status for first encountered error or most recent error
 - Enable deliberate corruption of ECC for test purposes
 - Status registers:
 - Error address
 - Error type: single-bit error or double-bit error
 - Respective byte error ECC syndrome
 - Error signal—an error signal corresponding to the data word is provided with the data and goes high if a double-bit error that cannot be corrected occurs in the return data word.
 - Counters:
 - Detected and/or corrected single-bit errors
 - Detected double-bit errors

The ECC logic can instantiate multiple encoders, each running in parallel, to encode any width of data words assuming they are integer multiples of 64.

The ECC logic operates between the local (native or Avalon-MM interface) and the memory controller.

The ECC logic has an $N \times 64$ -bit (where N is an integer) wide interface, between the local interface and the ECC logic, for receiving and returning data from the local interface. This interface can be a native interface or an Avalon-MM slave interface, you select the type of interface in the parameter editor.

The ECC logic has a second interface between the local interface and the ECC, which is a 32-bit wide Avalon-MM slave to control and report the status of the operation of the ECC controller.

The encoded data from the ECC logic is sent to the memory controller using a $N \times 72$ -bit wide Avalon-MM master interface, which is between the ECC logic and the memory controller.

When testing the DDR3 SDRAM HPC, you can turn off the ECC.

Interrupts

The ECC logic issues an interrupt signal when one of the following scenarios occurs:

- The single-bit error counter reaches the set maximum single-bit error threshold value.
- The double-bit error counter reaches the set maximum double-bit error threshold value.

The error counters increment every time the respective event occurs for all N parts of the return data word. This incremented value is compared with the maximum threshold and an interrupt signal is sent when the value is equal to the maximum threshold. The ECC logic clears the interrupts when you write a 1 to the respective status register. You can mask the interrupts from either of the counters using the control word.

Partial Writes

The ECC logic supports partial writes. Along with the address, data, and burst signals, the Avalon-MM interface also supports a signal vector that is responsible for byte-enable. Every bit of this signal vector represents a byte on the data-bus. Thus, a 0 on any of these bits is a signal for the controller not to write to that particular location—a partial write.

For partial writes, the ECC logic performs the following steps:

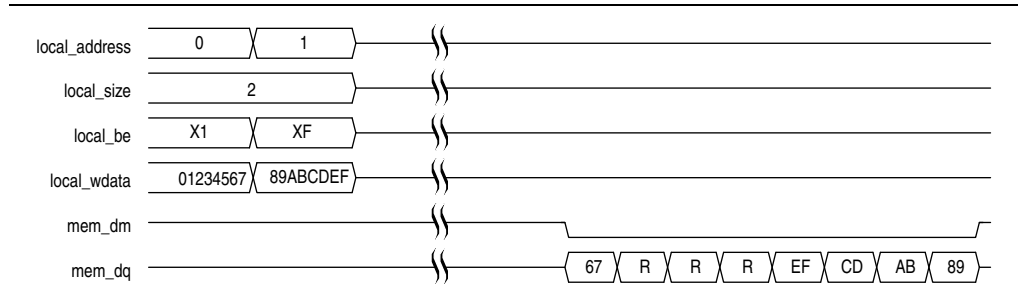
1. The ECC logic stalls further read or write commands from the Avalon-MM interface when it receives a partial write condition.
2. It simultaneously sends a self-generated read command, for the partial write address, to the memory controller.
3. Upon receiving the returned read data from the memory controller for the particular address, the decoder decodes the data, checks for errors, and then sends it to the ECC logic.
4. The ECC logic merges the corrected or correct dataword with the incoming information.
5. The ECC logic sends the updated dataword to the encoder for encoding, and then sends updated dataword to the memory controller with a write command.
6. The ECC logic stops stalling the commands from the Avalon-MM interface so that the logic can receive new commands.

The following corner cases can occur:

- A single-bit error during the read phase of the read-modify-write process. In this case, the single-bit error is corrected first, the single-bit error counter is incremented and then a partial write is performed to this corrected decoded data word.
- A double-bit error during the read phase of the read-modify-write process. In this case, the double-bit error counter is incremented and an interrupt is sent through the Avalon-MM interface. The new write word is written to the memory location. A separate field in the interrupt status register highlights this condition.

Figure 6-4 shows the partial write operation for HPC. The half-rate DDR3 SDRAM HPC supports a local size of 1 and 2.

Figure 6-4. Partial Write for HPC



Note to Figure 6-4:

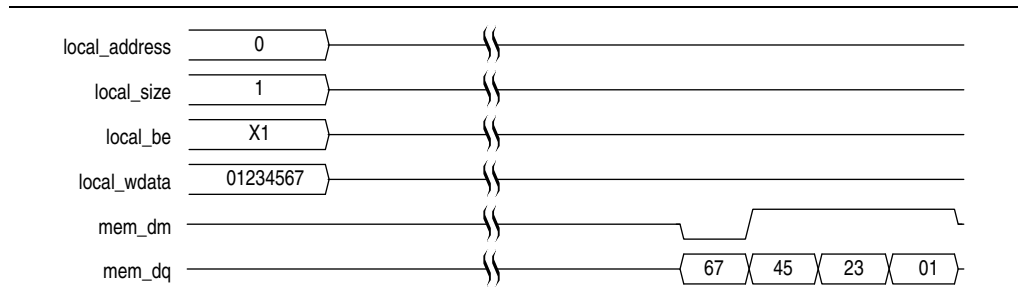
(1) R represents the internal read-back memory data during the read-modify-write process.

Partial Bursts

DIMMs that do not have the DM pins do not support partial bursts. A minimum of eight words must be written to the memory at the same time.

Figure 6-5 shows the partial burst operation for HPC.

Figure 6-5. Partial Burst for HPC



ECC Latency

Using the ECC results in the following latency changes:

- Local Burst Length 1
- Local Burst Length 2

Local Burst Length 1

For a local burst length of 1, the write latency increases by one clock cycle; the read latency increases by one clock cycle (including checking and correction).

A partial write results in a read followed by write in the ECC logic, so latency depends on the time the controller takes to fetch the data from the particular address.

Table 6-3 shows the relationship between burst lengths and rate.

Table 6-3. Burst Lengths and Rates

Local Burst Length	Rate	Memory Burst Length
1	Half	4
2	Full	4

Local Burst Length 2

For a local burst length of 2, the write latency increases by two clock cycles; the read latency increases by one clock cycle (including checking and correction).

A partial write results in a read followed by write in the ECC logic, so latency depends on the time the controller takes to fetch the data from the particular address.

For a single-bit error, the automatic correction of memory takes place without stalling the read cycle (if enabled), which stalls further commands to the ECC logic, while the correction takes place.

ECC Registers

Table 6-4 shows the ECC registers.

Table 6-4. ECC Registers (Part 1 of 3)

Name	Address	Size (Bits)	Attribute	Default	Description
Control word specifications	00	32	R/W	0000000F	This register contains all commands for the ECC functioning.
Maximum single-bit error counter threshold	01	32	R/W	00000001	The single-bit error counter increments (when a single-bit error occurs) until the maximum threshold, as defined by this register. When this threshold is crossed, the ECC logic generates an interrupt.
Maximum double-bit error counter threshold	02	32	R/W	00000001	The double-bit error counter increments (when a double-bit error occurs) until the maximum threshold, as defined by this register. When this threshold is crossed, the ECC logic generates an interrupt.
Current single-bit error count	03	32	RO	00000000	The single-bit error counter increments (when a single-bit error occurs) until the maximum threshold. You can find the value of the count by reading this status register.
Current double-bit error count	04	32	RO	00000000	The double-bit error counter increments (when a double-bit error occurs) until the maximum threshold. You can find the value of the count by reading this status register.
Last or first single-bit error error address	05	32	RO	00000000	This status register stores the last single-bit error error address. It can be cleared using the control word clear. If bit 10 of the control word is set high, the first occurred address is stored.

Table 6-4. ECC Registers (Part 2 of 3)

Name	Address	Size (Bits)	Attribute	Default	Description
Last or first double-bit error error address	06	32	RO	00000000	This status register stores the last double-bit error error address. It can be cleared using the control word clear. If bit 10 of the control word is set high, the first occurred address is stored.
Last single-bit error error data	07	32	RO	00000000	This status register stores the last single-bit error error data word. As the data word is an M th multiple of 64, the data word is stored in a $2N$ -deep, 32-bit wide FIFO buffer with the least significant 32-bit sub word stored first. It can be cleared individually by using the control word clear.
Last single-bit error syndrome	08	32	RO	00000000	This status register stores the last single-bit error syndrome, which specifies the location of the error bit on a 64-bit data word. As the data word is an M th multiple of 64, the syndrome is stored in a N deep, 8-bit wide FIFO buffer where each syndrome represents errors in every 64-bit part of the data word. The register gets updated with the correct syndrome depending on which part of the data word is shown on the last single-bit error error data register. It can be cleared individually by using the control word clear.
Last double-bit error error data	09	32	RO	00000000	This status register stores the last double-bit error error data word. As the data word is an M th multiple of 64, the data word is stored in a $2N$ deep, 32-bit wide FIFO buffer with the least significant 32-bit sub word stored first. It can be cleared individually by using the control word clear.
Interrupt status register	0A	5	RO	00000000	This status register stores the interrupt status in four fields (refer to Table 6-6). These status bits can be cleared by writing a 1 in the respective locations.
Interrupt mask register	0B	5	WO	00000001	This register stores the interrupt mask in four fields (refer to Table 6-7).

Table 6-4. ECC Registers (Part 3 of 3)

Name	Address	Size (Bits)	Attribute	Default	Description
Single-bit error location status register	0C	32	R/W	00000000	This status register stores the occurrence of single-bit error for each 64-bit part of the data word in every bit (refer to Table 6-8). These status bits can be cleared by writing a 1 in the respective locations.
Double-bit error location status register	0D	32	R/W	00000000	This status register stores the occurrence of double-bit error for each 64-bit part of the data word in every bit (refer to Table 6-9). These status bits can be cleared by writing a 1 in the respective locations.

ECC Register Bits

[Table 6-5](#) shows the control word specification register.

Table 6-5. Control Word Specification Register

Bit	Name	Direction	Description
0	Count single-bit error	Decoder-corrector	When 1, count single-bit errors.
1	Correct single-bit error	Decoder-corrector	When 1, correct single-bit errors.
2	Double-bit error enable	Decoder-corrector	When 1, detect all double-bit errors and increment double-bit error counter.
3	Reserved	N/A	Reserved for future use.
4	Clear all status registers	Controller	When 1, clear counters single-bit error and double-bit error status registers for first and last error address.
5	Reserved	N/A	Reserved for future use.
6	Reserved	N/A	Reserved for future use.
7	Counter clear on read	Controller	When 1, enables counters to clear on read feature.
8	Corrupt ECC enable	Controller	When 1, enables deliberate ECC corruption during encoding, to test the ECC.
9	ECC corruption type	Controller	When 0, creates single-bit errors in all ECC codewords; when 1, creates double-bit errors in all ECC codewords.
10	First or last error	Controller	When 1, stores the first error address rather than the last error address of single-bit error or double-bit error.
11	Clear interrupt	Controller	When 1, clears the interrupt.

Table 6-6 shows the interrupt status register.

Table 6-6. Interrupt Status Register

Bit	Name	Description
0	Single-bit error	When 1, single-bit error occurred.
1	Double-bit error	When 1, double-bit error occurred.
2	Maximum single-bit error	When 1, single-bit error maximum threshold exceeded.
3	Maximum double-bit error	When 1, double-bit error maximum threshold exceeded.
4	Double-bit error during read-modify-write	When 1, double-bit error occurred during a read modify write condition. (partial write).
Others	Reserved	Reserved.

Table 6-7 shows the interrupt mask register.

Table 6-7. Interrupt Mask Register

Bit	Name	Description
0	Single-bit error	When 1, masks single-bit error.
1	Double-bit error	When 1, masks interrupt when double-bit error occurs during a normal or read-modify-write condition (partial write). When 0, interrupt when double-bit error occurs during a normal or read-modify-write condition (partial write).
2	Maximum single-bit error	When 1, masks single-bit error maximum threshold exceeding condition.
3	Maximum double-bit error	When 1, masks double-bit error maximum threshold exceeding condition.
4	Double-bit error during read-modify-write	When 1, masks interrupt when double-bit error occurs during a read-modify-write condition (partial write). When 0, interrupt when double-bit error occurs during a read-modify-write condition (partial write).
Others	Reserved	Reserved.

Table 6-8 shows the single-bit error location status register.

Table 6-8. Single-Bit Error Location Status Register

Bit	Name	Description
Bits $N-1$ down to 0	Interrupt	When 0, no single-bit error; when 1, single-bit error occurred in this 64-bit part.
Others	Reserved	Reserved.

Table 6-9 shows the double-bit error location status register.

Table 6-9. Double-Bit Error Location Status Register

Bit	Name	Description
Bits N-1 down to 0	Cause of Interrupt	When 0, no double-bit error; when 1, double-bit error occurred in this 64-bit part.
Others	Reserved	Reserved.

Example Top-Level File

The MegaWizard Plug-In Manager helps you create an example top-level file that shows you how to instantiate and connect the DDR3 SDRAM HPC. The example top-level file consists of the DDR3 HPC, some driver logic to issue read and write requests to the controller. The example top-level file is a working system that you can compile and use for both static timing checks and board tests.

Figure 6-6 shows the testbench and the example top-level file.

Figure 6-6. Testbench and Example Top-Level File

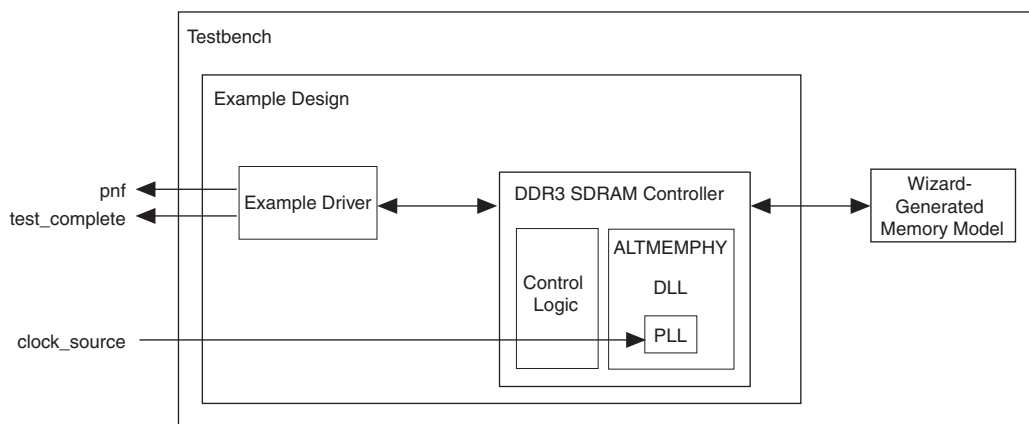


Table 6-10 describes the files that are associated with the example top-level file and the testbench.

Table 6-10. Example Top-Level File and Testbench Files


Filename	Description
<variation name>_example_top_tb.v or .vhd	Testbench for the example top-level file.
<variation name>_example_top.v or .vhd	Example top-level file.
<variation name>_mem_model.v or .vhd	Associative-array memory model.
<variation name>_full_mem_model.v or .vhd	Full-array memory model.
<variation name>_example_driver.v or .vhd	Example driver.
<variation name>.v or .vhd	Top-level description of the custom MegaCore function.
<variation name>.qip	Contains Quartus II project information for your MegaCore function variations.

There are two Altera-generated memory models available—associative-array memory model and full-array memory model.

The associative-array memory model (*<variation name>_mem_model.v*) allocates reduced set of memory addresses with a default depth of 2,048 or 2K address spaces. This allocation allows for a larger memory array compilation and simulation which enables you to easily reconfigure the depth of the associate array.

The full-array memory model (*<variation name>_full_mem_model.v*) allocates memory for all addresses accessible by the DDR cores. This allocation makes it impossible to simulate large memory (more than 2K address spaces) designs, because simulators need more memory than what is available on a typical system.

Both the memory models display similar behaviors and have the same calibration time.

 The memory model, *<variation name>_test_component.v/vhd*, used in SOPC Builder designs, is actually a variation of the full-array memory model. To ensure your simulation works in SOPC Builder, use memory model with less than 512-Mbit capacity.

Example Driver

The example driver is a self-checking test pattern generator for the memory interface. It uses a state machine to write and read from the memory to verify that the interface is operating correctly.

It performs the following tests and loops back the tests indefinitely:

- Sequential addressing writes and reads

The state machine writes pseudo-random data generated by a linear feedback shift register (LFSR) to a set of incrementing row, bank, and column addresses. The state machine then resets the LFSR, reads back the same set of addresses, and compares the data it receives against the expected data. You can adjust the length and pattern of the bursts that are written by changing the `MAX_ROW`, `MAX_BANK`, and `MAX_COL` constants in the example driver source code, and the entire memory space can be tested by adjusting these values. You can skip this test by setting the `test_seq_addr_on` signal to logic zero.

- Incomplete write operation

The state machine issues a series of write requests that are less than the maximum burst size supported by your controller variation. The addresses are then read back to ensure that the controller has issued the correct signals to the memory. This test is only applicable when the local burst size is two. You can skip this test by setting the `test_incomplete_writes_on` signal to logic zero.

- Byte enable/data mask pin operation

The state machine issues two sets of write commands, the first of which clears a range of addresses. The second set of write commands has only one byte enable bit asserted. The state machine then issues a read request to the same addresses and the data is verified. This test checks if the data mask pins are operating correctly. You can skip this test by setting the `test_dm_pin_on` signal to logic zero.

- Address pin operation

The example driver generates a series of write and read requests starting with an all-zeros pattern, a walking-one pattern, a walking-zero pattern, and ending with an all-zeros pattern. This test checks to make sure that all the individual address bits are operating correctly. You can skip this test by setting the `test_addr_pin_on` signal to logic zero.

- Low-power mode operation

The example driver requests that the controller place the memory into power-down and self-refresh states, and hold it in those states for the amount of time specified by the `COUNTER_VALUE` signal. You can vary this value to adjust the duration the memory is kept in the low-power states. This test is only available if your controller variation enables the low-power mode option.

The example driver has four outputs that allow you to observe which tests are currently running and if the tests are passing. The pass not fail (`pnf`) signal goes low once one or more errors occur and remains low. The pass not fail per byte (`pnf_per_byte`) signal goes low when there is incorrect data in a byte but goes back high again once correct data is observed in the following byte. The `test_status` signal indicates the test that is currently running, allowing you to determine which test has failed. The `test_complete` signal goes high for a single clock cycle at the end of the set of tests.

Table 6-11 shows the bit mapping for each test status.

Table 6-11. Test Status[] Bit Mapping

Bit	Test
0	Sequential address test
1	Incomplete write test
2	Data mask pin test
3	Address pin test
4	Power-down test
5	Self-refresh test
6	Auto precharge test

Top-level Signals Description

Table 6-12 shows the clock and reset signals.

Table 6-12. Clock and Reset Signals (Part 1 of 2)

Name	Direction	Description
<code>global_reset_n</code>	Input	The asynchronous reset input to the controller. All other reset signals are derived from resynchronized versions of this signal. This signal holds the complete ALTMEMPHY megafunction, including the PLL, in reset while low.
<code>pll_ref_clk</code>	Input	The reference clock input to PLL.
<code>soft_reset_n</code>	Input	Edge detect reset input intended for SOPC Builder use or to be controlled by other system reset logic. It is asserted to cause a complete reset to the PHY, but not to the PLL used in the PHY.

Table 6-12. Clock and Reset Signals (Part 2 of 2)

Name	Direction	Description
oct_ctl_rs_value	Input	ALTMEMPHY signal that specifies the serial termination value. Should be connected to the ALT_OCT megafunction output <code>seriesterminationcontrol</code> .
oct_ctl_rt_value	Input	ALTMEMPHY signal that specifies the parallel termination value. Should be connected to the ALT_OCT megafunction output <code>parallelterminationcontrol</code> .
dqs_delay_ctrl_import	Input	Allows the use of DLL in another ALTMEMPHY instance in this ALTMEMPHY instance. Connect the <code>export</code> port on the ALTMEMPHY instance with a DLL to the <code>import</code> port on the other ALTMEMPHY instance.

Table 6-13 on page 6-17 shows the DDR3 SDRAM HPC local interface signals.

Table 6-13. Local Interface Signals (Part 1 of 4)


Signal Name	Direction	Description
local_address[]	Input	<p>Memory address at which the burst should start. The width of this bus is sized using the following equation:</p> <p>For one chip select: width = bank bits + row bits + column bits – 2</p> <p>For multiple chip selects: width = chip bits + bank bits + row bits + column bits – 2</p> <p>If the bank address is 3 bits wide, row is 14 bits wide and column is 10 bits wide, then the local address is 25 bits wide. To map <code>local_address</code> to bank, row and column address:</p> <p><code>local_address</code> is 25 bits wide <code>local_address[24:22] = bank address [2:0]</code> <code>local_address[21:8] = row address [13:0]</code> <code>local_address [7:0] = col_address[9:2]</code></p> <p>The two least significant bits (LSB) of the column address on the memory side are ignored, because the local data width is four times that of the memory data bus width.</p> <p> You can get the information on address mapping from the <code><variation_name>_example_top.v</code> or <code>vhd</code> file.</p>
local_be[]	Input	<p>Byte enable signal, which you use to mask off individual bytes during writes. <code>local_be</code> is active high; <code>mem_dm</code> is active low.</p> <p>To map <code>local_wdata</code> and <code>local_be</code> to <code>mem_dq</code> and <code>mem_dm</code>, consider a full-rate design with 32-bit <code>local_wdata</code> and 16-bit <code>mem_dq</code>.</p> <p><code>Local_wdata = < 22334455 >< 667788AA >< BBCCDDEE ></code> <code>Local_be = < 1100 >< 0110 >< 1010 ></code></p> <p>These values map to:</p> <p><code>Mem_dq = <4455><2233><88AA><6677><DDEE><BBCC></code> <code>Mem_dm = <1 1 ><0 0 ><0 1 ><1 0 ><0 1 ><0 1 ></code></p>

Table 6-13. Local Interface Signals (Part 2 of 4)

Signal Name	Direction	Description
local_burstbegin	Input	<p>Avalon burst begin strobe, which indicates the beginning of an Avalon burst. This signal is only available when the local interface is an Avalon-MM interface and the memory burst length is greater than 2. Unlike all other Avalon-MM signals, the burst begin signal does not stay asserted if local_ready is deasserted.</p> <p>For write transactions, assert this signal at the beginning of each burst transfer and keep this signal high for one cycle per burst transfer, even if the slave has deasserted the local_ready signal. After the slave deasserts the local_ready signal, the master keeps all the write request signals asserted until the local_ready signal becomes high again.</p> <p>For read transactions, assert this signal for one clock cycle when read request is asserted and the local_address from which the data should be read is given to the memory. After the slave deasserts the local_ready signal (waitrequest_n in Avalon), the master keeps all the read request signals asserted until the local_ready signal becomes high again.</p>
local_read_req	Input	Read request signal. You cannot assert the read request signal before the reset_phy_clk_n signal goes high.
local_refresh_req	Input	User-controlled refresh request. If Enable user auto-refresh controls is turned on, local_refresh_req becomes available and you are responsible for issuing sufficient refresh requests to meet the memory requirements. This option allows complete control over when refreshes are issued to the memory including ganging together multiple refresh commands. Refresh requests take priority over read and write requests unless they are already being processed.
local_size[]	Input	Controls the number of beats in the requested read or write access to memory, encoded as a binary number. The DDR3 SDRAM HPC supports burst lengths of 1 and 2 on the local side interface.
local_wdata[]	Input	Write data bus. The width of local_wdata is twice that of the memory data bus for a full rate controller; four times the memory data bus for a half rate controller.
local_write_req	Input	Write request signal. You cannot assert the write request signal before the reset_phy_clk_n signal goes high.
local_autopch_req	Input	User control of precharge. If Enable Auto-Precharge Control is turned on, local_autopch_req becomes available and you can request the controller to issue an auto-precharge write or auto-precharge read command. These commands cause the memory to issue a precharge command to the current bank at the appropriate time without an explicit precharge command from the controller. This is particularly useful if you know the current read or write is the last one you intend to issue to the currently open row. The next time you need to use that bank, the access could be quicker as the controller does not need to precharge the bank before activating the row you wish to access.

Table 6-13. Local Interface Signals (Part 3 of 4)

Signal Name	Direction	Description
local_powerdn_req	Input	User control of the power-down feature. If Enable Power Down Controls option is enabled, you can request that the controller place the memory devices into a power-down state as soon as it can without violating the relevant timing parameters and responds by asserting the <code>local_powerdn_ack</code> signal. You can hold the memory in the power-down state by keeping this signal asserted. The controller brings the memory out of the power-down state to issue periodic auto-refresh commands to the memory at the appropriate interval if you hold it in the power-down state. You can release the memory from the power-down state at any time by deasserting the <code>local_powerdn_ack</code> signal once it has successfully brought the memory out of the power-down state.
local_self_rfsh_req	Input	User control of the self-refresh feature. If Enable Self-Refresh Controls option is enabled, you can request that the controller place the memory devices into a self-refresh state by asserting this signal. The controller places the memory in the self-refresh state as soon as it can without violating the relevant timing parameters and responds by asserting the <code>local_self_rfsh_ack</code> signal. You can hold the memory in the self-refresh state by keeping this signal asserted. You can release the memory from the self-refresh state at any time by deasserting the <code>local_self_rfsh_req</code> signal and the controller responds by deasserting the <code>local_self_rfsh_ack</code> signal once it has successfully brought the memory out of the self-refresh state.
phy_clk	Output	The system clock that the ALTMEMPHY megafunction provides to the user. All user inputs to and outputs from the DDR HPC must be synchronous to this clock.
reset_phy_clk_n	Output	The reset signal that the ALTMEMPHY megafunction provides to the user. It is asserted asynchronously and deasserted synchronously to <code>phy_clk</code> clock domain.
dll_reference_clk	Output	Reference clock to feed to an externally instantiated DLL.
reset_request_n	Output	Reset request output that indicates when the PLL outputs are not locked. Use this signal as a reset request input to any system-level reset controller you may have. This signal is always low when the PLL is trying to lock, and so any reset logic using it is advised to detect a reset request on a falling edge rather than by level detection.
local_init_done	Output	When the memory initialization, training, and calibration are complete, the ALTMEMPHY sequencer asserts the <code>ctrl_usr_mode_rdy</code> signal to the memory controller, which then asserts this signal to indicate that the memory interface is ready to be used. Read and write requests are still accepted before <code>local_init_done</code> is asserted, however they are not issued to the memory until it is safe to do so. This signal does not indicate that the calibration is successful. To find out if the calibration is successful, look for the calibration signal, <code>ctl_cal_success</code> or <code>ctl_cal_fail</code> .
local_rdata[]	Output	Read data bus. The width of <code>local_rdata</code> is four times the memory data bus.
local_rdata_error	Output	Asserted if the current read data has an error. This signal is only available if the Enable error detection and correction logic is turned on.

Table 6–13. Local Interface Signals (Part 4 of 4)

Signal Name	Direction	Description
local_rdata_valid	Output	Read data valid signal. The <code>local_rdata_valid</code> signal indicates that valid data is present on the read data bus. The timing of <code>local_rdata_valid</code> is automatically adjusted to cope with your choice of resynchronization and pipelining options.
local_ready	Output	The <code>local_ready</code> signal indicates that the DDR3 SDRAM HPC is ready to accept request signals. If <code>local_ready</code> is asserted in the clock cycle that a read or write request is asserted, that request has been accepted. The <code>local_ready</code> signal is deasserted to indicate that the DDR3 SDRAM HPC cannot accept any more requests. The controller is able to buffer four read or write requests.
local_refresh_ack	Output	Refresh request acknowledge, which is asserted for one clock cycle every time a refresh is issued. Even if the Enable User Auto-Refresh Controls option is not selected, <code>local_refresh_ack</code> still indicates to the local interface that the controller has just issued a refresh command.
local_wdata_req	Output	Write data request signal, which indicates to the local interface that it should present valid write data on the next clock edge. This signal is only required when the controller is operating in Native interface mode.
local_powerdn_ack	Output	Power-down request acknowledge signal. This signal is asserted and deasserted in response to the <code>local_powerdn_req</code> signal from the user.
local_self_rfsh_ack	Output	Self refresh request acknowledge signal. This signal is asserted and deasserted in response to the <code>local_self_rfsh_req</code> signal from the user.

Table 6–14 shows the DDR3 SDRAM interface signals.

Table 6–14. DDR3 SDRAM Interface Signals

Signal Name	Direction	Description
mem_dq[]	Bidirectional	Memory data bus. This bus is half the width of the local read and write data busses.
mem_dqs[]	Bidirectional	Memory data strobe signal, which writes data into the DDR3 SDRAM and captures read data into the Altera device.
mem_clk (1)	Bidirectional	Clock for the memory device.
mem_clk_n (1)	Bidirectional	Inverted clock for the memory device.
mem_a[]	Output	Memory address bus.
mem_ba[]	Output	Memory bank address bus.
mem_cas_n	Output	Memory column address strobe signal.
mem_cke[]	Output	Memory clock enable signals.
mem_cs_n[]	Output	Memory chip select signals.
mem_dm[]	Output	Memory data mask signal, which masks individual bytes during writes.
mem_odt[]	Output	Memory on-die termination control signal.
mem_ras_n	Output	Memory row address strobe signal.
mem_reset_n	Output	Memory reset signal.
mem_we_n	Output	Memory write enable signal.

Note to Table 6–14:

- (1) The `mem_clk` signals are output only signals from the FPGA. However, in the Quartus II software they must be defined as bidirectional (INOUT) I/Os to support the mimic path structure that the ALTMEMPHY megafunction uses.

Table 6-15 shows the ECC logic signals.

Table 6-15. ECC Logic Signals

Signal Name	Direction	Description
ecc_addr[]	Input	Address for ECC logic.
ecc_be[]	Input	ECC logic byte enable.
ecc_read_req	Input	Read request for ECC logic.
ecc_wdata[]	Input	ECC logic write data.
ecc_write_req	Input	Write request for ECC logic.
ecc_interrupt	Output	Interrupt from ECC logic.
ecc_rdata[]	Output	Return data from ECC logic.

The high-performance controller II (HPC II) architecture is an upgraded controller with higher efficiency and more features than the HPC. HPC II is recommended for all new designs.

HPC II is pin-out compatible with your existing DDR high-performance designs. HPC II has the following additional features:

- Higher efficiency with in-order read and write commands, and out-of-order bank management commands
- Run-time programmability to configure the behavior of the controller
- Integrated burst adapter supporting a range of burst sizes on the local interface
- Integrated ECC logic, supporting 40-bit and 72-bit interfaces with partial word writes and optional write back on error
- Reduced bank tracking for area optimization
- Controller variable latency to enhance the performance of your design
- Support for multi-rank UDIMM and RDIMM ports

Upgrading from HPC to HPC II


If you want to migrate your designs from the existing HPC to the more efficient HPC II, you must do the following:

- In the **Preset Editor** dialog box, assign the following HPC II timing parameters to match your memory specification. Set these parameters according to the memory datasheet:
 - t_{FAW}
 - t_{RRD}
 - t_{RTP}

For example, for Micron DDR3-800 datasheet, $t_{FAW}=40$ ns, $t_{RRD}=10$ ns, $t_{RTP}=10$ ns.

- HPC II replaces the port interface level for the AFI and Avalon interface without requiring any top-level change.

- The side-band signals differ slightly for HPC II. If you use these signals, you need to perform the following steps.
 - `local_refresh_req`
You need to drive an additional active high signal, `local_refresh_chip`, to control which chip to issue the user-refresh to.
 - `local_powerdn_req`
The user-manual power signal is no longer supported in HPC II. Instead, you can select auto power-down on the **Controller Settings** tab in the MegaWizard Plug-In Manager, and specify the desired time-out (n cycles) after which the controller automatically powers down the memory.
- Because HPC II only supports a specific memory burst length, you must update the memory burst length to match the controller settings. For DDR3, HPC II supports on-the-fly burst length in half-rate mode.
- Because HPC II supports arbitrary user burst length ranging from of 1 to 64, you can adjust the `max_local_size` value in HPC II. Adjusting the maximum local size value changes the width of the `local_size` signal. The maximum `local_size` signal value is 2^{n-1} , where n is the width of the `local_size` signal. HPC has a fixed `local_size` signal width of 2.

 You only can migrate your HPC designs to HPC II if you are using an Avalon-MM interface.

Block Description

Figure 7–1 shows the top-level block diagram of the DDR3 SDRAM HPC II.

Figure 7–1. DDR3 SDRAM HPC II Block Diagram

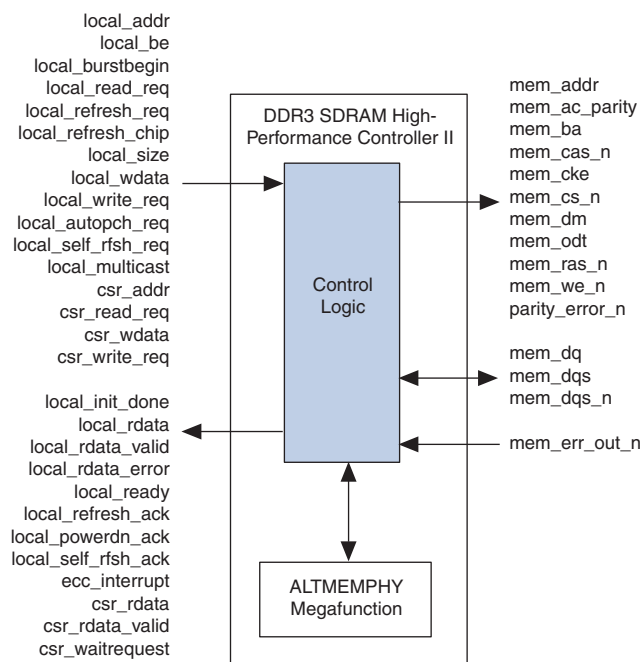
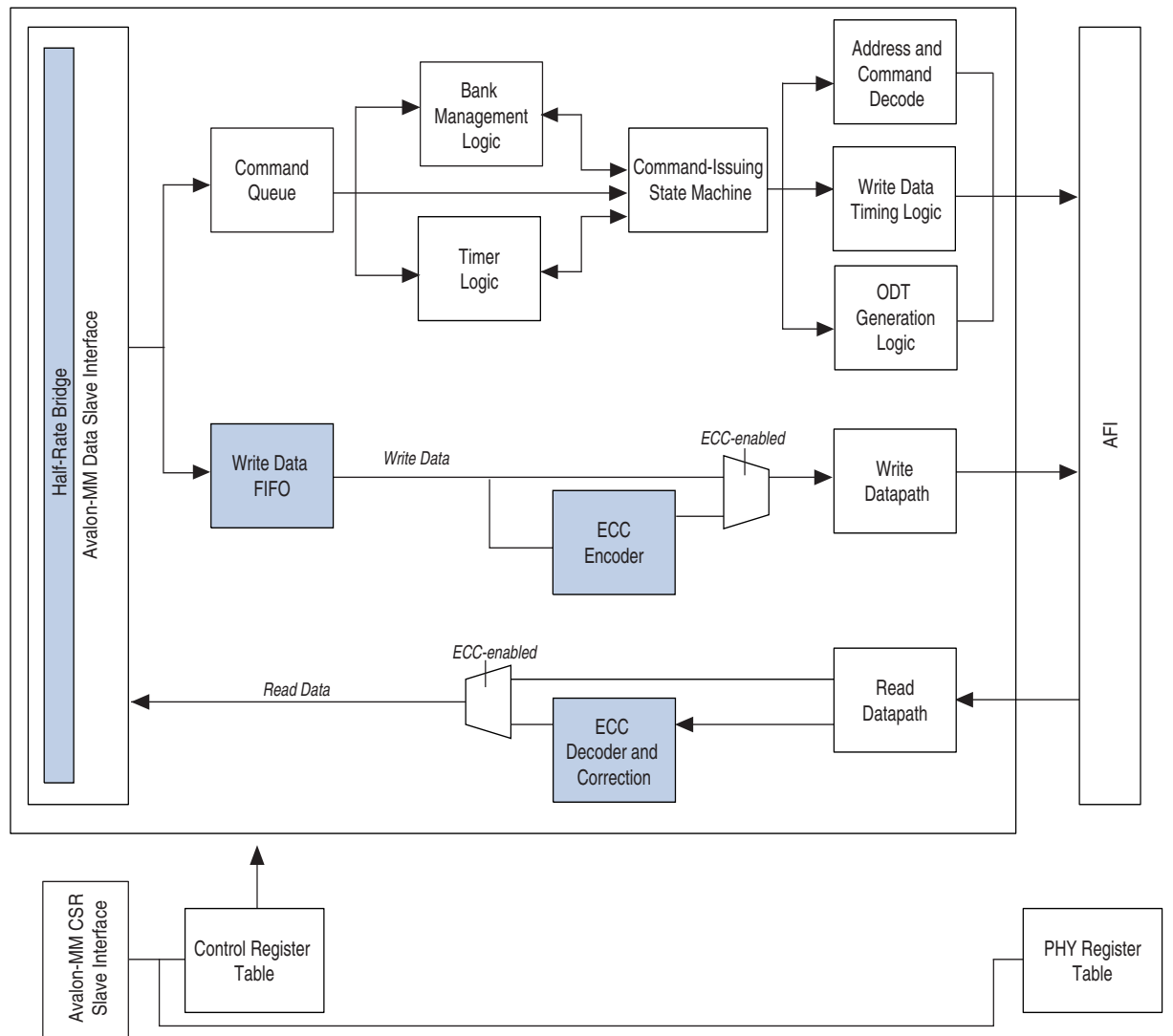


Figure 7-2 shows a block diagram of the DDR3 SDRAM HPC II architecture.

Figure 7-2. DDR3 SDRAM HPC II Architecture Block Diagram



The blocks in Figure 7-2 on page 7-3 are described in the following sections.

Avalon-MM Data Slave Interface

The Avalon-MM data slave interface accepts read and write requests from the Avalon-MM master. The width of the data, `local_wdata` and `local_rdata`, is four times the width of the external memory.

The local address width is sized based on the memory chip, row, bank, and column address widths. For example:

- For multiple chip select:

$$\text{width} = \text{chip bits} + \text{row bits} + \text{bank bits} + \text{column} - 2$$

- For single chip select:

$$\text{width} = \text{row bits} + \text{bank bits} + \text{column} - 2$$

For every Avalon transaction, the number of read or write requests cannot exceed the the maximum local burst count of 64. Altera recommends that you set this maximum burst count to match your system master's supported burst count.

Write Data FIFO Buffer

The write data FIFO buffer holds the write data and byte-enable from the user logic until the main state machine requests for the data. The `local_ready` signal is deasserted when either the command queue or write data FIFO buffer is full. The write data FIFO buffer is wide enough to store the write data and the byte-enable signals.

Command Queue

The command queue allows the controller to buffer up to eight consecutive reads or writes. The command queue presents the next 4, 6, or 8 accesses to the internal logic for the look-ahead bank management. The bank management is more efficient if the look-ahead is deeper, but a deeper queue consumes more resources, and may cause maximum frequency degradation.

In addition to storing incoming commands, the command queue also maps the local address to memory address based on the address mapping option selected. By default, the command queue leverages the bank interleaving scheme, where the address increment goes to the next bank instead of the next row to increase chances of page hit.

Bank Management Logic

The bank management logic keeps track of the current state in each bank across multiple chips. It can keep a row open in every bank in your memory system. When a command is issued by the state machine, the bank management logic is updated with the latest bank status. The main state machine uses its look-ahead capability to issue early bank management commands. The controller supports a close-page policy, where a bank is closed after it is used.

The bank management logic also includes a reduced bank tracking feature that reduces the controller's resource usage. This feature allows you to reduce the number of bank tracking blocks in the bank management logic. However, the number of bank tracking blocks used is limited because the controller is limited to the number of pages it keeps open at any given time. This limit is determined by the controller's command queue look-ahead depth.

The reduced bank tracking feature provides the ability for the controller to dynamically allocate a memory bank to be tracked to one of the available bank tracking block. When you do not need the memory bank to be tracked anymore, the memory bank is no longer allocated.


This feature is useful if your design is highly dependent on the total number of banks. Using this feature may have an impact on the memory bus efficiency, but it allows a trade-off between area and efficiency. The higher the number of banks to track, the better the efficiency.

Timer Logic

The timer logic models the internal behavior of each bank in the memory interface and provides status output signals to the state machine. The state machine then decides whether to issue the look-ahead bank management command based on the timer status signals.

Command-Issuing State Machine

The command-issuing state machine decides what DDR commands to issue based on the inputs from the command queue, bank management logic, and timer logic. The DDR3 SDRAM provides half-rate command-issuing state machine. The half-rate state machine supports 2T address and command, and issues “on-the-fly” memory bursts.

 A longer memory burst length, in this case 8 beats, increases the command bandwidth by allowing more data cycles for the same amount of command cycles. A longer memory burst length also provides more command cycles that ensures a more effective look-ahead bank management. However, longer memory burst lengths are less efficient if the bursts you issue do not provide enough data to fill the burst.

This state machine accepts any local burst count of 1 to 64. The built-in burst adapter in this state machine maps the local burst count to the most efficient memory burst. The state machine also supports reads and writes that start on non-aligned memory burst boundary addresses. For effective command bus bandwidth, this state machine supports additive latency which issues reads and writes immediately after the ACT command. This state machine accepts additive latency values greater or equal to $t_{\text{RCD}} - 1$, in clock cycle unit (t_{CK}).

Address and Command Decode Logic

When the main state machine issues a command to the memory, it asserts a set of internal signals. The address and command decode logic turns these signals into AFI-specific commands and address. This block generates the following signals:

- Clock enable and reset signals: `afi_cke`, `afi_rst_n`
- Command and address signals: `afi_cs_n`, `afi_ba`, `afi_addr`, `afi_ras_n`, `afi_cas_n`, `afi_we_n`

Write and Read Datapath, and Write Data Timing Logic

The write and read datapath, and the write data timing logic generate the AFI read and write control signals.

When the state machine issues a write command to the memory, the IP core gets the write data for that write burst from the write data FIFO buffer. The relationship between the write command and write data depends on the `afi_wlat` signal. The write data timing logic presents the write data FIFO read request signal so that the data arrives on the external memory interface DQ pins at the correct time.

During write, the following AFI signals are generated based on the state machine outputs and the `afi_wlat` signal:

- `afi_dqs_burst`

- `afi_wdata_valid`
- `afi_wdata`
- `afi_dm`

During read, the `afi_doing_read` signal generates the `afi_rdata_valid` signal and controls the ALTMEMPHY postamble circuit.

ODT Generation Logic

The ODT generation logic generates the necessary ODT signals for DDR3 SDRAM HPC II memory devices, based on the scheme recommended by Altera.

Table 7-1 shows which ODT signal on the adjacent DIMM is enabled.

Table 7-1. ODT

DIMM	Chip Select per DIMM	Write or Read On	ODT Enabled (Write)	ODT Enabled (Read)
1	Single chip select	<code>mem_cs[0]</code>	<code>mem_odt[0]</code>	— (1)
	Dual chip select	<code>mem_cs[0]</code>	<code>mem_odt[0]</code>	— (1)
		<code>mem_cs[1]</code>	<code>mem_odt[1]</code>	— (1)
2	Single chip select	<code>mem_cs[0]</code>	<code>mem_odt[0]</code> and <code>mem_odt[1]</code>	<code>mem_odt[1]</code>
		<code>mem_cs[1]</code>	<code>mem_odt[0]</code> and <code>mem_odt[1]</code>	<code>mem_odt[0]</code>
	Dual chip select	<code>mem_cs[0]</code>	<code>mem_odt[0]</code> and <code>mem_odt[2]</code>	<code>mem_odt[2]</code>
		<code>mem_cs[1]</code>	<code>mem_odt[1]</code> and <code>mem_odt[3]</code>	<code>mem_odt[3]</code>
		<code>mem_cs[2]</code>	<code>mem_odt[0]</code> and <code>mem_odt[2]</code>	<code>mem_odt[0]</code>
		<code>mem_cs[3]</code>	<code>mem_odt[1]</code> and <code>mem_odt[3]</code>	<code>mem_odt[1]</code>

Note to Table 7-1:

(1) The controller does not drive the ODT signals during read operation.

User-Controlled Side-Band Signals

The user-controlled side-band signals consists of the following signals.

User-Refresh Commands

The user-refresh command enables the request to place the memory into refresh mode. The user-refresh control takes precedence over a read or write request. You can issue up to nine consecutive refresh commands to the selected memory chips. However, if you enable the multi-cast write feature, the user refresh commands are always issued to all chips.

Multi-Cast Write

The multi-cast write request signal allows you to ask the controller to send the current write requests to all the chip selects. This means that the write data is written to all the ranks in the system. The multi-cast write feature is useful for t_{RC} mitigation where you can cycle through chips to continuously read data without hitting t_{RC} . The multi-cast write is not supported for registered DIMM interfaces or when the ECC logic is enabled.

Low-Power Mode Logic

There are two types of low-power mode logic: the user-controlled self-refresh logic and automatic power-down with programmable time-out logic.


User-Controlled Self-Refresh Logic

When you assert the `local_self_rfsh_req` signal, the controller completes all pending reads and writes before it places the memory into self-refresh mode. Once the controller places the memory into self-refresh mode, it responds by asserting the acknowledge signal, `local_self_rfsh_ack`. You can leave the memory in self-refresh mode for as long as you choose.

To bring the memory out of self-refresh mode, you must deassert the request signal, and the controller responds by deasserting the acknowledge signal when the memory is no longer in self-refresh mode.

Automatic Power-Down with Programmable Time-Out


The controller automatically places the memory in power-down mode to save power if the requested number of idle controller clock cycles is observed in the controller. The **Auto Power Down Cycles** parameter on the **Controller Settings** tab allows you to specify a range between 1 to 65,535 idle controller clock cycles. The counter for the programmable time-out starts when there are no user read or write requests in the command queue. Once the controller places the memory in power-down mode, it responds by asserting the acknowledge signal, `local_powerdown_ack`.

 HPC II supports only precharge power-down mode and not active power-down mode.

Configuration and Status Register (CSR) Interface

The configuration and status register interface is a 32-bit wide interface that uses the Avalon-MM interface standard. The CSR interface allows you to configure the timing parameters, address widths, and the behavior of the controller for without leveling interfaces. If you do not need this feature, you can disable it and all the programmable settings are fixed to the values configured during the generation process. This interface is synchronous to the controller clock.

 The CSR interface is not fully supported for DDR3 SDRAM with leveling interfaces, such as DIMMs.

 Refer to [Table 7-9](#) through [Table 7-23](#) in [page 7-18](#) for detailed information about the register maps.

Error Correction Coding (ECC)

The optional ECC logic comprises an encoder and a decoder-corrector, which can detect and correct single-bit errors, and detect double-bit errors. The ECC logic is available in two widths: 64/72 bit and 32/40 bit. The ECC logic has the following features:

- Hamming code ECC logic that encodes every 64 or 32 bits of data into 72 or 40 bits of codeword.

- A latency increase of one clock for both writes and reads.
- Detects and corrects all single-bit errors.
- Detects all double-bit errors.
- Counts the number of single-bit and double-bit errors.
- Accepts partial writes, which trigger a read-modify-write cycle, for memory devices with DM pins.
- Is able to inject single-bit and double-bit errors to trigger ECC correction for testing and debugging purposes.
- Generates an interrupt signal when an error occurs.

When a single-bit or double-bit error occurs, the ECC logic triggers the `ecc_interrupt` signal to inform you that an ECC error has occurred. When a single-bit error occurs, the ECC logic issues an internal read to the error address, and performs an internal write to write back the corrected data. When a double-bit error occurs, the ECC logic does not do any error correction but it asserts the `local_rdata_error` signal to indicate that the data is incorrect. The `local_rdata_error` signal follows the same timing as the `local_rdata_valid` signal.

Enabling auto-correction allows the ECC logic to hold off all controller pending activities until the correction is completed. You can choose to disable auto-correction and schedule the correction manually when the controller is idle to ensure better system efficiency. To manually correct ECC errors, do the following:

1. When an interrupt occurs, read the `SBE_ERROR` register. When a single-bit error occurs, the `SBE_ERROR` register is equal to one.
 2. Read out the `ERR_ADDR` register.
 3. Correct the single-bit error by doing one of the following:
 - Issue a dummy write to the memory address stored in the `ERR_ADDR` register. A dummy write is a write request with the `local_be` signal zero, that triggers a partial write which is effectively a read-modify-write event. The partial write corrects the data at that address and writes it back.
- or
- Enable the `ENABLE_AUTO_CORR` register using the CSR interface and issue a read request to the memory address stored in the `ERR_ADDR` register. The read request triggers auto-error correction to the memory address stored in the `ERR_ADDR` register.

Partial Writes

The ECC logic supports partial writes. Along with the address, data, and burst signals, the Avalon-MM interface also supports a signal vector, `local_be`, that is responsible for byte-enable. Every bit of this signal vector represents a byte on the data-bus. Thus, a logic low on any of these bits instructs the controller not to write to that particular byte, resulting in a partial write. The ECC code is calculated on all bytes of the data-bus. If any bytes are changed, the ECC code must be recalculated and the new code must be written back to the memory.

For partial writes, the ECC logic performs the following steps:

1. The ECC logic sends a read command to the partial write address.
2. Upon receiving a return data from the memory for the particular address, the ECC logic decodes the data, checks for errors, and then merges the corrected or correct dataword with the incoming information.
3. The ECC logic issues a write to write back the updated data and the new ECC code.

The following corner cases can occur:

- A single-bit error during the read phase of the read-modify-write process. In this case, the single-bit error is corrected first, the single-bit error counter is incremented and then a partial write is performed to this corrected decoded data word.
- A double-bit error during the read phase of the read-modify-write process. In this case, the double-bit error counter is incremented and an interrupt is issued. A new write word is written to the location of the error. The ECC status register keeps track of the error information.

Figure 7-3 shows the partial write operation for HPC II.

Figure 7-3. Partial Write for HPC II



Note to Figure 7-3:

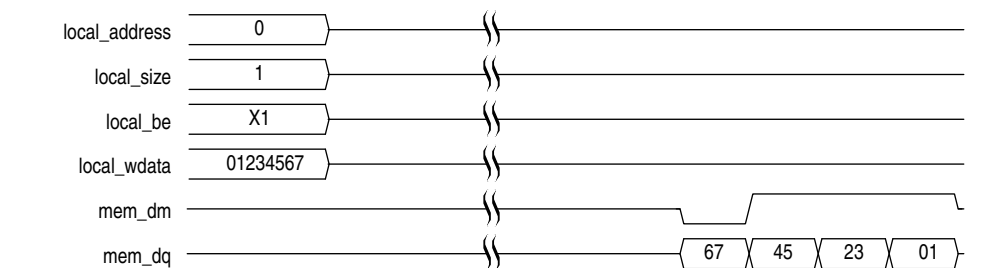
- (1) R represents the internal read-back memory data during the read-modify-write process.

Partial Bursts

DIMMs that do not have the DM pins do not support partial bursts. You must write a minimum of eight words to the memory at the same time.

Figure 7-4 shows the partial burst operation for HPC II.

Figure 7-4. Partial Burst for HPC II



Example Top-Level File

The MegaWizard Plug-In Manager helps you create an example top-level file that shows you how to instantiate and connect the DDR3 SDRAM HPC II. The example top-level file consists of the DDR3 SDRAM HPC II, some driver logic to issue read and write requests to the controller, a PLL to create the necessary clocks, and a DLL (Stratix series only). The example top-level file is a working system that you can compile and use for both static timing checks and board tests.

Figure 7-5 shows the testbench and the example top-level file.

Figure 7-5. Testbench and Example Top-Level File

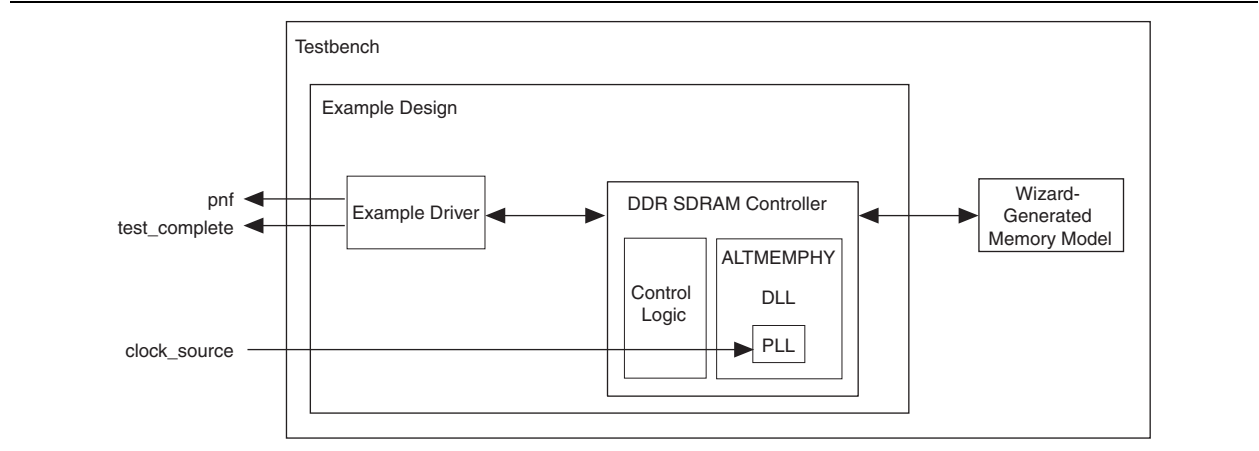


Table 7-2 describes the files that are associated with the example top-level file and the testbench.

Table 7-2. Example Top-Level File and Testbench Files

Filename	Description
<variation name>_example_top_tb.v or .vhd	Testbench for the example top-level file.
<variation name>_example_top.v or .vhd	Example top-level file.
<variation name>_mem_model.v or .vhd	Associative-array memory model.
<variation name>_full_mem_model.v or .vhd	Full-array memory model.
<variation name>_example_driver.v or .vhd	Example driver.
<variation name>.v or .vhd	Top-level description of the custom MegaCore function.
<variation name>.qip	Contains Quartus II project information for your MegaCore function variations.

There are two Altera-generated memory models available—associative-array memory model and full-array memory model.

The associative-array memory model (<variation name>_mem_model.v) allocates reduced set of memory addresses with a default depth of 2,048 or 2K address spaces. This allocation allows for a larger memory array compilation and simulation which enables you to easily reconfigure the depth of the associate array.

The full-array memory model (<variation name>_mem_model_full.v) allocates memory for all addresses accessible by the DDR cores. This allocation makes it impossible to simulate large memory designs.

Both the memory models display similar behaviors and have the same calibration time.



The memory model, `<variation name>_test_component.v/vhd`, used in SOPC Builder designs, is actually a variation of the full-array memory model. To ensure your simulation works in SOPC Builder, use memory model with less than 512-Mbit capacity.

Example Driver

The example driver is a self-checking test pattern generator for the memory interface. It uses a state machine to write and read from the memory to verify that the interface is operating correctly.

The example driver performs the following tests and loops back the tests indefinitely:

- Sequential addressing writes and reads

The state machine writes pseudo-random data generated by a linear feedback shift register (LFSR) to a set of incrementing row, bank, and column addresses. The state machine then resets the LFSR, reads back the same set of addresses, and compares the data it receives against the expected data. You can adjust the length and pattern of the bursts that are written by changing the `MAX_ROW`, `MAX_BANK`, and `MAX_COL` constants in the example driver source code, and the entire memory space can be tested by adjusting these values. You can skip this test by setting the `test_seq_addr_on` signal to logic zero.

- Incomplete write operation

The state machine issues a series of write requests that are less than the maximum burst size supported by your controller variation. The addresses are then read back to ensure that the controller has issued the correct signals to the memory. This test is only applicable in full-rate mode, when the local burst size is two. You can skip this test by setting the `test_incomplete_writes_on` signal to logic zero.

- Byte enable/data mask pin operation

The state machine issues two sets of write commands, the first of which clears a range of addresses. The second set of write commands has only one byte enable bit asserted. The state machine then issues a read request to the same addresses and the data is verified. This test checks if the data mask pins are operating correctly. You can skip this test by setting the `test_dm_pin_on` signal to logic zero.

- Address pin operation

The example driver generates a series of write and read requests starting with an all-zeros pattern, a walking-one pattern, a walking-zero pattern, and ending with an all-zeros pattern. This test checks to make sure that all the individual address bits are operating correctly. You can skip this test by setting the `test_addr_pin_on` signal to logic zero.

- Low-power mode operation

The example driver requests the controller to place the memory into power-down and self-refresh states, and hold it in those states for the amount of time specified by the `COUNTER_VALUE` signal. You can vary this value to adjust the duration the memory is kept in the low-power states. This test is only available if your controller variation enables the low-power mode option.

The example driver has four outputs that allow you to observe which tests are currently running and if the tests are passing. The pass not fail (`pnf`) signal goes low once one or more errors occur and remains low. The pass not fail per byte (`pnf_per_byte`) signal goes low when there is incorrect data in a byte but goes back high again once correct data is observed in the following byte. The `test_status` signal indicates the test that is currently running, allowing you to determine which test has failed. The `test_complete` signal goes high for a single clock cycle at the end of the set of tests.

Table 7-3 shows the bit mapping for each test status.

Table 7-3. Test Status[] Bit Mapping

Bit	Test
0	Sequential address test
1	Incomplete write test
2	Data mask pin test
3	Address pin test
4	Power-down test
5	Self-refresh test
6	Auto precharge test

Top-level Signals Description

Table 7-4 shows the clock and reset signals.

Table 7-4. Clock and Reset Signals (Part 1 of 2)

Name	Direction	Description
<code>global_reset_n</code>	Input	The asynchronous reset input to the controller. All other reset signals are derived from resynchronized versions of this signal. This signal holds the complete ALTMEMPHY megafunction, including the PLL, in reset while low.
<code>pll_ref_clk</code>	Input	The reference clock input to PLL.
<code>phy_clk</code>	Output	The system clock that the ALTMEMPHY megafunction provides to the user. All user inputs to and outputs from the DDR3 HPC II must be synchronous to this clock.
<code>reset_phy_clk_n</code>	Output	The reset signal that the ALTMEMPHY megafunction provides to the user. It is asserted asynchronously and deasserted synchronously to <code>phy_clk</code> clock domain.

Table 7-4. Clock and Reset Signals (Part 2 of 2)

Name	Direction	Description
aux_full_rate_clk	Output	An alternative clock that the ALTMEMPHY megafunction provides to the user. This clock always runs at the same frequency as the external memory interface. In half-rate mode, this clock is twice the frequency of the phy_clk and can be used whenever a 2x clock is required. In full-rate mode, this clock is driven by the same PLL output as the phy_clk signal.
aux_half_rate_clk	Output	An alternative clock that the ALTMEMPHY megafunction provides to the user. This clock always runs at half the frequency as the external memory interface. In full-rate mode, this clock is half the frequency of the phy_clk and can be used, for example to clock the user side of a half-rate bridge. In half-rate mode, or if the Enable Half Rate Bridge option is turned on, this clock is driven by the same PLL output that drives the phy_clk signal.
dll_reference_clk	Output	Reference clock to feed to an externally instantiated DLL.
reset_request_n	Output	Reset request output that indicates when the PLL outputs are not locked. Use this signal as a reset request input to any system-level reset controller you may have. This signal is always low when the PLL is trying to lock, and so any reset logic using it is advised to detect a reset request on a falling edge rather than by level detection.
soft_reset_n	Input	Edge detect reset input intended for SOPC Builder use or to be controlled by other system reset logic. It is asserted to cause a complete reset to the PHY, but not to the PLL used in the PHY.
oct_ctl_rs_value	Input	ALTMEMPHY signal that specifies the serial termination value. Should be connected to the ALT_OCT megafunction output serieterminationcontrol.
oct_ctl_rt_value	Input	ALTMEMPHY signal that specifies the parallel termination value. Should be connected to the ALT_OCT megafunction output parallelterminationcontrol.
dqs_delay_ctrl_import	Input	Allows the use of DLL in another ALTMEMPHY instance in this ALTMEMPHY instance. Connect the export port on the ALTMEMPHY instance with a DLL to the import port on the other ALTMEMPHY instance.

Table 7-5 shows the DD3 SDRAM HPC II local interface signals.

Table 7-5. Local Interface Signals (Part 1 of 3)

Signal Name	Direction	Description
local_address[]	Input	<p>Memory address at which the burst should start.</p> <p>By default, the local address is mapped to the bank interleaving scheme. You can change the ordering via the Local-to-Memory Address Mapping option in the Controller Settings page.</p> <p>The width of this bus is sized using the following equation:</p> <p>For one chip select: width = row bits + bank bits + column bits – 2</p> <p>For multiple chip selects: width = chip bits + row bits + bank bits + column bits – 2</p> <p>If the bank address is 2 bits wide, row is 13 bits wide and column is 10 bits wide, then the local address is 23 bits wide. To map local_address to bank, row and column address:</p> <p>local_address is 23 bits wide local_address [22:10] = row address [12:0] local_address [9:8] = bank address [1:0] local_address [7:0] = column address [9:2]</p> <p>Two least significant bits (LSB) of the column address on the memory side are ignored, because the local data width is four times that of the memory data bus width.</p>
local_be[]	Input	<p>Byte enable signal, which you use to mask off individual bytes during writes. local_be is active high; mem_dm is active low.</p> <p>To map local_wdata and local_be to mem_dq and mem_dm, consider a full-rate design with 32-bit local_wdata and 16-bit mem_dq.</p> <p>Local_wdata = < 22334455 >< 667788AA >< BBCCDDEE > Local_be = < 1100 >< 0110 >< 1010 ></p> <p>These values map to:</p> <p>Mem_dq = <4455><2233><88AA><6677><DDEE><BBCC> Mem_dm = <1 1 ><0 0 ><0 1 ><1 0 ><0 1 ><0 1 ></p>
local_burstbegin	Input	<p>Avalon burst begin strobe, which indicates the beginning of an Avalon burst. Unlike all other Avalon-MM signals, the burst begin signal does not stay asserted if local_ready is deasserted.</p> <p>For write transactions, assert this signal at the beginning of each burst transfer and keep this signal high for one cycle per burst transfer, even if the slave has deasserted the local_ready signal. This signal is sampled at the rising edge of the phy_clk when the local_write_req signal is asserted. After the slave deasserts the local_ready signal, the master keeps all the write request signals asserted until local_ready signal becomes high again.</p> <p>For read transactions, assert this signal for one clock cycle when read request is asserted and the local_address from which the data should be read is given to the memory. After the slave deasserts the local_ready signal (waitrequest_n in Avalon interface), the master keeps all the read request signals asserted until the local_ready signal becomes high again.</p>

Table 7-5. Local Interface Signals (Part 2 of 3)

Signal Name	Direction	Description
local_read_req	Input	Read request signal. You cannot assert the read request signal before the <code>reset_phy_clk_n</code> signal goes high.
local_refresh_req	Input	User-controlled refresh request. If Enable User Auto-Refresh Controls option is turned on, <code>local_refresh_req</code> becomes available and you are responsible for issuing sufficient refresh requests to meet the memory requirements. This option allows complete control over when refreshes are issued to the memory including grouping together multiple refresh commands. Refresh requests take priority over read and write requests, unless the requests are already being processed.
local_refresh_chip	Input	Controls which chip to issue the user-refresh to. This active high signal is used together with the <code>local_refresh_req</code> signal. This signal is as wide as the memory chip select. This signal asserts a high value to each bit that represents the refresh for the corresponding memory chip. For example: If the <code>local_refresh_chip</code> signal is assigned with a value of <code>4'b0101</code> , the controller refreshes the memory chips 0 and 2, and memory chips 1 and 3 are not refreshed. If you turn on the Enable Multi-cast Write Control option, this signal is ignored.
local_size[]	Input	Controls the number of beats in the requested read or write access to memory, encoded as a binary number. The range of supported Avalon burst lengths is 1 to 64. The width of this signal is derived based on the burst count specified in the Local Maximum Burst Count option. With the derived width, you choose a value ranging from 1 to the local maximum burst count specified.
local_wdata[]	Input	Write data bus. The width of <code>local_wdata</code> is four times the memory data bus for a half rate controller.
local_write_req	Input	Write request signal. You cannot assert the write request signal before the <code>reset_phy_clk_n</code> signal goes high.
local_multicast	Input	In-band multi-cast write request signal. This active high signal is used together with the <code>local_write_req</code> signal. When this signal is asserted high, data is written to all the memory chips available.
local_self_rfsh_req	Input	User control of the self-refresh feature. If Enable Self-Refresh Controls option is enabled, you can request that the controller place the memory devices into a self-refresh state by asserting this signal. The controller places the memory in the self-refresh state as soon as it can without violating the relevant timing parameters and responds by asserting the <code>local_self_rfsh_ack</code> signal. You can hold the memory in the self-refresh state by keeping this signal asserted. You can release the memory from the self-refresh state at any time by deasserting the <code>local_self_rfsh_req</code> signal and the controller responds by deasserting the <code>local_self_rfsh_ack</code> signal once it has successfully brought the memory out of the self-refresh state.
local_init_done	Output	When the memory initialization, training, and calibration are complete, the ALTMEMPHY sequencer asserts the <code>ctrl_usr_mode_rdy</code> signal to the memory controller, which then asserts this signal to indicate that the memory interface is ready to be used. Read and write requests are still accepted before <code>local_init_done</code> is asserted, however they are not issued to the memory until it is safe to do so. This signal does not indicate that the calibration is successful.

Table 7-5. Local Interface Signals (Part 3 of 3)

Signal Name	Direction	Description
local_rdata[]	Output	Read data bus. The width of <code>local_rdata</code> is twice that of the memory data bus for a full rate controller; four times the memory data bus for a half rate controller.
local_rdata_error	Output	Asserted if the current read data has an error. This signal is only available if the Enable Error Detection and Correction Logic option is turned on. This signal is asserted together with the <code>local_rdata_valid</code> signal. If the controller encounters double-bit errors, no correction is made and the controller asserts this signal.
local_rdata_valid	Output	Read data valid signal. The <code>local_rdata_valid</code> signal indicates that valid data is present on the read data bus.
local_ready	Output	The <code>local_ready</code> signal indicates that the controller is ready to accept request signals. If the <code>local_ready</code> signal is asserted in the clock cycle that a read or write request is asserted, that request is accepted. The <code>local_ready</code> signal is deasserted to indicate that the controller cannot accept any more requests. The controller is able to buffer eight read or write requests.
local_refresh_ack	Output	Refresh request acknowledge, which is asserted for one clock cycle every time a refresh is issued. Even if the Enable User Auto-Refresh Controls option is not selected, <code>local_refresh_ack</code> still indicates to the local interface that the controller has just issued a refresh command.
local_self_rfsh_ack	Output	Self refresh request acknowledge signal. This signal is asserted and deasserted in response to the <code>local_self_rfsh_req</code> signal from the user.
local_power_down_ack	Output	Auto power-down acknowledge signal. This signal is asserted for one clock cycle every time auto power-down is issued.
ecc_interrupt	Output	Interrupt signal from the ECC logic. This signal is asserted when the ECC feature is turned on, and an error is detected. This signal remains asserted until the user logic clears the error through the CSR interface.

Table 7-6 shows the DDR3 SDRAM HPC II CSR interface signals.

Table 7-6. CSR Interface Signals (Part 1 of 2) (Part 1 of 2)

Signal Name	Direction	Description
csr_addr[]	Input	Register map address. The width of <code>csr_addr</code> is 16 bits.
csr_be[]	Input	Byte-enable signal, which you use to mask off individual bytes during writes. <code>csr_be</code> is active high.
csr_wdata[]	Input	Write data bus. The width of <code>csr_wdata</code> is 32 bits.
csr_write_req	Input	Write request signal. You cannot assert <code>csr_write_req</code> and <code>csr_read_req</code> signals at the same time.
csr_read_req	Input	Read request signal. You cannot assert <code>csr_read_req</code> and <code>csr_write_req</code> signals at the same time.
csr_rdata[]	Output	Read data bus. The width of <code>csr_rdata</code> is 32 bits.

Table 7-6. CSR Interface Signals (Part 2 of 2) (Part 2 of 2)

Signal Name	Direction	Description
csr_rdata_valid	Output	Read data valid signal. The <code>csr_rdata_valid</code> signal indicates that valid data is present on the read data bus.
csr_waitrequest	Output	The <code>csr_waitrequest</code> signal indicates that the HPC II is busy and not ready to accept request signals. If the <code>csr_waitrequest</code> signal goes high in the clock cycle when a read or write request is asserted, that request is not accepted. If the <code>csr_waitrequest</code> signal goes low, the HPC II is then ready to accept more requests.

Table 7-7 shows the DDR3 SDRAM HPC II interface signals.

Table 7-7. DDR3 SDRAM Interface Signals

Signal Name	Direction	Description
mem_dq[]	Bidirectional	Memory data bus. This bus is half the width of the local read and write data busses.
mem_dqs[]	Bidirectional	Memory data strobe signal, which writes data into the DDR3 SDRAM and captures read data into the Altera device.
mem_dqs_n[]	Bidirectional	Inverted memory data strobe signal, which is used together with the <code>mem_dqs</code> signal to improve signal integrity.
mem_clk (1)	Bidirectional	Clock for the memory device.
mem_clk_n (1)	Bidirectional	Inverted clock for the memory device.
mem_addr[]	Output	Memory address bus.
mem_ac_parity (2)	Output	Address or command parity signal generated by the PHY and sent to the DIMM.
mem_ba[]	Output	Memory bank address bus.
mem_cas_n	Output	Memory column address strobe signal.
mem_cke[]	Output	Memory clock enable signals.
mem_cs_n[]	Output	Memory chip select signals.
mem_dm[]	Output	Memory data mask signal, which masks individual bytes during writes.
mem_odt	Output	Memory on-die termination control signal.
mem_ras_n	Output	Memory row address strobe signal.
mem_we_n	Output	Memory write enable signal.
parity_error_n (2)	Output	Active-low signal that is asserted when a parity error occurs and stays asserted until the PHY is reset.
mem_err_out_n (2)	Input	Signal sent from the DIMM to the PHY to indicate that a parity error has occurred for a particular cycle.

Notes to Table 7-7:

- (1) The `mem_clk` signals are output only signals from the FPGA. However, in the Quartus II software they must be defined as bidirectional (INOUT) I/Os to support the mimic path structure that the ALTMEMPHY megafunction uses.
- (2) This signal is for Registered DIMMs only.

Table 7-8 shows the ALTMEMPHY Debug interface signals, which are located in `<variation_name>_phy.v/vhd` file.

Table 7-8. ALTMEMPHY Debug Interface Signals

Signal Name	Direction	Description
dbg_clk	Input	Debug interface clock
dbg_addr	Input	Debug interface address
dbg_cs	Input	Debug interface chip select
dbg_wr	Input	Debug interface write request
dbg_wr_data	Input	Debug interface write data
dbg_rd	Input	Debug interface read request
dbg_rd_data	Input	Debug interface read data
dbg_waitrequest	Output	Debug interface wait request

Register Maps Description

Table 7-9 through Table 7-23 show the register maps for the DDR3 SDRAM HPC II.

Table 7-9. Register Map

Address	Contents
ALTMEMPHY Register Map	
0x005	Mode register 0-1
0x006	Mode register 2-3
Controller Register Map	
0x100	ALTMEMPHY status and control register
0x110	Controller status and configuration register
0x120	Memory address size register 0
0x121	Memory address size register 1
0x122	Memory address size register 2
0x123	Memory timing parameters register 0
0x124	Memory timing parameters register 1
0x125	Memory timing parameters register 2
0x126	Memory timing parameters register 3
0x130	ECC control register
0x131	ECC status register
0x132	ECC error address register

ALTMEMPHY Register Map

The ALTMEMPHY register map allows you to control the memory components' mode register settings. To access the ALTMEMPHY register map, connect the ALTMEMPHY Debug interface signals in [Table 7-8](#) using the Avalon-MM protocol.

After configuring the ALTMEMPHY register map, initialize a calibration request by setting bit 2 in the CSR register map address 0x100 ([Table 7-12](#)) for the mode register settings to take effect.


 DDR3 SDRAM with leveling does not support the ALTMEMPHY register map. For more information about DDR3 SDRAM with leveling, refer to “[DDR3 SDRAM With Leveling](#)” on page 5-7.

Table 7-10. Address 0x005 Mode Register 0-1 (Part 1 of 2)

Bit	Name	Default	Access	Description
2:0	Burst length	8	RO	This value is set to 8 because the DDR3 SDRAM HPC II only supports a burst length of 8.
3	BT	0	RO	This value is set to 0 because DDR3 SDRAM SDRAM HPC II only supports sequential bursts.
6:4	CAS latency	—	RW	CAS latency setting. The default value for these bits is set by the MegaWizard CAS Latency setting for your controller instance. You must set this value in the CSR interface register map 0x126 (Table 7-20) as well.
7	Reserved	0	—	Reserved for future use.
8	DLL	0	RW	Not used by the controller, but you can set and program into the memory device mode register.
11:9	Write recovery	—	RW	Write recovery (t_{WR}) setting. The default value for these bits is set by the MegaWizard Write Recovery (t_{WR}) setting for your controller instance. You must set this value in CSR interface register map 0x126 (Table 7-20) as well.
12	PD	0/1	RO	This value is set to 0 because DDR3 SDRAM HPC II only supports power-down fast exit mode.
15:13	Reserved	0	—	Reserved for future use.
16	DLL	0	RW	Not used by the controller, but you can set and program into the memory device mode register.
17	ODS	0	RW	
18	RTT	0	RW	
21:19	AL	—	RW	Additive latency setting. The default value for these bits is set by the MegaWizard Additive Latency setting for your controller instance. You must set this value in CSR interface register map 0x126 (Table 7-20) as well.

Table 7-10. Address 0x005 Mode Register 0-1 (Part 2 of 2)

Bit	Name	Default	Access	Description
22	RTT	0	RW	Not used by the controller, but you can set and program into the memory device mode register.
25:23	RTT/WL/OCD	0	RW	
26	DQS#	0	RW	
27	TDQS/RDQS	0	RW	
28	QOFF	0	RW	
31:29	Reserved	0	—	Reserved for future use.

Table 7-11. Address 0x006 Mode Register 2-3

Bit	Name	Default	Access	Description
2:0	Reserved	0	—	Reserved for future use.
5:3	CWL	—	RW	CAS write latency setting. The default value for these bits is set by the MegaWizard CAS Write Latency setting for your controller instance. You must set this value in the CSR interface register map 0x126 (Table 7-20) as well.
6	ASR	0	RW	Not used by the controller, but you can set and program into the memory device mode register.
7	SRT/ET	0	RW	
8	Reserved	0	—	Reserved for future use.
10:9	RTT_WR	0	RW	Not used by the controller, but you can set and program into the memory device mode register.
15:11	Reserved	0	—	Reserved for future use.
17:16	MPR_RF	0	RW	Not used by the controller, but you can set and program into the memory device mode register.
18	MPR	0	RW	
31:19	Reserved	0	—	Reserved for future use.

Controller Register Map

The controller register map allows you to control the memory controller settings. To access the controller register map, connect the CSR interface signals in Table 7-6 using the Avalon-MM protocol.

Table 7-12. Address 0x100 ALTMEMPHY Status and Control Register


Bit	Name	Default	Access	Description
0	CAL_SUCCESS	—	RO	This bit reports the value of the ALTMEMPHY <code>ctl_cal_success</code> output. Writing to this bit has no effect.
1	CAL_FAIL	—	RO	This bit reports the value of the ALTMEMPHY <code>ctl_cal_fail</code> output. Writing to this bit has no effect.
2	CAL_REQ	0	RW	Writing a 1 to this bit asserts the <code>ctl_cal_req</code> signal to the ALTMEMPHY megafunction. Writing a 0 to this bit deasserts the signal, and the ALTMEMPHY megafunction will then initiate its calibration sequence.  You must not use this register during the ALTMEMPHY megafunction calibration. You must wait until the CAL_SUCCESS or CAL_FAIL register shows a value of 1.
7:3	Reserved	0	—	Reserved for future use.
13:8	CLOCK_OFF	0	RW	Writing a 1 to any of the bits in this register causes the appropriate <code>ctl_mem_clk_disable</code> signal to the ALTMEMPHY megafunction to be asserted, which disables the memory clock outputs. Writing a 0 to this register deasserts the signal and re-enables the memory clocks. The ALTMEMPHY megafunction supports up to 6 individual memory clocks, each bit will represent each individual clock.
30:14	Reserved	0	—	Reserved for future use.

Table 7-13. Address 0x110 Controller Status and Configuration Register (Part 1 of 2)

Bit	Name	Default	Access	Description
15:0	AUTO_PD_CYCLES	0x0	RW	The number of idle clock cycles after which the controller should place the memory into power-down mode. The controller is considered to be idle if there are no commands in the command queue. Setting this register to 0 disables the auto power-down mode. The default value of this register depends on the values set during the generation of the design.
16	AUTO_PD_ACK	1	RO	This bit indicates that the memory is in power-down state.

Table 7-13. Address 0x110 Controller Status and Configuration Register (Part 2 of 2)

Bit	Name	Default	Access	Description
17	SELF_RFSH	0	RW	Setting this bit, or asserting the <code>local_self_rfsh</code> signal, causes the memory to go into self-refresh state.
18	SELF_RFSH-ACK	0	RO	This bit indicates that the memory is in self-refresh state.
19	Reserved	0	—	Reserved for future use.
21:20	ADDR_ORDER	00	RW	00 - Chip, row, bank, column. 01 - Chip, bank, row, column. 10 - Reserved for future use. 11 - Reserved for future use.
22	REGDIMM	0	RW	Setting this bit to 1 enables REGDIMM support in controller.
24:23	CTRL_DRATE	00	RO	These bits represent controller data rate: 00 - Full rate. 01 - Half rate. 10 - Reserved for future use. 11 - Reserved for future use.
30:24	Reserved	0	—	Reserved for future use.

Table 7-14. Address 0x120 Memory Address Size Register 0

Bit	Name	Default	Access	Description
7:0	Column address width	—	RW	The number of column address bits for the memory devices in your memory interface. The range of legal values is 7-12.
15:8	Row address width	—	RW	The number of row address bits for the memory devices in your memory interface. The range of legal values is 12-16.
19:16	Bank address width	—	RW	The number of bank address bits for the memory devices in your memory interface. The range of legal values is 2-3.
23:20	Chip select address width	—	RW	The number of chip select address bits for the memory devices in your memory interface. The range of legal values is 0-2. If there is only one single chip select in the memory interface, set this bit to 0.
31:24	Reserved	0	—	Reserved for future use.

Table 7-15. Address 0x121 Memory Address Size Register 1

Bit	Name	Default	Access	Description
31:0	Data width representation (word)	—	RW	The number of DQS bits in the memory interface. This bit can be used to derive the width of the memory interface by multiplying this value by the number of DQ pins per DQS pin (typically 8).

Table 7-16. Address 0x122 Memory Address Size Register 2

Bit	Name	Default	Access	Description
7:0	Chip select representation	—	RW	The number of chip select in binary representation. For example, a design with 2 chip selects has the value of 00000011.
31:8	Reserved	0	—	Reserved for future use.

Table 7–17. Address 0x123 Memory Timing Parameters Register 0

Bit	Name	Default	Access	Description
3:0	t_{RCD}	—	RW	The activate to read or write a timing parameter. The range of legal values is 2-11 cycles.
7:4	t_{RRD}	—	RW	The activate to activate a timing parameter. The range of legal values is 2-8 cycles.
11:8	t_{RP}	—	RW	The precharge to activate a timing parameter. The range of legal values is 2-11 cycles.
15:12	t_{MRD}	—	RW	The mode register load time parameter. This value is not used by the controller, as the controller derives the correct value from the memory type setting.
23:16	t_{RAS}	—	RW	The activate to precharge a timing parameter. The range of legal values is 4-29 cycles.
31:24	t_{RC}	—	RW	The activate to activate a timing parameter. The range of legal values is 8-40 cycles.

Table 7–18. Address 0x124 Memory Timing Parameters Register 1

Bit	Name	Default	Access	Description
3:0	t_{WTR}	—	RW	The write to read a timing parameter. The range of legal values is 1-10 cycles.
7:4	t_{RTP}	—	RW	The read to precharge a timing parameter. The range of legal values is 2-8 cycles.
15:8	t_{FAW}	—	RW	The four-activate window timing parameter. The range of legal values is 6-32 cycles.
31:16	Reserved	0	—	Reserved for future use.

Table 7–19. Address 0x125 Memory Timing Parameters Register 2

Bit	Name	Default	Access	Description
15:0	t_{REFI}	—	RW	The refresh interval timing parameter. The range of legal values is 780-6240 cycles.
23:16	t_{RFC}	—	RW	The refresh cycle timing parameter. The range of legal values is 12-88 cycles.
31:24	Reserved	0	—	Reserved for future use.

Table 7-20. Address 0x126 Memory Timing Parameters Register 3

Bit	Name	Default	Access	Description
3:0	CAS latency, t_{CL}	—	RW	This value must be set to match the memory CAS latency. You must set this value in the 0x04 register map as well.
7:4	Additive latency, AL	—	RW	Additive latency setting. The default value for these bits is set in the Memory additive CAS latency setting in the Preset Editor dialog box. You must set this value in the 0x05 register map as well.
11:8	CAS write latency, CWL	—	RW	CAS write latency setting. You must set this value in the 0x06 register map as well.
15:12	Write recovery, t_{WR}	—	RW	This value must be set to match the memory write recovery time (t_{WR}). You must set this value in the 0x04 register map as well.
31:16	Reserved	0	—	Reserved for future use.

Table 7-21. Address 0x130 ECC Control Register

Bit	Name	Default	Access	Description
0	ENABLE_ECC	1	RW	When 1, enables the generation and checking of ECC.
1	ENABLE_AUTO_CORR	—	RW	When 1, enables auto-correction when a single-bit error is detected.
2	GEN_SBE	0	RW	When 1, enables the deliberate insertion of single-bit errors, bit 0, in the data written to memory. This bit is only used for testing purposes.
3	GEN_DBE	0	RW	When 1, enables the deliberate insertion of double-bit errors, bits 0 and 1, in the data written to memory. This bit is only used for testing purposes.
4	ENABLE_INTR	1	RW	When 1, enables the interrupt output.
5	MASK_SBE_INTR	0	RW	When 1, masks the single-bit error interrupt.
6	MASK_DBE_INTR	0	RW	When 1, masks the double-bit error interrupt.
7	CLEAR	0	RW	When 1, writing to this self-clearing bit clears the interrupt signal, and the error status and error address registers.
9	Reserved	0	—	Reserved for future use.

Table 7-22. Address 0x131 ECC Status Register (Part 1 of 2)

Bit	Name	Default	Access	Description
0	SBE_ERROR	0	RO	Set to 1 when any single-bit errors occur.
1	DBE_ERROR	0	RO	Set to 1 when any double-bit errors occur.
7:2	Reserved	0	—	Reserved for future use.

Table 7–22. Address 0x131 ECC Status Register (Part 2 of 2)

Bit	Name	Default	Access	Description
15:8	SBE_COUNT	0	RO	Reports the number of single-bit errors that have occurred since the status register counters were last cleared.
23:16	DBE_COUNT	0	RO	Reports the number of double-bit errors that have occurred since the status register counters were last cleared.
31:24	Reserved	0	—	Reserved for future use.

Table 7–23. Address 0x132 ECC Error Address Register

Bit	Name	Default	Access	Description
31:0	ERR_ADDR	0	RO	The address of the most recent ECC error. This address contains concatenation of chip, bank, row, and column addresses.

Latency is defined using the local (user) side frequency and absolute time (ns). There are two types of latencies that exist while designing with memory controllers—read and write latencies, which have the following definitions:

- Read latency—the amount of time it takes for the read data to appear at the local interface after initiating the read request.
- Write latency—the amount of time it takes for the write data to appear at the memory interface after initiating the write request.



For a half-rate controller, the local side frequency is half of the memory interface frequency.

Altera defines read and write latencies in terms of the local interface clock frequency and by the absolute time for the memory controllers. These latencies apply to supported device families with the half-rate DDR3 high-performance controllers (HPC and HPC II).

The latency defined in this section uses the following assumptions:

- The row is already open, there is no extra bank management needed.
- The controller is idle, there is no queued transaction pending, indicated by the `local_ready` signal asserted high.
- No refresh cycles occur before the transaction.

The latency for the high-performance controller comprises many different stages of the memory interface.

Figure 8-1 shows a typical memory interface read latency path showing read latency from the time a `local_read_req` assertion is detected by the controller up to data available to be read from the dual-port RAM (DPRAM) module.

Figure 8-1. Typical Latency Path

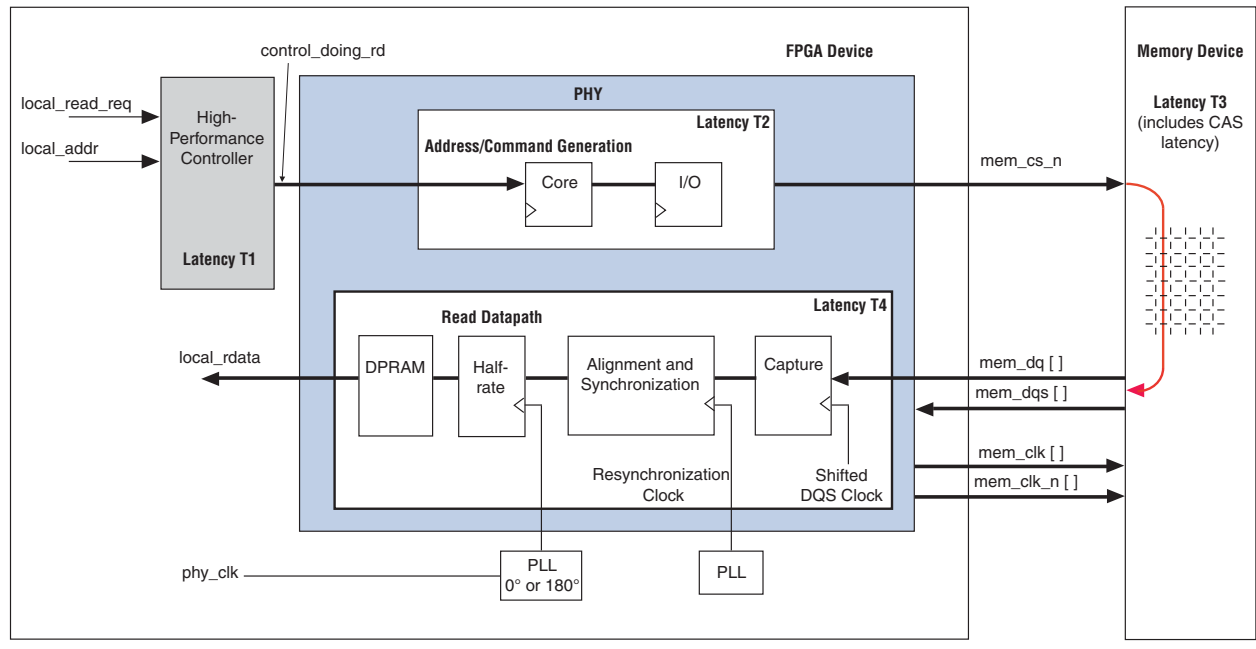


Table 8-1 shows the different stages that make up the whole read and write latency that Figure 8-1 shows.

Table 8-1. High-Performance Controller Latency Stages and Descriptions

Latency Number	Latency Stage	Description
T1	Controller	<code>local_read_req</code> or <code>local_write_req</code> signal assertion to <code>ddr_cs_n</code> signal assertion.
T2	Command Output	<code>ddr_cs_n</code> signal assertion to <code>mem_cs_n</code> signal assertion.
T3	CAS or WL	Read command to DQ data from the memory or write command to DQ data to the memory.
T4	ALTMEMPHY read data input	Read data appearing on the local interface.
T2 + T3	Write data latency	Write data appearing on the memory interface.

From Figure 8-1, the read latency in the high-performance controllers is made up of four components:

$$\text{read latency} = \text{controller latency (T1)} + \text{command output latency (T2)} + \text{CAS latency (T3)} + \text{PHY read data input latency (T4)}$$

Similarly, the write latency in the high-performance controllers is made up of three components:

$$\text{write latency} = \text{controller latency (T1)} + \text{write data latency (T2+T3)}$$

You can separate the controller and ALTMEMPHY read data input latency into latency that occurred in the I/O element (IOE) and latency that occurred in the FPGA fabric.

Table 8-2 shows the read and write latency derived from the write and read latency definitions for half rate controller for Stratix III and Stratix IV devices.



The exact latency depends on your precise configuration. You should obtain precise latency from simulation, but this figure may vary in hardware because of the automatic calibration process.

Table 8-2. Typical Latency

Device	Controller Rate	Frequency (MHz)	Latency Type	Total Latency	
				Local Clock Cycles	Time (ns)
Stratix III	Half	400	Read	23	115
			Write	14	68
Stratix IV	Half	400	Read	23	115
			Write	14	68



To see the latency incurred in the IOE for both read and write paths for ALTMEMPHY variations in Stratix IV and Stratix III devices refer to the IOE figures in the *External Memory Interfaces in Stratix III Devices* chapter of the *Stratix III Device Handbook* and the *External Memory Interfaces in Stratix IV Devices* chapter of the *Stratix IV Device Handbook*.

This chapter details the timing diagrams for the DDR3 SDRAM high-performance controllers (HPC) and high-performance controllers II (HPC II).

DDR3 High-Performance Controllers

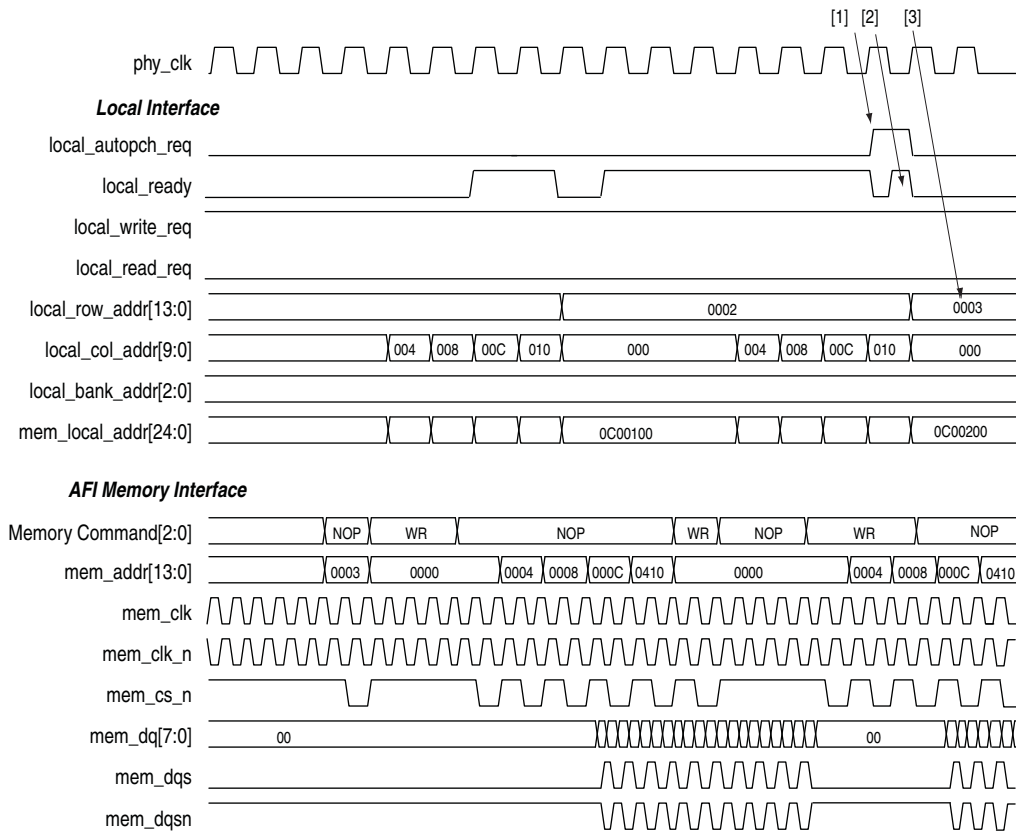
This section discusses the following timing diagrams for HPC in AFI mode:

- “Auto-Precharge”
- “User Refresh”
- “Half-Rate Read for Avalon Interface”
- “Half-Rate Write for Avalon Interface”
- “Half Rate Write for Native Interface”
- “Initialization Timing for HPC”
- “Calibration Timing for HPC”

Auto-Precharge

The auto-precharge read and auto-precharge write commands allow you to indicate to the memory device that this read or write command is the last access to the currently open row. The memory device automatically closes (auto-precharges) the page it is currently accessing so that the next access to the same bank is quicker. This command is particularly useful for applications that require fast random accesses.

Figure 9-1. Auto-Precharge Operation for HPC



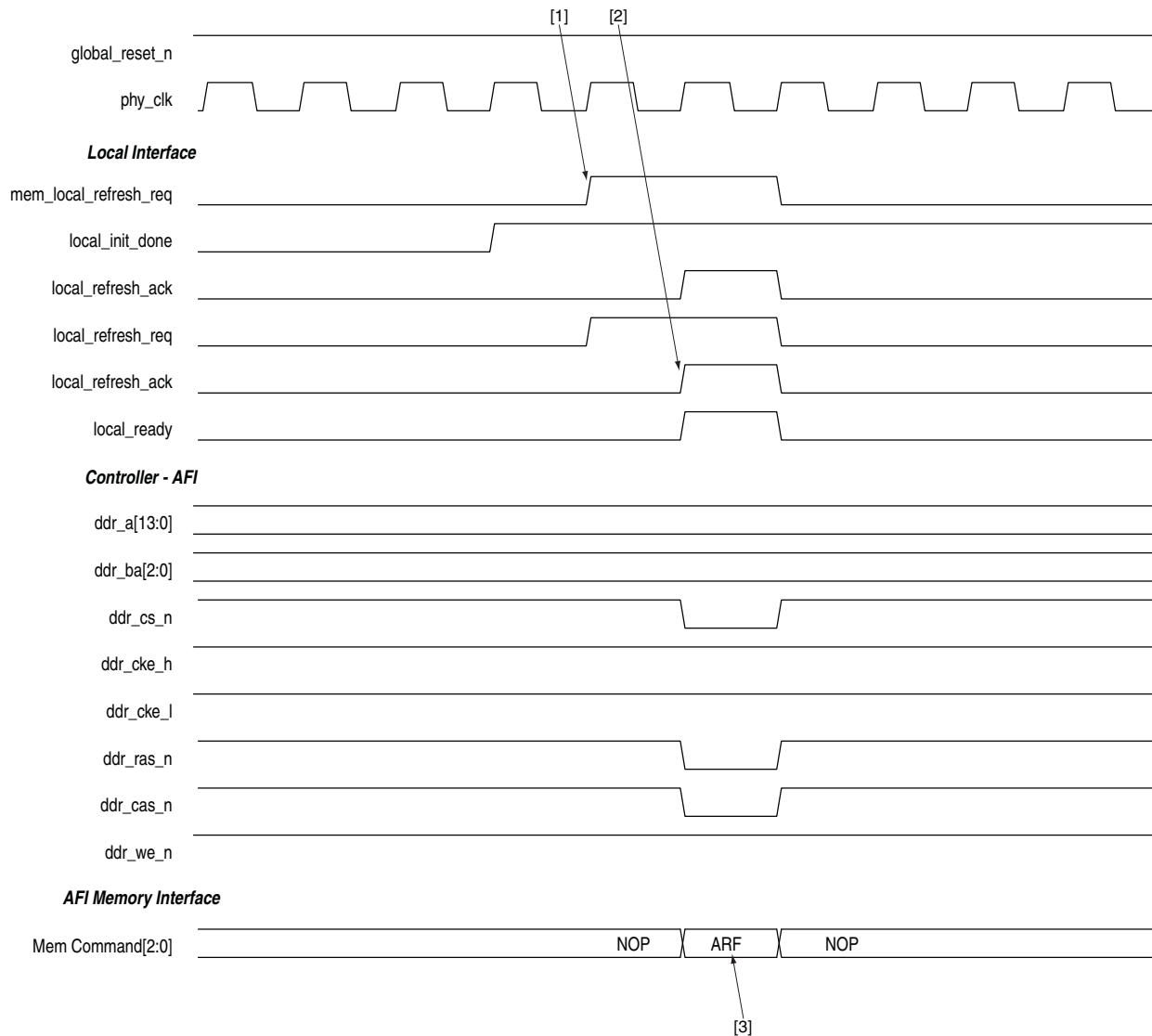
Notes to Figure 9-1:

- (1) The auto-precharge request goes high.
- (2) The local_ready signal is asserted and remains high until the auto-precharge request goes low.
- (3) A new row address begins.

User Refresh

Figure 9-2 shows the user refresh control interface. This feature allows you to control when the controller issues refreshes to the memory. This feature allows better control of worst case latency and allows refreshes to be issued in bursts to take advantage of idle periods.

Figure 9-2. User-Refresh Operation for HPC

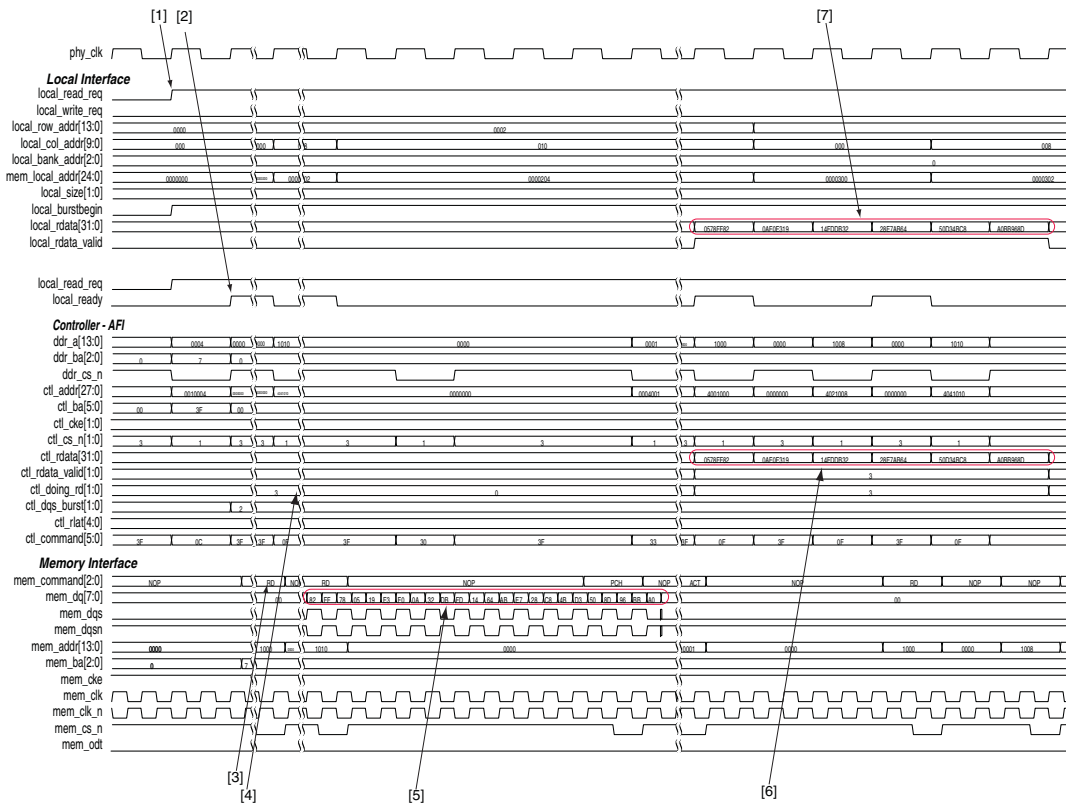


Notes to Figure 9-2:

- (1) The local refresh request signal is asserted.
- (2) The controller asserts the `local_refresh_ack` signal.
- (3) The auto-refresh (ARF) command on the command bus.

Half-Rate Read for Avalon Interface

Figure 9-3. Half-Rate Read Operation for HPC Using Avalon-MM Interface

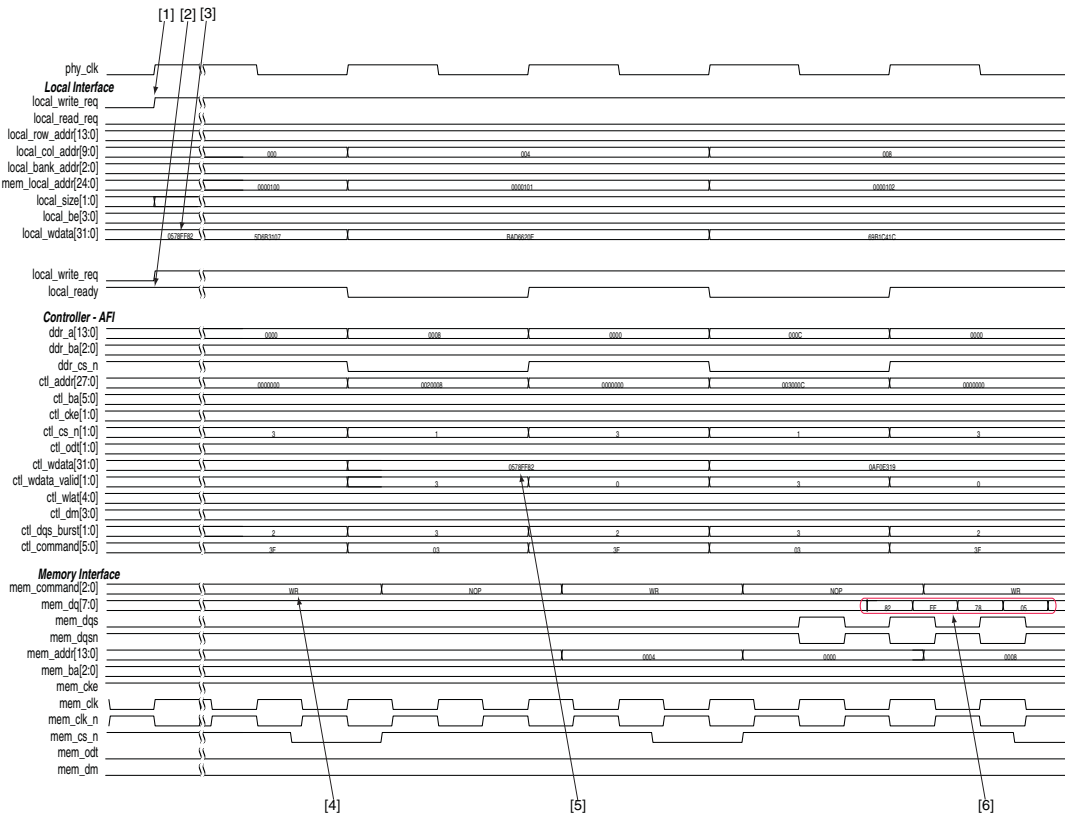


The following sequence corresponds with the numbered items in [Figure 9-3](#):

1. The local read request signal is asserted.
2. The controller accepts the request, the `local_ready` signal is asserted.
3. The controller asserts the `ctl_doing_rd` to tell the PHY how many clock cycles of read data to expect.
4. The read command (RD) on the command bus.
5. The `mem_dqs` signal has the read data from the controller.
6. These are the data to the controller with the valid signal.
7. The controller returns the valid read data to the user logic by asserting the `local_rdata_valid` signal when there is valid local read data.

Half-Rate Write for Avalon Interface

Figure 9-4. Half-Rate Write Operation for HPC Using Avalon Interface

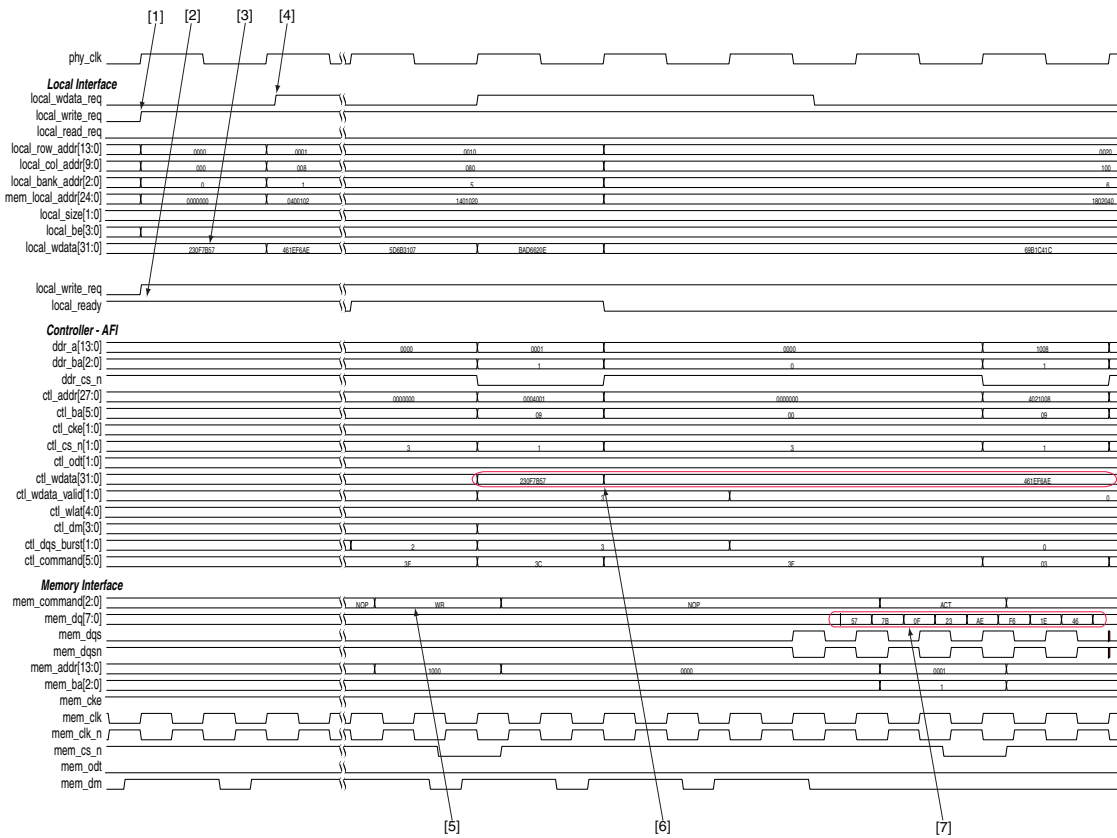


The following sequence corresponds with the numbered items in [Figure 9-4](#):

1. The user logic requests write by asserting the `local_write_req` signal.
2. The `local_ready` signal is asserted, indicating that the controller has accepted the request.
3. The data written to the memory for the write command.
4. The write (WR) command on the command bus.
5. The valid write data on the `ctl_wdata` signal.
6. The valid data on the `mem_dq` signal goes to the controller.

Half Rate Write for Native Interface

Figure 9-5. Half-Rate Write Operation for HPC Using Native Interface

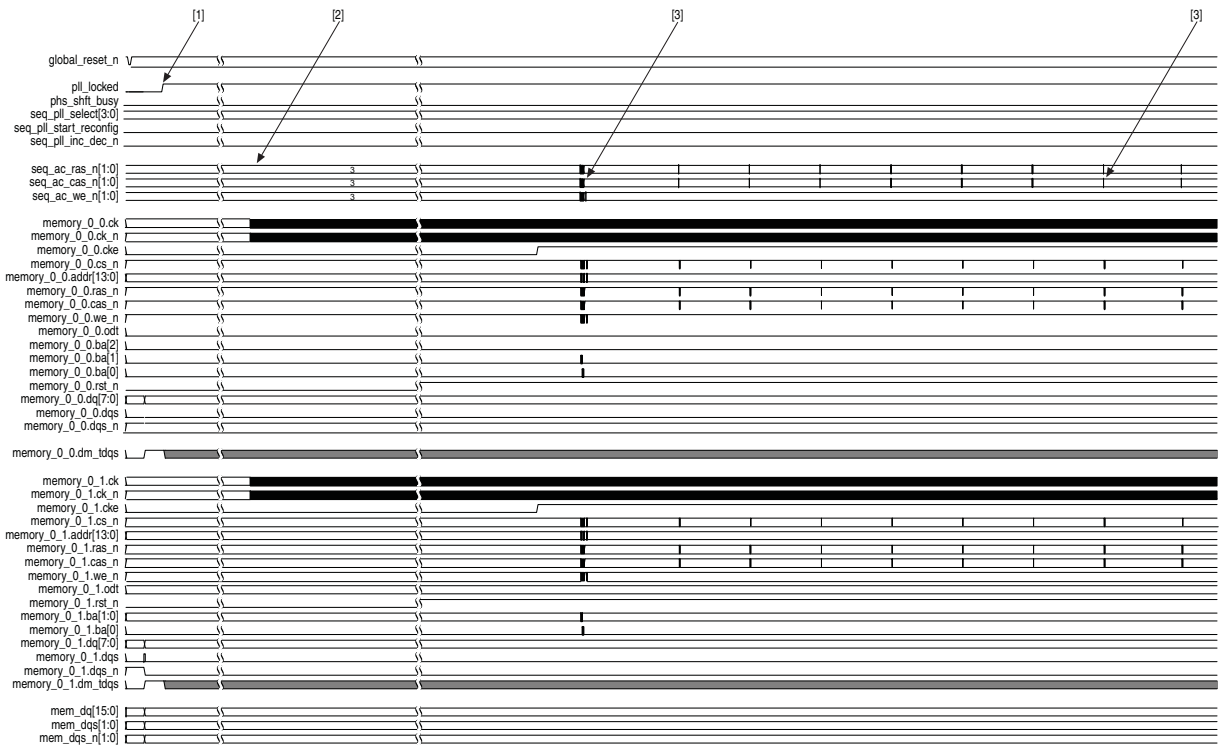


The following sequence corresponds with the numbered items in [Figure 9-5](#):

1. The user logic requests write by asserting the `local_write_req` signal.
2. The `local_ready` signal is asserted, indicating that the controller has accepted the request.
3. The data written to the memory for the write command.
4. The controller requests the user logic for the write data and byte-enables for the write by asserting the `local_wdata_req` signal.
5. The write (WR) command on the command bus.
6. The valid write data on the `ctl_wdata` signal.
7. The valid data on the `mem_dq` signal goes to the controller.

Initialization Timing

Figure 9-6. Initialization Timing for HPC

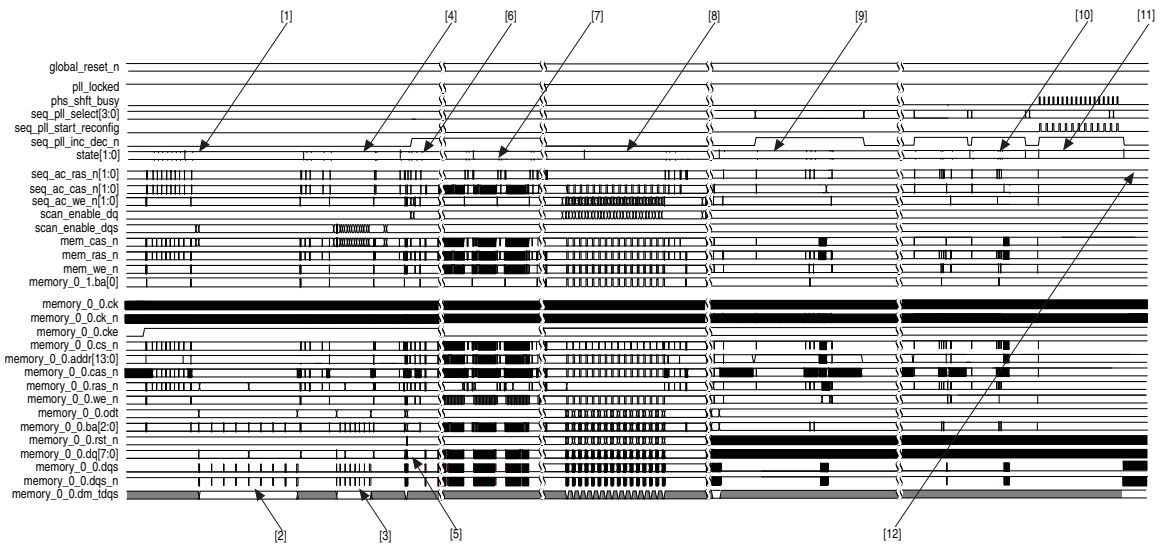


The following sequence corresponds with the numbered items in [Figure 9-6](#):

1. The PHY initialization stage; wait for PLL to unlock.
2. The DRAM initialization stage; reset sequence.
3. Various SDRAM bus commands during the initialization sequence.

Calibration Timing

Figure 9-7. Calibration Timing for HPC



The following sequence corresponds with the numbered items in [Figure 9-7](#):

1. The write leveling stage.
2. The write leveling coarse phase sweep.
3. Fine T9/T10 delay chain sweep.
4. The write burst training pattern.
5. Three training patterns available at different addresses—zeroes, ones, and mixed.
6. The read path setup starts with the first operation, read deskew.
7. The read path deskew increases capture margin.
8. The write deskew stage; patterns written to RAM and read back.
9. The write datapath setup; data written to DRAM to determine latency.
10. Advertise read and write latency stage.
11. Tracking setup stage to set up mimic window.
12. Calibration successful on user mode.

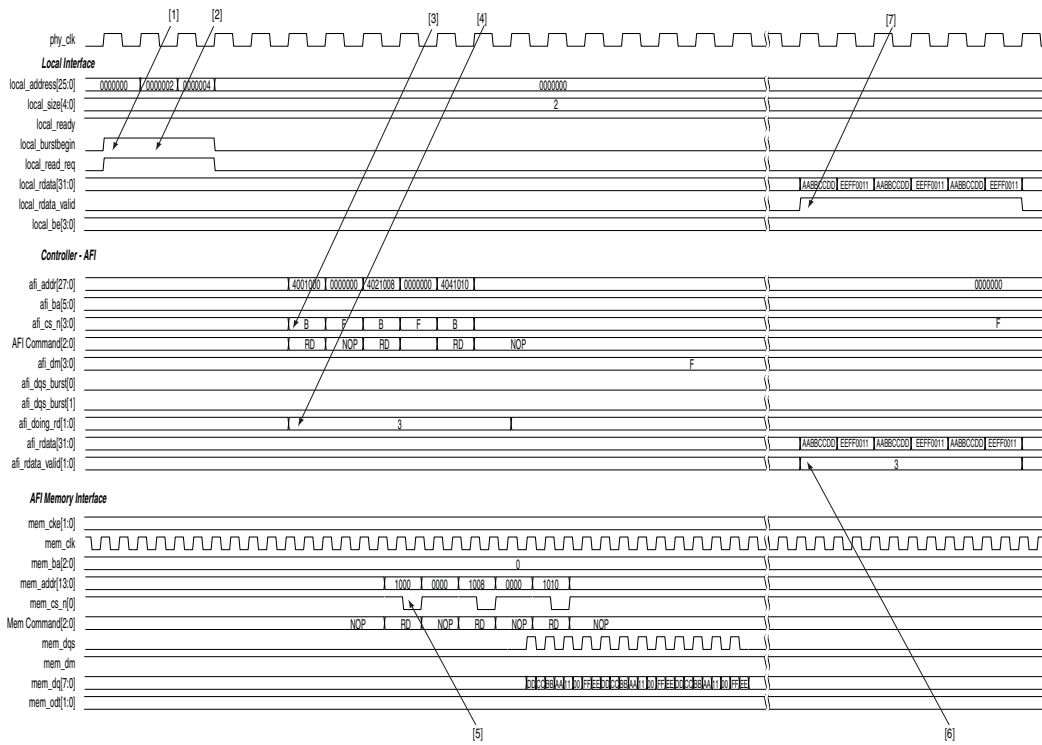
DDR3 High-Performance Controllers II

This section discusses the following timing diagrams for HPC II:

- “Half-Rate Read (Burst-Aligned Address)”
- “Half-Rate Write (Burst-Aligned Address)”
- “Half-Rate Read (Non Burst-Aligned Address)”
- “Half-Rate Write (Non Burst-Aligned Address)”
- “Half-Rate Read With Gaps”
- “Half-Rate Write With Gaps”
- “Half-Rate Write Operation (Merging Writes)”
- “Write-Read-Write-Read Operation”

Half-Rate Read (Burst-Aligned Address)

Figure 9-8. Half-Rate Read Operation for HPC II—Burst-Aligned Address



The following sequence corresponds with the numbered items in [Figure 9-8](#):

1. The user logic requests the first read by asserting the `local_read_req` signal, and the size and address for this read. In this example, the request is a burst of length of 2 to the local address `0x000000`. This local address is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x000000
```

```
mem_col_address = 0x0000
```

```
mem_bank_address = 0x00
```

2. The user logic initiates a second read to a different memory column within the same row. The request for the second write is a burst length of 2. In this example, the user logic continues to accept commands until the command queue is full. When the command queue is full, the controller deasserts the `local_ready` signal. The starting local address `0x000002` is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0000
```

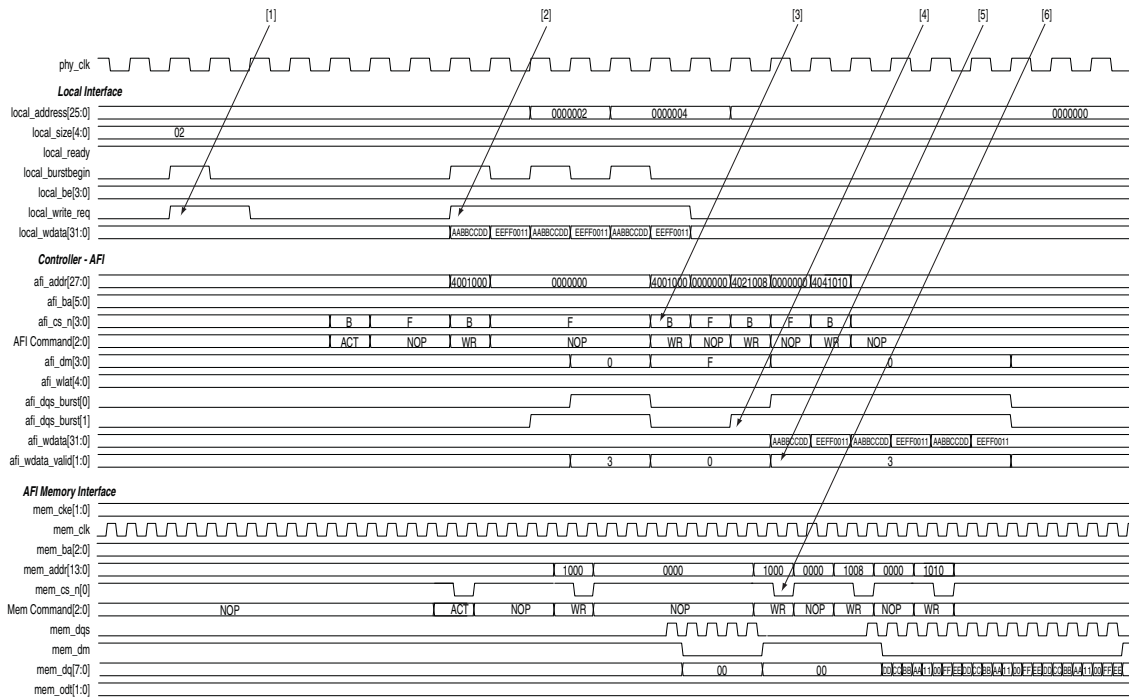
```
mem_col_address = 0x0002<<2 = 0x0008
```

```
mem_bank_address = 0x00
```

3. The controller issues the first read memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
4. The controller asserts the `afi_doing_rd` signal to indicate to the ALTMEMPHY megafunction the number of clock cycles of read data it must expect for the first read. The ALTMEMPHY megafunction uses the `afi_doing_rd` signal to enable its capture registers for the expected duration of memory burst.
5. The ALTMEMPHY megafunction issues the first read command to the memory and captures the read data from the memory.
6. The ALTMEMPHY megafunction returns the first data read to the controller after resynchronizing the data to the `phy_clk` domain, by asserting the `afi_rdata_valid` signal when there is valid read data on the `afi_rdata` bus.
7. The controller returns the first read data to the user by asserting the `local_rdata_valid` signal when there is valid read data on the `local_rdata` bus. If the ECC logic is disabled, there is no delay between the `afi_rdata` and the `local_rdata` buses. If there is ECC logic in the controller, there is one or three clock cycles of delay between the `afi_rdata` and `local_rdata` buses.

Half-Rate Write (Burst-Aligned Address)

Figure 9-9. Half-Rate Write Operation for HPC II—Burst-Aligned Address



The following sequence corresponds with the numbered items in [Figure 9-9](#):

1. The user logic asserts the first write request to row 0 so that row 0 is open before the next transaction.
2. The user logic asserts a second `local_write_req` signal with size of 2 and address of 0 (`col = 0, row = 0, bank = 0, chip = 0`). The `local_ready` signal is asserted along with the `local_write_req` signal, which indicates that the controller has accepted this request, and the user logic can request another read or write in the following clock cycle. If the `local_ready` signal was not asserted, the user logic must keep the write request, size, and address signals asserted until the `local_ready` signal is registered high.
3. The controller issues the necessary memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
4. The controller asserts the `afi_wdata_valid` signal to indicate to the ALTMEMPHY megafunction that valid write data and write data masks are present on the inputs to the ALTMEMPHY megafunction.
5. The controller asserts the `afi_dqs_burst` signals to control the timing of the DQS signal that the ALTMEMPHY megafunction issues to the memory.
6. The ALTMEMPHY megafunction issues the write command, and sends the write data and write DQS to the memory.

The following sequence corresponds with the numbered items in Figure 9-10:

1. The user logic requests the first read by asserting the `local_read_req` signal, and the size and address for this read. In this example, the request is a burst of length of 2 to the local address `0x000001`. This local address is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0000
```

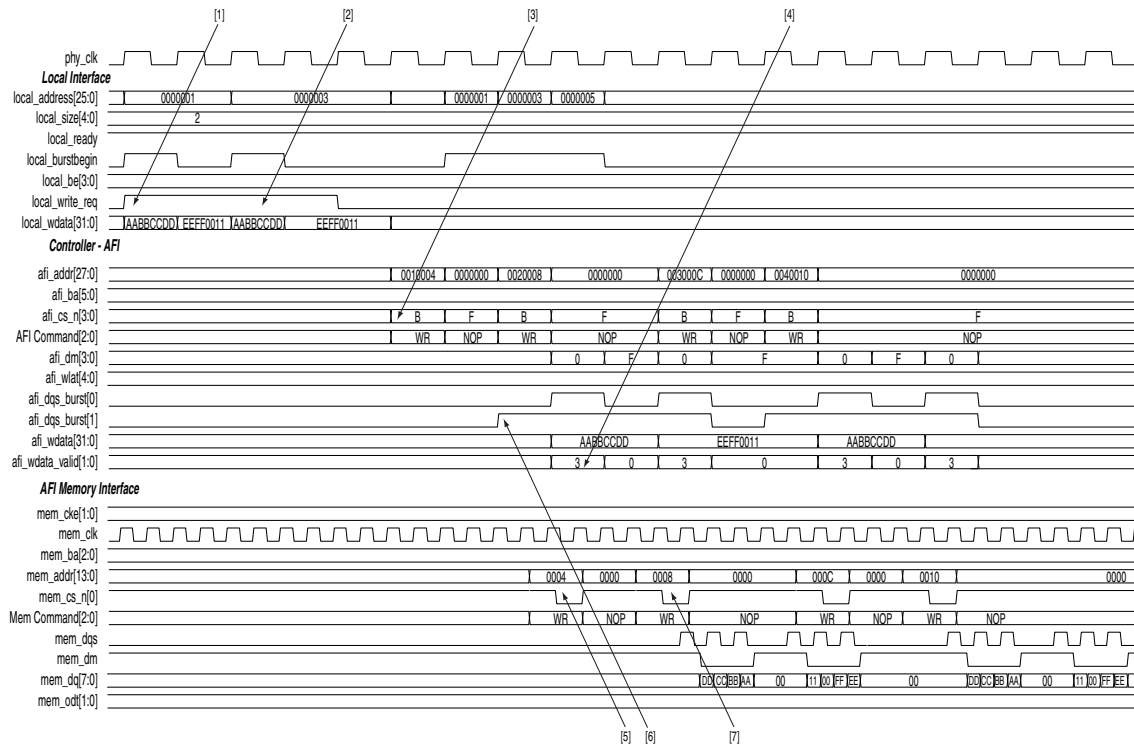
```
mem_col_address = 0x0001<<2 = 0x0004
```

```
mem_bank_address = 0x00
```

2. The controller issues the first read memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
3. The controller asserts the `afi_doing_rd` signal to indicate to the ALTMEMPHY megafunction the number of clock cycles of read data it must expect for the first read. The ALTMEMPHY megafunction uses the `afi_doing_rd` signal to enable its capture registers for the expected duration of memory burst.
4. The ALTMEMPHY megafunction issues the first read command to the memory and captures the read data from the memory.
5. The ALTMEMPHY megafunction returns the first data read to the controller after resynchronizing the data to the `phy_clk` domain, by asserting the `afi_rdata_valid` signal when there is valid read data on the `afi_rdata` bus.
6. The controller returns the first read data to the user by asserting the `local_rdata_valid` signal when there is valid read data on the `local_rdata` bus. If the ECC logic is disabled, there is no delay between the `afi_rdata` and the `local_rdata` buses. If there is ECC logic in the controller, there is one or three clock cycles of delay between the `afi_rdata` and `local_rdata` buses.

Half-Rate Write (Non Burst-Aligned Address)

Figure 9-11. Half-Rate Write Operation for HPC II—Non Burst-Aligned Address



The following sequence corresponds with the numbered items in [Figure 9-11](#):

1. The user logic asserts the first `local_write_req` signal with a size of 2 and an address of `0x000001`. The `local_ready` signal is asserted along with the `local_write_req` signal, which indicates that the controller has accepted this request, and the user logic can request another read or write in the following clock cycle. If the `local_ready` signal was not asserted, the user logic must keep the write request, size, and address signals asserted until the `local_ready` signal is registered high. The local address `0x000001` is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0000  
mem_col_address = 0x000001<<2 = 0x000004  
mem_bank_address = 0x00
```

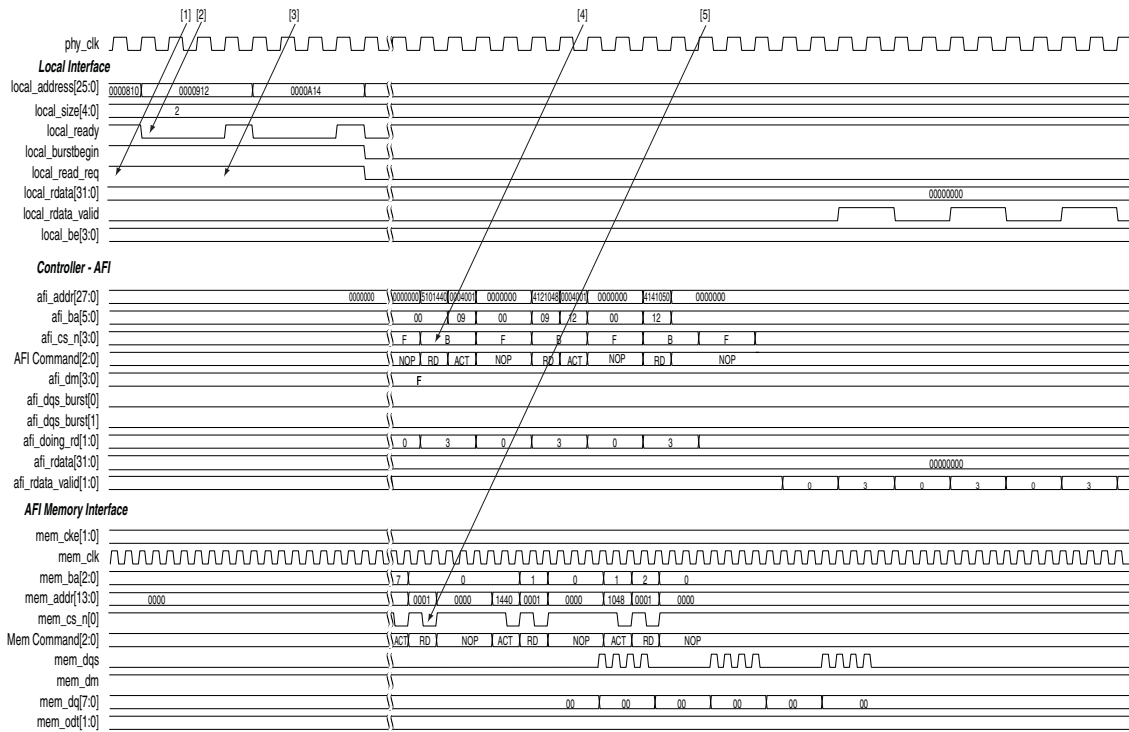
2. The user logic asserts the second `local_write_req` signal with a size of 2 and an address of `0x000003`. The local address `0x000003` is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0000  
mem_col_address = 0x000003<<2 = 0x00000C  
mem_bank_address = 0x00
```

3. The controller issues the necessary memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
4. The controller asserts the `afi_wdata_valid` signal to indicate to the ALTMEMPHY megafunction that valid write data and write data masks are present on the inputs to the ALTMEMPHY megafunction.
5. The controller asserts the `afi_dqs_burst` signals to control the timing of the DQS signal that the ALTMEMPHY megafunction issues to the memory.
6. The ALTMEMPHY megafunction issues the write command, and sends the write data and write DQS to the memory.
7. The controller generates another write because the first write is to a non-aligned memory address, `0x0004`. The controller performs the second write burst at the memory address of `0x0008`.

Half-Rate Read With Gaps

Figure 9-12. Half-Rate Read Operation for HPC II—With Gaps



The following sequence corresponds with the numbered items in Figure 9-12:

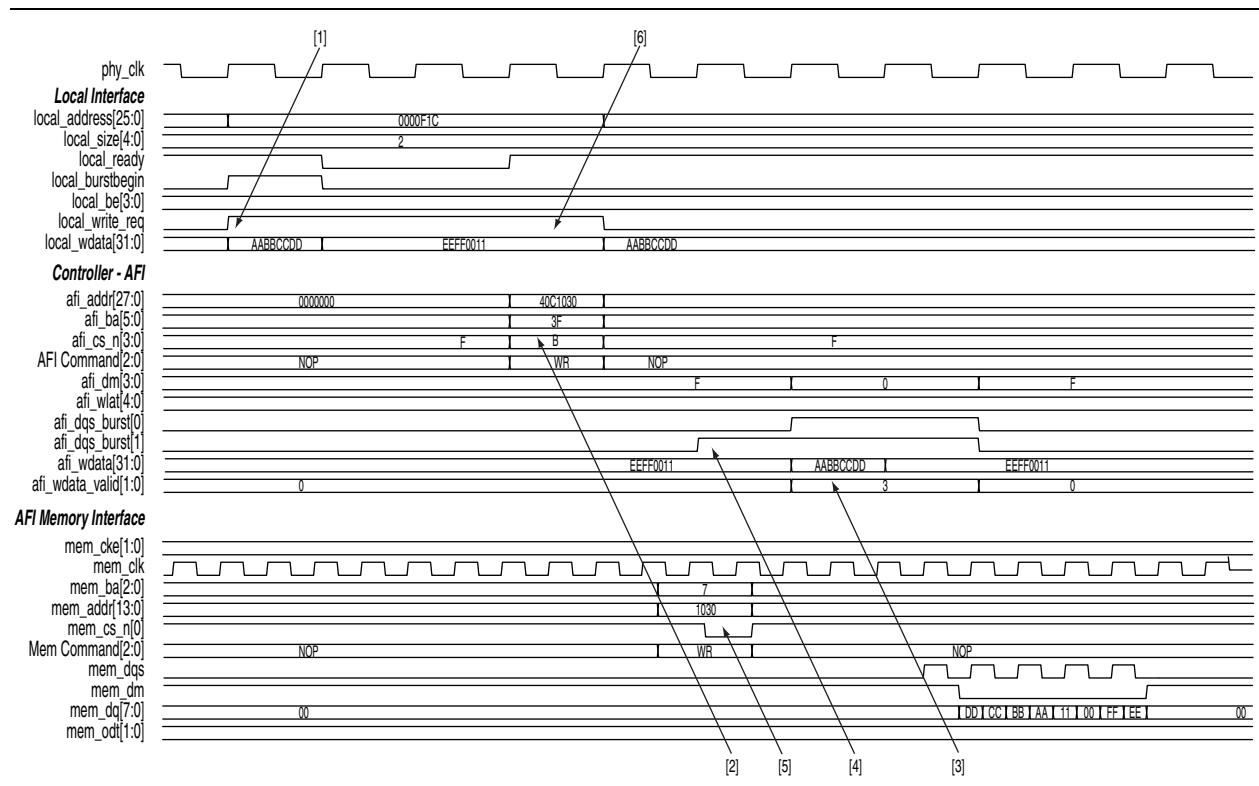
1. The user logic requests the first read by asserting the `local_read_req` signal, and the size and address for this read. In this example, the request is a burst of length of 2 to the local address `0x0000810`. This local address is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0001
mem_col_address = 0x0010<<2 = 0x0040
mem_bank_address = 0x00
```

2. When the command queue is full, the controller deasserts the `local_ready` signal to indicate that the controller has not accepted the command. The user logic must keep the read request, size, and address signal until the `local_ready` signal is asserted again.
3. The user logic asserts a second `local_read_req` signal with a size of 2 and address of `0x0000912`.
4. The controller issues the first read memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
5. The ALTMEMPHY megafunction issues the read command to the memory and captures the read data from the memory.

Half-Rate Write With Gaps

Figure 9-13. Half-Rate Write Operation for HPC II—With Gaps

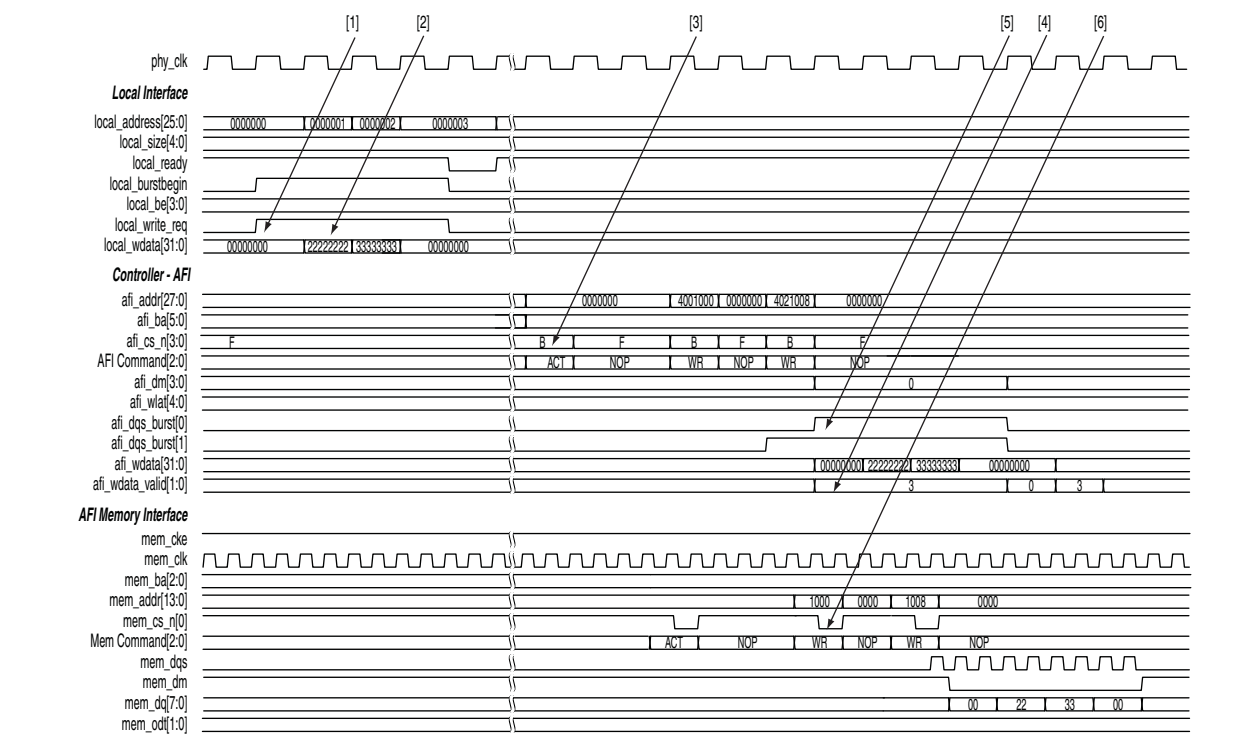


The following sequence corresponds with the numbered items in Figure 9-13:

1. The user logic asserts a local_write_req signal with a size of 2 and an address of 0x0000F1C.
2. The controller issues the necessary memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
3. The controller asserts the afi_wdata_valid signal to indicate to the ALTMEMPHY megafunction that valid write data and write data masks are present on the inputs to the ALTMEMPHY megafunction.
4. The controller asserts the afi_dqs_burst signals to control the timing of the DQS signal that the ALTMEMPHY megafunction issues to the memory.
5. The ALTMEMPHY megafunction issues the write command, and sends the write data and write DQS to the memory.
6. For transactions with a local size of two, the local_write_req and local_ready signals must be high for two clock cycles so that all the write data can be transferred to the controller.

Half-Rate Write Operation (Merging Writes)

Figure 9-14. Write Operation for HPC II—Merging Writes



The following sequence corresponds with the numbered items in [Figure 9-14](#):

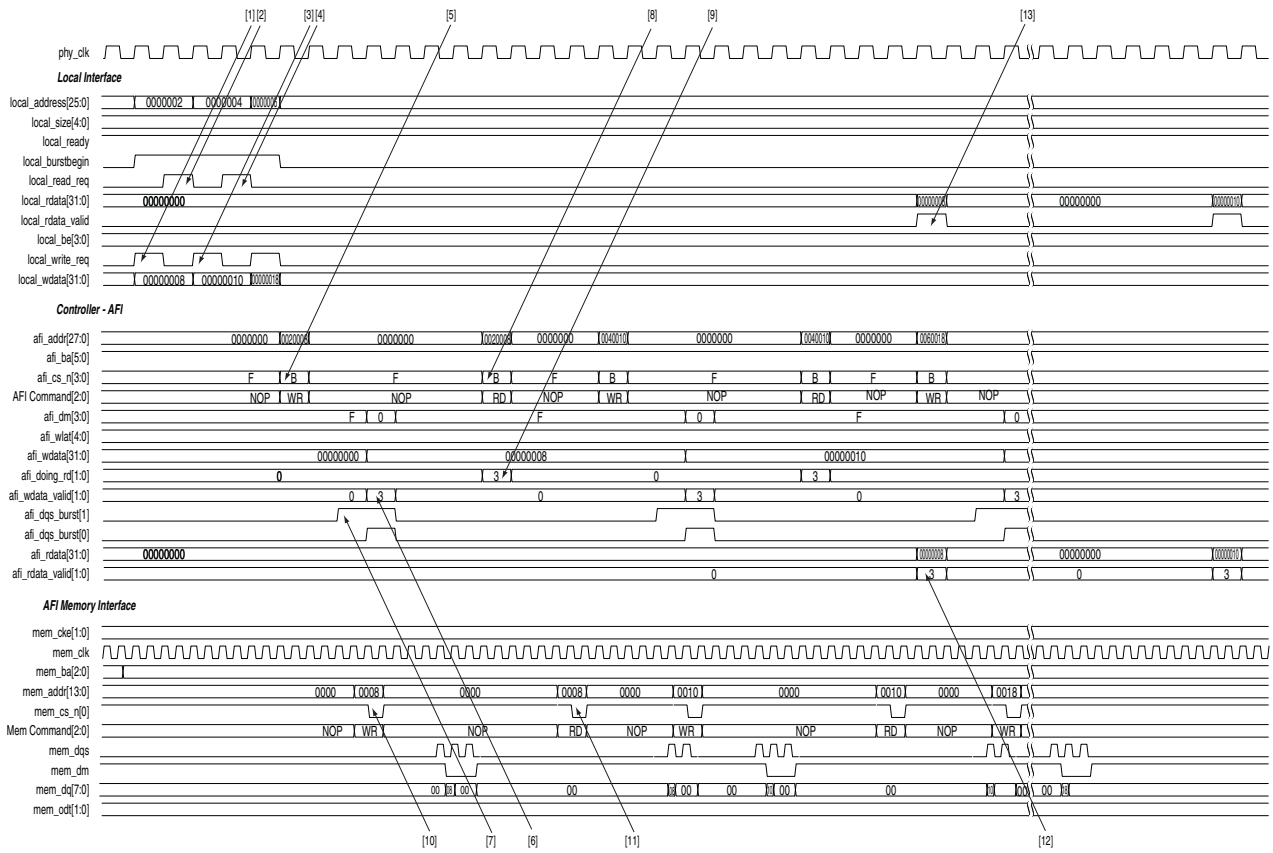
1. The user logic asserts the first `local_write_req` signal with a size of 1 and an address of `0x000000`. The `local_ready` signal is asserted along with the `local_write_req` signal, which indicates that the controller has accepted this request, and the user logic can request another read or write in the following clock cycle. If the `local_ready` signal was not asserted, the user logic must keep the write request, size, and address signals asserted until the `local_ready` signal is registered high. The local address `0x000000` is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0000  
mem_col_address = 0x0000<<2 = 0x0000  
mem_bank_address = 0x00
```

2. The user logic asserts a second `local_write_req` signal with a size of 1 and address of 1. The `local_ready` signal is asserted along with the `local_write_req` signal, which indicates that the controller has accepted this request. Since the second write request is to a sequential address (same row, same bank, and column increment by 1), this write and the first write can be merged at the memory transaction.
3. The controller issues the necessary memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
4. The controller asserts the `afi_wdata_valid` signal to indicate to the ALTMEMPHY megafunction that valid write data and write data masks are present on the inputs to the ALTMEMPHY megafunction.
5. The controller asserts the `afi_dqs_burst` signals to control the timing of the DQS signal that the ALTMEMPHY megafunction issues to the memory.
6. The ALTMEMPHY megafunction issues the write command, and sends the write data and write DQS to the memory.

Write-Read-Write-Read Operation

Figure 9-15. Write-Read Sequential Operation for HPC II



The following sequence corresponds with the numbered items in [Figure 9-15](#):

1. The user logic requests the first write by asserting the `local_write_req` signal, and the size and address for this write. In this example, the request is a burst length of 1 to a local address `0x000002`. This local address is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0000  
mem_col_address = 0x0002<<2 = 0x0008  
mem_bank_address = 0x00
```

2. The user logic initiates the first read to the same address as the first write. The request for the read is a burst length of 1. The controller continues to accept commands until the command queue is full. When the command queue is full, the controller deasserts the `local_ready` signal. The starting local address `0x000002` is mapped to the following memory address in half-rate mode:

```
mem_row_address = 0x0000  
mem_col_address = 0x0002<<2 = 0x0008  
mem_bank_address = 0x00
```

3. The user logic asserts a second `local_write_req` signal with a size of 1 and address of `0x000004`.
4. The user logic asserts a second `local_read_req` signal with a size of 1 and address of `0x000004`.
5. The controller issues the necessary memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
6. The controller asserts the `afi_wdata_valid` signal to indicate to the ALTMEMPHY megafunction that valid write data and write data masks are present on the inputs to the ALTMEMPHY megafunction.
7. The controller asserts the `afi_dqs_burst` signals to control the timing of the DQS signals that the ALTMEMPHY megafunction issues to the memory.
8. The controller issues the first read memory command and address signals to the ALTMEMPHY megafunction for it to send to the memory device.
9. The controller asserts the `afi_doing_rd` signal to indicate to the ALTMEMPHY megafunction the number of clock cycles of read data it must expect for the first read. The ALTMEMPHY megafunction uses the `afi_doing_rd` signal to enable its capture registers for the expected duration of memory burst.
10. The ALTMEMPHY megafunction issues the write command, and sends the write data and write DQS to the memory.
11. The ALTMEMPHY megafunction issues the first read command to the memory and captures the read data from the memory.
12. The ALTMEMPHY megafunction returns the first data read to the controller after resynchronizing the data to the `phy_clk` domain, by asserting the `afi_rdata_valid` signal when there is valid read data on the `afi_rdata` bus.

13. The controller returns the first read data to the user by asserting the `local_rdata_valid` signal when there is valid read data on the `local_rdata` bus. If the ECC logic is disabled, there is no delay between the `afi_rdata` and the `local_rdata` buses. If there is ECC logic in the controller, there is one or three clock cycles of delay between the `afi_rdata` and `local_rdata` buses.

This chapter provides additional information about the document and Altera.

Document Revision History

The following table shows the revision history for this document.

Date	Version	Changes
December 2010	2.1	Updated for 10.1.
July 2010	2.0	<ul style="list-style-type: none"> ■ Added information for new GUI parameters: Controller latency, Enable reduced bank tracking for area optimization, and Number of banks to track. ■ Removed information about IP Advisor. This feature is removed from the DDR3 SDRAM IP support for version 10.0.
February 2010	1.3	Corrected typos.
February 2010	1.2	<ul style="list-style-type: none"> ■ Full support for Stratix IV devices. ■ Added information for Register Control Word parameters. ■ Added descriptions for <code>mem_ac_parity</code>, <code>mem_err_out_n</code>, and <code>parity_error_n</code> signals. ■ Added timing diagrams for initialization and calibration stages for HPC.
November 2009	1.1	Minor corrections.
November 2009	1.0	First published.

How to Contact Altera

To locate the most up-to-date information about Altera products, refer to the following table.







Contact (1)	Contact Method	Address
Technical support	Website	www.altera.com/support
Technical training	Website	www.altera.com/training
	Email	custrain@altera.com
Product literature	Website	www.altera.com/literature
Non-technical support (General) (Software Licensing)	Email	nacomp@altera.com
	Email	authorization@altera.com

Note to Table:

(1) You can also contact your local Altera sales office or sales representative.

Typographic Conventions

The following table shows the typographic conventions this document uses.

Visual Cue	Meaning
Bold Type with Initial Capital Letters	Indicate command names, dialog box titles, dialog box options, and other GUI labels. For example, Save As dialog box. For GUI elements, capitalization matches the GUI.
bold type	Indicates directory names, project names, disk drive names, file names, file name extensions, software utility names, and GUI labels. For example, \qdesigns directory, D: drive, and chiptrip.gdf file.
<i>Italic Type with Initial Capital Letters</i>	Indicate document titles. For example, <i>Stratix IV Design Guidelines</i> .
<i>italic type</i>	Indicates variables. For example, $n + 1$. Variable names are enclosed in angle brackets (< >). For example, <file name> and <project name>. .pdf file.
Initial Capital Letters	Indicate keyboard keys and menu names. For example, the Delete key and the Options menu.
“Subheading Title”	Quotation marks indicate references to sections within a document and titles of Quartus II Help topics. For example, “Typographic Conventions.”
Courier type	Indicates signal, port, register, bit, block, and primitive names. For example, <code>data1</code> , <code>tdi</code> , and <code>input</code> . The suffix <code>n</code> denotes an active-low signal. For example, <code>resetn</code> . Indicates command line commands and anything that must be typed exactly as it appears. For example, <code>c:\qdesigns\tutorial\chiptrip.gdf</code> . Also indicates sections of an actual file, such as a Report File, references to parts of files (for example, the AHDL keyword <code>SUBDESIGN</code>), and logic function names (for example, <code>TRI</code>).
↵	An angled arrow instructs you to press the Enter key.
1., 2., 3., and a., b., c., and so on	Numbered steps indicate a list of items when the sequence of the items is important, such as the steps listed in a procedure.
■ ■ ■	Bullets indicate a list of items when the sequence of the items is not important.
	The hand points to information that requires special attention.
	A question mark directs you to a software help system with related information.
	The feet direct you to another document or website with related information.
	A caution calls attention to a condition or possible situation that can damage or destroy the product or your work.
	A warning calls attention to a condition or possible situation that can cause you injury.
	The envelope links to the Email Subscription Management Center page of the Altera website, where you can sign up to receive update notifications for Altera documents.